
IGLOO2 FPGA and SmartFusion2 SoC FPGA

DS0128 Datasheet



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List of Changes

Datasheet Categories

Safety Critical, Life Support, and High-Reliability Applications Policy

Microsemi Corporate Headquarters

IGLOO2 and SmartFusion2 SoC FPGA AC/DC Electrical Characteristics

1. Introduction

Microsemi’s mainstream SmartFusion®2 SoC and IGLOO®2 FPGA families integrate an industry standard 4-input lookup table-based (LUT) FPGA fabric with integrated mathblocks, multiple embedded memory blocks, and high-performance SERDES communication interfaces on a single chip. Both families benefit from low power flash technology and are the most secure and reliable FPGAs in the industry. These next generation devices offer up to 150K Logic Elements, up to five MB of embedded RAM, up to 16 SERDES lanes, and up to four PCI Express Gen 2 endpoints, as well as integrated hard DDR3 memory controllers with error correction.

SmartFusion2 devices integrate an entire low power real time Microcontroller Subsystem with a rich set of Industry standard peripherals including Ethernet, USB, and CAN, while IGLOO2 devices integrate a high-performance memory subsystem with on-chip flash, 32 Kbyte embedded SRAM, and multiple DMA controllers.

2. Device Status

For more information on device status, refer to the ["Datasheet Categories"](#) section on page 139.

Table 1 • IGLOO2 FPGA and SmartFusion2 SoC FPGA Device Status

Design Security Device Densities	Status
005	Production
010, 010T	Production
025, 025T	Production
050, 050T	Production
060, 060T	Production
090, 090T	Production
150, 150T	Production
Data Security Device Densities	Status
005S	Production
010TS	Production
025TS	Production
050TS	Production
060TS	Production
090TS	Production
150TS	Production

3. Product Briefs and Pin Descriptions

The product brief and pin descriptions are published separately:

- PB0121: IGLOO2 Product Brief
- DS0124: IGLOO2 Pin Descriptions
- PB0115: SmartFusion2 SoC FPGA Product Brief
- DS0115: SmartFusion2 Pin Descriptions

4. General Specifications

4.1 Operating Conditions

Stresses beyond those listed in [Table 2](#) may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Absolute maximum ratings are stress ratings only; functional operation of the device at these or any other conditions beyond those listed under the recommended operating conditions specified in [Table 2](#) is not implied.

Table 2 • Absolute Maximum Ratings

Symbol	Parameter	Limits		Units	Notes
		Min	Max		
VDD	DC core supply voltage. Must always power this pin.	-0.3	1.32	V	-
VPP	Power supply for charge pumps (for normal operation and programming). Must always power this pin.	-0.3	3.63	V	-
MSS_MDDR_PLL_VDDA	Analog power pad for MDDR PLL	-0.3	3.63	V	-
HPMS_MDDR_PLL_VDDA	Analog power pad for MDDR PLL	-0.3	3.63	V	-
FDDR_PLL_VDDA	Analog power pad for FDDR PLL	-0.3	3.63	V	-
PLL0_PLL1_MSS_MDDR_VDDA	Analog power pad for MDDR PLL	-0.3	3.63	V	-
PLL0_PLL1_HPMS_MDDR_VDDA	Analog power pad for MDDR PLL	-0.3	3.63	V	-
CCC_XX[01]_PLL_VDDA	Analog power pad for PLL0–5	-0.3	3.63	V	-
SERDES_[01]_PLL_VDDA	High supply voltage for PLL SERDES[01]	-0.3	3.63	V	-
SERDES_[01]_L[0123]_VDDAPLL	Analog power for SERDES[01] PLL lane0 to lane3. This is a +2.5 V SERDES internal PLL supply.	-0.3	2.75	V	-
SERDES_[01]_L[0123]_VDDAIO	TX/RX analog I/O voltage. Low voltage power for the lanes of SERDESIF0. This is a +1.2 V SERDES PMA supply.	-0.3	1.32	V	-
SERDES_[01]_VDD	PCIe®/PCS power supply	-0.3	1.32	V	-
VDDIx	DC FPGA I/O buffer supply voltage for MSIO I/O Bank	-0.3	3.63	V	-
	DC FPGA I/O buffer supply voltage for MSIOD/DDRIO I/O Banks	-0.3	2.75	V	-
VI	I/O Input voltage for MSIO I/O Bank	-0.3	3.63	V	-
	I/O Input voltage for MSIOD/DDRIO I/O Bank	-0.3	2.75	V	-
VPPNVM	Analog sense circuit supply of embedded nonvolatile memory (eNVM). Must be shorted to VPP.	-0.3	3.63	V	-
T _{STG}	Storage temperature	-65	150	°C	*

Table 2 • Absolute Maximum Ratings (continued)

Symbol	Parameter	Limits		Units	Notes
		Min	Max		
T _J	Junction temperature	-55	125	°C	-

Note: *For flash programming and retention maximum limits, refer to Table 4 on page 15. For recommended operating conditions, refer to Table 3.

Table 3 • Recommended Operating Conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Units	Notes
T _J	Operating Junction Temperature	Commercial	0	25	85	°C	-
		Industrial	-40	25	100	°C	-
	Programming Junction Temperatures	Commercial	0	25	85	°C	-
		Industrial	-40	25	100	°C	1
VDD	DC core supply voltage. Must always power this pin.	-	1.14	1.2	1.26	V	-
VPP	Power supply for charge pumps (for normal operation and programming) for the 005, 010, 025, 050,060 devices	2.5 V range	2.375	2.5	2.625	V	-
		3.3 V range	3.15	3.3	3.45	V	-
	Power supply for charge pumps (for normal operation and programming) for the 090 and 150 devices	3.3 V range	3.15	3.3	3.45	V	-
MSS_MDDR_PLL_VDDA	Analog power pad for MDDR PLL	2.5 V range	2.375	2.5	2.625	V	-
		3.3 V range	3.15	3.3	3.45	V	-
HPMS_MDDR_PLL_VDDA	Analog power pad for MDDR PLL	2.5 V range	2.375	2.5	2.625	V	-
		3.3 V range	3.15	3.3	3.45	V	-
FDDR_PLL_VDDA	Analog power pad for FDDR PLL	2.5 V range	2.375	2.5	2.625	V	-
		3.3 V range	3.15	3.3	3.45	V	-
PLL0_PLL1_MSS_MDDR_VDDA	Analog power pad for MDDR PLL	2.5 V range	2.375	2.5	2.625	V	-
		3.3 V range	3.15	3.3	3.45	V	-
PLL0_PLL1_HPMS_MDDR_VDDA	Analog power pad for MDDR PLL	2.5 V range	2.375	2.5	2.625	V	-
		3.3 V range	3.15	3.3	3.45	V	-
CCC_XX[01]_PLL_VDDA	Analog power pad for PLL0 to PLL5	2.5 V range	2.375	2.5	2.625	V	-
		3.3 V range	3.15	3.3	3.45	V	-
SERDES_[01]_PLL_VDDA	High supply voltage for PLL SERDES[01]	2.5 V range	2.375	2.5	2.625	V	2
		3.3 V range	3.15	3.3	3.45	V	2
SERDES_[01]_L[0123]_VDDAPLL	Analog power for SERDES[01] PLL Lane0 to Lane3. This is a +2.5 V SERDES internal PLL supply.		2.375	2.5	2.625	V	-

Notes:

1. Programming at Industrial temperature range is available only with VPP = 3.3V.
2. Power supply ramps must all be strictly monotonic, without plateaus.

Table 3 • Recommended Operating Conditions (continued)

Symbol	Parameter	Conditions	Min	Typ	Max	Units	Notes
SERDES_[01]_L[0123]_VDDAIO	TX/RX analog I/O voltage. Low voltage power for the lanes of SERDESIF0. This is a +1.2 V SERDES PMA supply.		1.14	1.2	1.26	V	–
SERDES_[01]_VDD	PCIe/PCS power supply		1.14	1.2	1.26	V	–
Symbol	Parameter	Conditions	Min	Typ	Max	Units	Notes
VDDIx	1.2 V DC supply voltage	–	1.14	1.2	1.26	V	–
	1.5 V DC supply voltage	–	1.425	1.5	1.575	V	–
	1.8 V DC supply voltage	–	1.71	1.8	1.89	V	–
	2.5 V DC supply voltage	–	2.375	2.5	2.625	V	–
	3.3 V DC supply voltage	–	3.15	3.3	3.45	V	–
	LVDS differential I/O	–	2.375	2.5	3.45	V	–
	B-LVDS, M-LVDS, Mini-LVDS, RSDS differential I/O	–	2.375	2.5	2.625	V	–
	LVPECL differential I/O	–	3.15	3.3	3.45	V	–
VREFx	Reference voltage supply for FDDR (Bank0) and MDDR (Bank5)		0.49 × VDDIx	0.5 × VDDIx	0.51 × VDDIx	V	–
VPPNVM	Analog sense circuit supply of embedded nonvolatile memory (eNVM). Must be shorted to VPP.	2.5 V range	2.375	2.5	2.625	V	–
		3.3 V range	3.15	3.3	3.45	V	–
Notes:							
1. Programming at Industrial temperature range is available only with VPP = 3.3V.							
2. Power supply ramps must all be strictly monotonic, without plateaus.							

Table 4 • FPGA Operating Limits

Product Grade	Element	Programming Temperature	Operating Temperature	Programming Cycles	Digest Temperature	Digest Cycles	Retention (Biased/Unbiased)	Notes
Commercial	FPGA	Min T _J = 0°C Max T _J = 85°C	Min T _J = 0°C Max T _J = 85°C	500	Min T _J = 0°C Max T _J = 85°C	2000	20 years	–
Industrial	FPGA	Min T _J = –40°C Max T _J = 100°C	Min T _J = –40°C Max T _J = 100°C	500	Min T _J = –40°C Max T _J = 100°C	2000	20 years	*

Notes:

- * Programming at Industrial temperature range is available only with VPP = 3.3 V
- The retention specification is defined to be the total number of programming and digest cycles. For example, 20 years of retention after 500 programming cycles.
- The digest cycle specification is 2000 digest cycles for every program cycle with a maximum of 500 programming cycles.

Table 5 • Embedded Operating Flash Limits

Product Grade	Element	Programming Temperature	Maximum Operating Temperature	Programming Cycles	Retention (Biased/Unbiased)
Commercial	Embedded flash	Min T _J = 0°C Max T _J = 85°C	Min T _J = 0°C Max T _J = 85°C	< 1000 cycles per page, up to two million cycles per eNVM Array	20 years
			Min T _J = 0°C Max T _J = 85°C	< 10000 cycles per page, up to 20 million cycles per eNVM Array	10 years
Industrial	Embedded flash	Min T _J = –40°C Max T _J = 100°C	Min T _J = –40°C Max T _J = 100°C	< 1000 cycles per page, up to two million cycles per eNVM Array	20 years
			Min T _J = –40°C Max T _J = 100°C	< 10000 cycles per page, up to 20 million cycles per eNVM Array	10 years

Note: If accelerated programming cycles are required as part of your product qualification, refer to the RT0001: Microsemi Corporation - SoC Products Reliability Report on recommended methodologies.

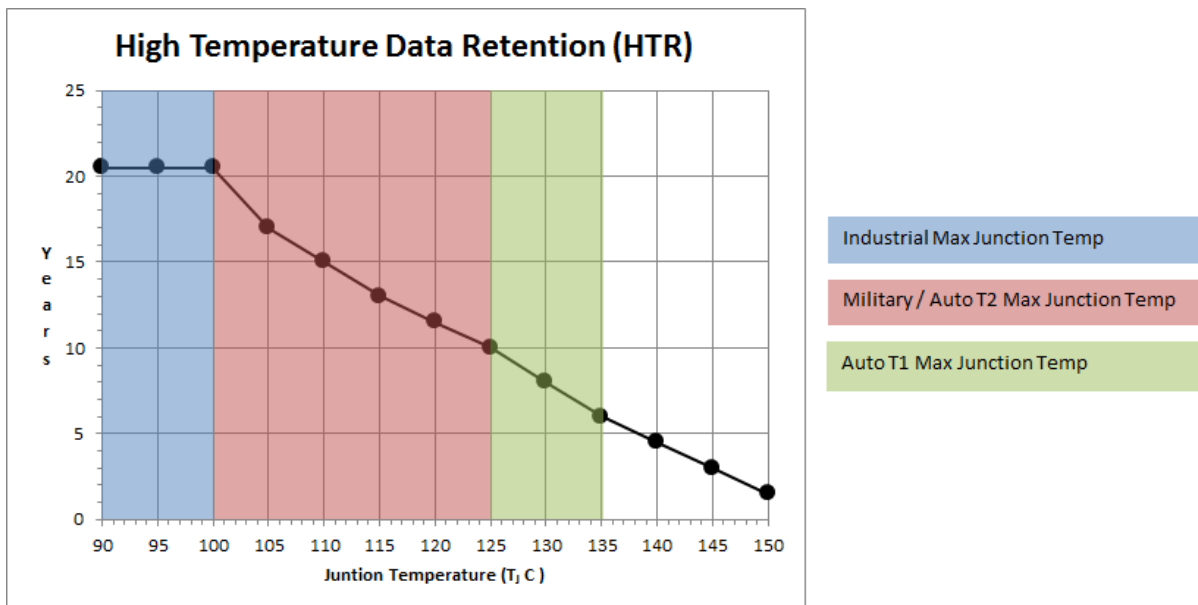
Table 6 • Device Storage Temperature and Retention

Product Grade	Storage Temperature (Tstg)	Retention
Commercial	Min T _J = 0°C Max T _J = 85°C	20 years
Industrial	Min T _J = –40°C Max T _J = 100°C	20 years

Table 7 • High Temperature Data Retention (HTR) Lifetime

T_J (C)	HTR Lifetime * (yrs)
90	20.5
95	20.5
100	20.5
105	17.0
110	15.0
115	13.0
120	11.5
125	10.0
130	8.0
135	6.0
140	4.5
145	3.0
150	1.5

Note: * HTR Lifetime is the period during which a verify failure is not expected due to flash leakage.


Figure 1 • High Temperature Data Retention (HTR)

4.2. Overshoot/Undershoot Limits

For AC signals, the input signal may undershoot during transitions to -1.0 V for no longer than 10% of the period. The current during the transition must not exceed 100mA.

For AC signals, the input signal may overshoot during transitions to VCCI + 1.0 V for no longer than 10% of the period. The current during the transition must not exceed 100mA.

Note: The above specification does not apply to the PCI standard. The IGLOO2 and SmartFusion2 PCI I/Os are compliant to the PCI standard including the PCI overshoot/undershoot specifications.

4.3 Thermal Characteristics

4.3.1 Introduction

The temperature variable in the Microsemi SoC Products Group Designer software refers to the junction temperature, not the ambient, case, or board temperatures. This is an important distinction because dynamic and static power consumption causes the chip's junction temperature to be higher than the ambient, case, or board temperatures.

EQ 1 through EQ 3 give the relationship between thermal resistance, temperature gradient, and power.

$$\theta_{JA} = \frac{T_J - T_A}{P}$$

EQ 1

$$\theta_{JB} = \frac{T_J - T_B}{P}$$

EQ 2

$$\theta_{JC} = \frac{T_J - T_C}{P}$$

EQ 3

where

- θ_{JA} = Junction-to-air thermal resistance
- θ_{JB} = Junction-to-board thermal resistance
- θ_{JC} = Junction-to-case thermal resistance
- T_J = Junction temperature
- T_A = Ambient temperature
- T_B = Board temperature (measured 1.0 mm away from the package edge)
- T_C = Case temperature
- P = Total power dissipated by the device

Table 8 • Package Thermal Resistance

Product M2GL/M2S	θ_{JA}			θ_{JB}	θ_{JC}	Units
	Still Air	1.0 m/s	2.5 m/s			
005						
FG484	19.36	15.81	14.63	9.74	5.27	°C/W
VF256	41.30	38.16	35.30	28.41	3.94	°C/W
VF400	20.19	16.94	15.41	8.86	4.95	°C/W
TQ144	42.80	36.80	34.50	37.20	10.80	°C/W
010						
FG484	18.22	14.83	13.62	8.83	4.92	°C/W
VF256	37.36	34.26	31.45	24.84	7.89	°C/W

Table 8 • Package Thermal Resistance (continued)

Product M2GL/M2S	θ_{JA}			θ_{JB}	θ_{JC}	Units
	Still Air	1.0 m/s	2.5 m/s			
VF400	19.40	15.75	14.22	8.11	4.22	°C/W
TQ144	38.60	32.60	30.30	31.80	8.60	°C/W
025						
FG484	17.03	13.66	12.45	7.66	4.18	°C/W
VF256	33.85	30.59	27.85	21.63	6.13	°C/W
VF400	18.36	14.89	13.36	7.12	3.41	°C/W
FCS325	29.17	24.87	23.12	14.44	2.31	°C/W
050						
FG484	15.29	12.19	10.99	6.27	3.24	°C/W
FG896	14.70	12.50	10.90	7.20	4.90	°C/W
VF400	17.53	14.17	12.63	6.32	2.81	°C/W
FCS325	27.38	23.18	21.41	12.47	1.59	°C/W
060						
FG484	15.40	12.06	10.85	6.14	3.15	°C/W
FG676	15.49	12.21	11.06	7.07	3.87	°C/W
VF400	17.45	14.01	12.47	6.22	2.69	°C/W
FCS325	27.03	22.91	21.25	12.33	1.54	°C/W
090						
FG484	14.64	11.37	10.16	5.43	2.77	°C/W
FG676	14.52	11.19	10.37	6.17	3.24	°C/W
FCS325	26.63	22.26	20.13	14.24	2.50	°C/W
150						
FC1152	9.08	6.81	5.87	2.56	0.38	°C/W
FCS536	15.01	12.06	10.76	3.69	1.55	°C/W
FCV484	16.21	13.11	11.84	6.73	0.10	°C/W

4.3.2 Theta-JA

Junction-to-ambient thermal resistance (θ_{JA}) is determined under standard conditions specified by JEDEC (JESD-51), but it has little relevance in actual performance of the product. It should be used with caution, but it is useful for comparing the thermal performance of one package to another.

The maximum power dissipation allowed is calculated using [EQ 4](#).

$$\text{Maximum Power Allowed} = \frac{T_{J(\text{MAX})} - T_{A(\text{MAX})}}{\theta_{JA}}$$

EQ 4

The absolute maximum junction temperature is 100°C. [EQ 5](#) shows a sample calculation of the absolute maximum power dissipation allowed for the M2GL050T-FG896 package at commercial temperature and in still air, where

$$\theta_{JA} = 14.7^\circ\text{C/W (taken from Table 8 on page 17).}$$

$$T_A = 85^\circ\text{C}$$

$$\text{Maximum Power Allowed} = \frac{100^{\circ}\text{C} - 85^{\circ}\text{C}}{14.7^{\circ}\text{C/W}} = 1.088 \text{ W}$$

EQ 5

The power consumption of a device can be calculated using the Microsemi SoC Products Group power calculator. The device's power consumption must be lower than the calculated maximum power dissipation by the package.

If the power consumption is higher than the device's maximum allowable power dissipation, a heat sink can be attached on top of the case, or the airflow inside the system must be increased.

4.3.3 Theta-JB

Junction-to-board thermal resistance (θ_{JB}) measures the ability of the package to dissipate heat from the surface of the chip to the PCB. As defined by the JEDEC (JESD-51) standard, the thermal resistance from junction to board uses an isothermal ring cold plate zone concept. The ring cold plate is simply a means to generate an isothermal boundary condition at the perimeter. The cold plate is mounted on a JEDEC standard board with a minimum distance of 5.0 mm away from the package edge.

4.3.4 Theta-JC

Junction-to-case thermal resistance (θ_{JC}) measures the ability of a device to dissipate heat from the surface of the chip to the top or bottom surface of the package. It is applicable for packages used with external heat sinks. Constant temperature is applied to the surface in consideration and acts as a boundary condition.

This only applies to situations where all or nearly all of the heat is dissipated through the surface in consideration.

5. Power Consumption

5.1 Quiescent Supply Current

Table 9 • Quiescent Supply Current Characteristics

Power Supplies/Blocks	Modes and Configurations		Notes
	Non-Flash*Freeze Mode	Flash*Freeze Mode	
FPGA Core	On	Off	–
VDD / SERDES_[01]_VDD	On	On	1
VPP / VPPNVM	On	On	–
HPMS_MDDR_PLL_VDDA / FDDR_PLL_VDDA / CCC_XX[01]_PLL_VDDA / PLL0_PLL1_HPMS_MDDR_VDDA	0 V	0 V	–
SERDES_[01]_PLL_VDDA	0 V	0 V	3
SERDES_[01]_L[0123]_VDDAPLL / VDD_2V5	On	On	3
SERDES_[01]_L[0123]_VDDAIO	On	On	3
VDDIx	On	On	2, 4
VREFx	On	On	–
MSSDDR CLK	32 kHz	32 kHz	–
RAM	On	Sleep state	–
System Controller	50 MHz	50 MHz	–
50 MHz Oscillator (enable/disable)	Enable	Disabled	–
1 MHz Oscillator (enable/disable)	Disabled	Disabled	–

Table 9 • Quiescent Supply Current Characteristics (continued)

Crystal Oscillator (enable/disable)	Disabled	Disabled	–
Notes: 1. SERDES_[01]_VDD Power Supply is shorted to VDD. 2. VDDix has been set to ON for test conditions as described. Banks on the east side should always be powered with the appropriate VDDi Bank supplies. For details on bank power supplies, refer to the “Recommendation for Unused Bank Supplies” table in the AC393: SmartFusion2 and IGLOO2 Board Design Guidelines Application Note. 3. SERDES and DDR blocks to be unused. 4. No Differential (that is to say, LVDS) I/O's or ODT attributes to be used.			

Table 10 • SmartFusion2 and IGLOO2 Quiescent Supply Current – Typical Process

Parameter	Modes	Conditions	005	010	025	050	060	090	150	Units
			VDD=1.2 V	VDD=1.2 V	VDD=1.2 V	VDD=1.2 V	VDD= 1.2 V	VDD=1.2 V	VDD=1.2 V	
IDC1	Non-Flash*Freeze	Typical (T _J = 25°C)	6.2	6.9	8.9	13.1	15.3	15.4	27.5	mA
		Commercial (T _J = 85°C)	24.0	28.4	40.6	67.8	80.6	81.4	144.7	mA
		Industrial (T _J = 100°C)	35.2	41.9	60.5	102.1	121.4	122.6	219.1	mA
IDC2	Flash*Freeze	Typical (T _J = 25°C)	1.4	2.6	3.7	5.1	5.0	5.1	8.9	mA
		Commercial (T _J = 85°C)	12.0	20.0	26.6	35.3	35.4	35.7	57.8	mA
		Industrial (T _J = 100°C)	18.5	30.8	41.0	54.5	54.5	55.0	89.0	mA

Table 11 • SmartFusion2 and IGLOO2 Quiescent Supply Current – Worst-Case Process

Parameter	Modes	Conditions	005	010	025	050	060	090	150	Units
			VDD=1.26 V	VDD=1.26 V	VDD=1.26 V	VDD=1.26 V	VDD=1.26 V	VDD=1.26 V	VDD=1.26 V	
IDC1	Non-Flash*Freeze	Commercial (T _J = 85°C)	43.8	57.0	84.6	132.3	161.4	163.0	242.5	mA
		Industrial (T _J = 100°C)	65.3	85.7	127.8	200.9	245.4	247.8	369.0	mA
IDC2	Flash*Freeze	Commercial (T _J = 85°C)	29.1	45.6	51.7	62.7	69.3	70.0	84.8	mA
		Industrial (T _J = 100°C)	44.9	70.3	79.7	96.5	106.8	107.8	130.6	mA

5.2. Programming Currents

The tables below represent programming, verify and Inrush currents for SmartFusion2 SoC and IGLOO2 FPGA devices.

Table 12 • Currents During Program Cycle, 0°C ≤ T_j ≤ 85°C – Typical Process

Power Supplies	Voltage (V)	005	010	025	050	060	090	150	Units	Notes
VDD	1.26	46	53	55	58	30	42	52	mA	–
VPP	3.46	8	11	6	10	9	12	12	mA	–
VPPNVM	3.46	1	2	2	3	3	3	*	mA	–
VDDI	2.62	31	16	17	1	12	12	81	mA	–
	3.46	62	31	36	1	12	17	84	mA	–
Number of banks	–	7	8	8	10	10	9	19	–	–

*Note: *VPP and VPPNVM are internally shorted.*

Table 13 • Currents During Verify Cycle, 0°C ≤ T_j ≤ 85°C – Typical Process

Power Supplies	Voltage (V)	005	010	025	050	060	090	150	Units	Notes
VDD	1.26	44	53	55	58	33	41	51	mA	–
VPP	3.46	6	5	3	15	8	11	12	mA	–
VPPNVM	3.46	1	0	0	1	1	1	*	mA	–
VDDI	2.62	31	16	17	1	12	11	81	mA	–
	3.46	61	32	36	1	12	17	84	mA	–
Number of banks	–	7	8	8	10	10	9	19	–	–

*Note: *VPP and VPPNVM are internally shorted.*

Table 14 • Inrush Currents at Power up, –40°C ≤ T_j ≤ 100°C – Typical Process

Power Supplies	Voltage (V)	005	010	025	050	060	090	150	Units
VDD	1.26	25	32	38	48	45	77	109	mA
VPP	3.46	33	49	36	180	13	36	51	mA
VDDI	2.62	134	141	161	187	93	272	388	mA
Number of banks	–	7	8	8	10	10	9	19	–

6. Average Fabric Temperature and Voltage Derating Factors

Table 15 • Average Temperature and Voltage Derating Factors for Fabric Timing Delays

Normalized to T_j = 85°C, Worst-case VDD = 1.14 V

Array Voltage VDD (V)	Junction Temperature (°C)					
	–40°C	0°C	25°C	70°C	85°C	100°C
1.14	0.83	0.89	0.92	0.98	1.00	1.02
1.2	0.75	0.80	0.83	0.89	0.91	0.93
1.26	0.69	0.73	0.76	0.81	0.83	0.85

7. Timing Model

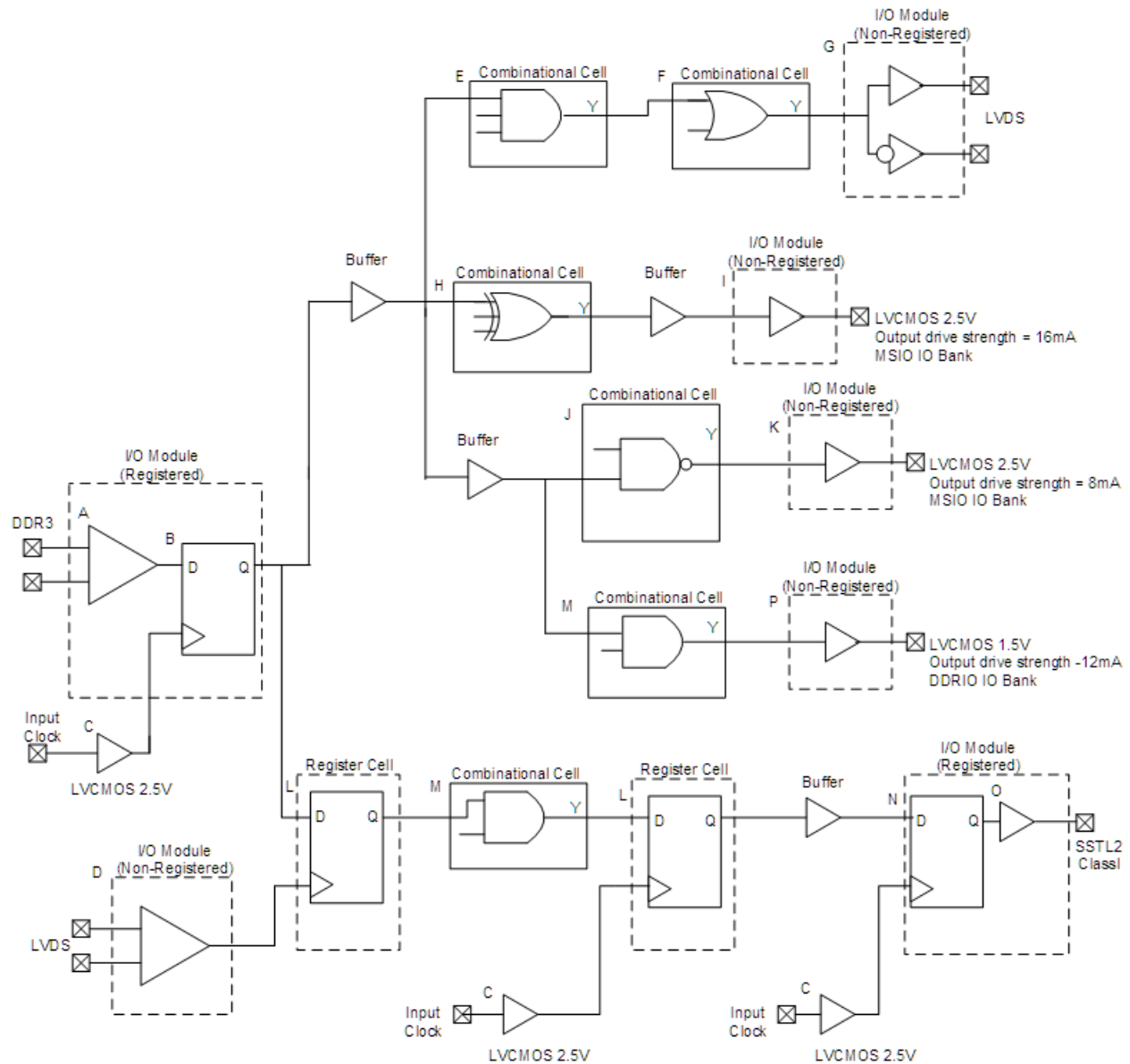


Figure 2 • Timing Model

Table 16 • Timing Model Parameters

Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Index	Parameter	Description	Speed Grade -1	Units	For More Information
A	t_{pY}	Propagation delay of DDR3 Receiver	1.605	ns	Refer to page 55
B	t_{iCLKQ}	Clock-to-Q of the Input Data Register	0.16	ns	Refer to page 76
	t_{iSUD}	Setup Time of the Input Data Register	0.357	ns	Refer to page 76
C	t_{rCKH}	Input High Delay for Global Clock	1.53	ns	Refer to page 83
	t_{rCKL}	Input Low Delay for Global Clock	0.897	ns	Refer to page 83

Table 16 • Timing Model Parameters (continued)
Worst Commercial-Case Conditions: T_J = 85°C, VDD = 1.14 V

Index	Parameter	Description	Speed Grade –1	Units	For More Information
D	t _{PY}	Input Propagation Delay of LVDS Receiver	2.774	ns	Refer to page 62
E	t _{DP}	Propagation Delay of a three-input AND Gate	0.198	ns	Refer to page 80
F	t _{DP}	Propagation Delay of an OR Gate	0.179	ns	Refer to page 80
G	t _{DP}	Propagation Delay of an LVDS Transmitter	2.136	ns	Refer to page 62
H	t _{DP}	Propagation Delay of a three-input XOR Gate	0.241	ns	Refer to page 80
I	t _{DP}	Propagation Delay of LVCMOS 2.5 V Transmitter, Drive strength of 16 mA on the MSIO Bank	2.412	ns	Refer to page 34
J	t _{DP}	Propagation Delay of a two-input NAND Gate	0.179	ns	Refer to page 80
K	t _{DP}	Propagation Delay of LVCMOS 2.5 V Transmitter, Drive strength of 8 mA on the MSIO Bank	2.309	ns	Refer to page 34
L	t _{CLKQ}	Clock-to-Q of the Data Register	0.108	ns	Refer to page 82
	t _{SUD}	Setup Time of the Data Register	0.254	ns	Refer to page 82
M	t _{DP}	Propagation Delay of a two-input AND Gate	0.179	ns	Refer to page 80
N	t _{OCLKQ}	Clock-to-Q of the Output Data Register	0.263	ns	Refer to page 73
	t _{OSUD}	Setup Time of the Output Data Register	0.19	ns	Refer to page 73
O	t _{DP}	Propagation Delay of SSTL2, Class I Transmitter on the MSIO Bank	2.055	ns	Refer to page 51
P	t _{DP}	Propagation Delay of LVCMOS 1.5 V Transmitter, Drive strength of 12 mA, fast slew on the DDRIO Bank	3.316	ns	Refer to page 41

8. User I/O Characteristics

There are three types of I/Os supported in the IGLOO2 FPGA and SmartFusion2 SoC FPGA Families: MSIO, MSIOD, and DDRIO I/O banks. The I/O standards supported by the different I/O banks is described in the "I/Os" section of the [UG0445: IGLOO2 FPGA and SmartFusion2 SoC FPGA Fabric User Guide](#).

8.1 Input Buffer and AC Loading

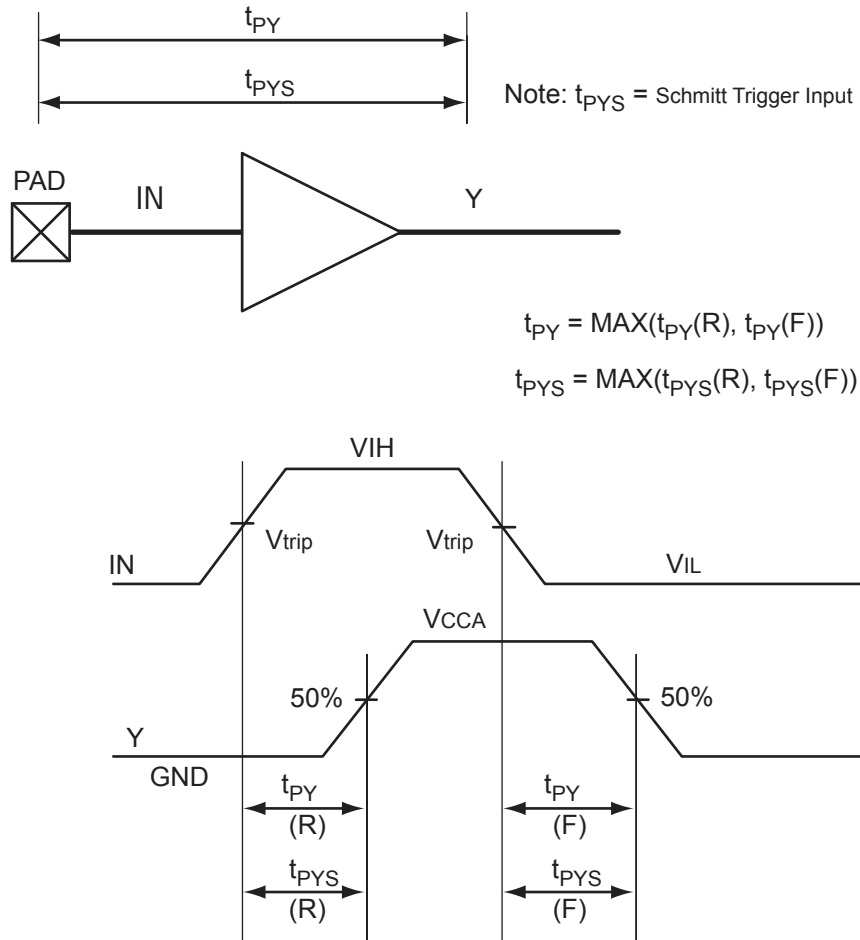


Figure 3 • Input Buffer AC Loading

8.2. Output Buffer and AC Loading

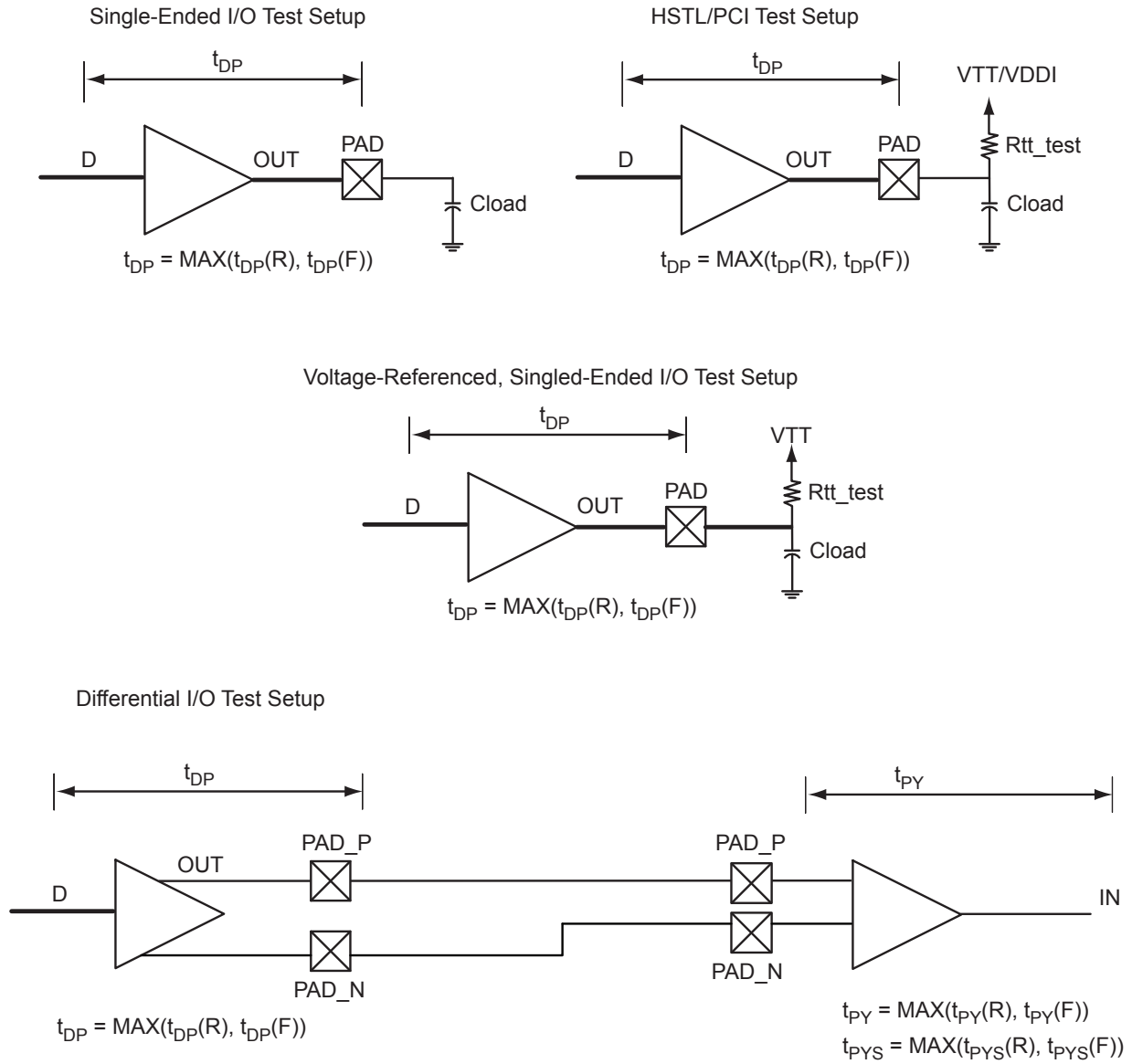


Figure 4 • Output Buffer AC Loading

8.3. Tristate Buffer and AC Loading

The tristate path for enable path loadings is described in the respective specifications. The methodology of characterization is illustrated by the enable path test point shown in Figure 5.

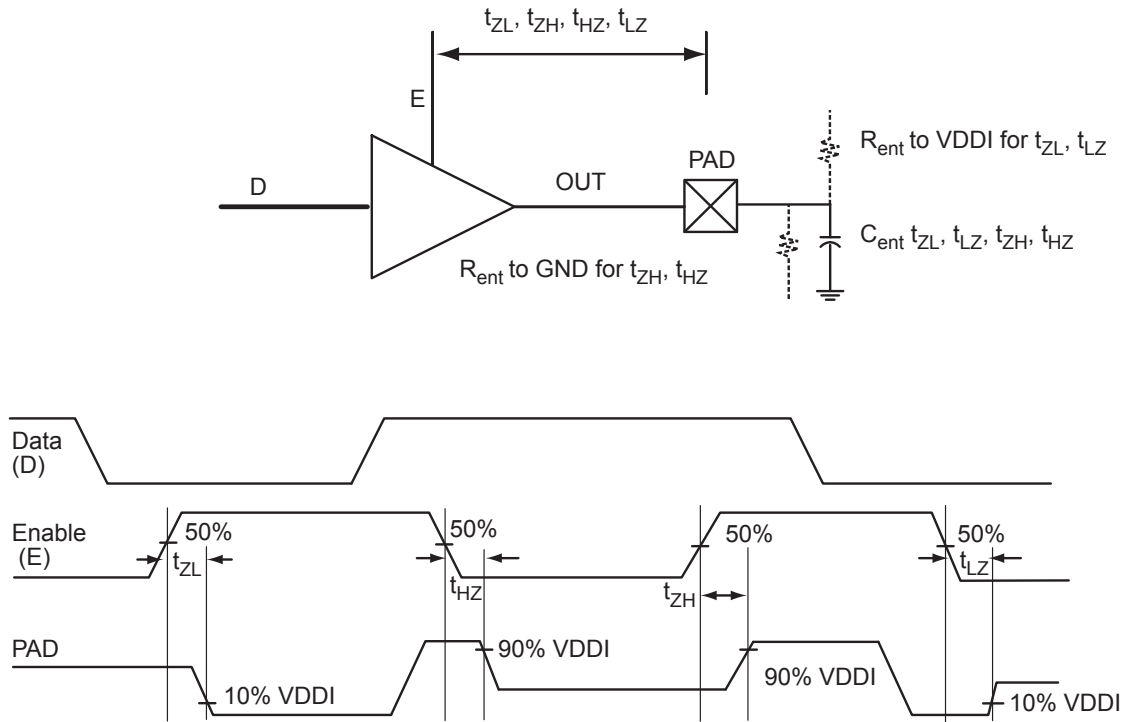


Figure 5 • Tristate Buffer for Enable Path Test Point

8.4 I/O Speeds

Table 17 • Maximum Data Rate Summary Table for Worst-Case Industrial Conditions

Single-Ended I/O	MSIO	MSIOD	DDRIO	Units
PCI 3.3 V	630	–	–	Mbps
LVTTL 3.3 V	600	–	–	Mbps
LVC MOS 3.3 V	600	–	–	Mbps
LVC MOS 2.5 V	410	420	400	Mbps
LVC MOS 1.8 V	295	400	400	Mbps
LVC MOS 1.5 V	160	220	235	Mbps
LVC MOS 1.2 V	120	160	200	Mbps
LPDDR-LVC MOS 1.8 V Mode	–	–	400	Mbps
Voltage-Referenced I/O	MSIO	MSIOD	DDRIO	Units
LPDDR	–	–	400	Mbps
HSTL 1.5 V	–	–	400	Mbps
SSTL 2.5 V	510	700	400	Mbps
Voltage-Referenced I/O	MSIO	MSIOD	DDRIO	Units
SSTL 1.8 V	–	–	667	Mbps
SSTL 1.5 V	–	–	667	Mbps
Differential I/O	MSIO	MSIOD	DDRIO	Units
LVPECL (input only)	900	–	–	Mbps
LVDS 3.3 V	535	–	–	Mbps
LVDS 2.5 V	535	700	–	Mbps
RS DS	520	700	–	Mbps
BLVDS	500	–	–	Mbps
MLVDS	500	–	–	Mbps
Mini-LVDS	520	700	–	Mbps

Note: Refer to the individual I/O standards for operating conditions.

Table 18 • Maximum Frequency Summary Table for Worst-Case Industrial Conditions

Single-Ended I/O	MSIO	MSIOD	DDRIO	Units
PCI 3.3 V	315	–	–	MHz
LVTTL 3.3 V	300	–	–	MHz
LVC MOS 3.3 V	300	–	–	MHz
LVC MOS 2.5 V	205	210	200	MHz
LVC MOS 1.8 V	147.5	200	200	MHz
LVC MOS 1.5 V	80	110	118	MHz
LVC MOS 1.2 V	60	80	100	MHz
LPDDR– LVC MOS 1.8 V mode	–	–	200	MHz

Table 18 • Maximum Frequency Summary Table for Worst-Case Industrial Conditions (continued)

Voltage-Referenced I/O	MSIO	MSIOD	DDRIO	Units
LPDDR	–	–	200	MHz
HSTL1.5 V	–	–	200	MHz
SSTL 2.5 V	255	350	200	MHz
SSTL 1.8 V	–	–	334	MHz
SSTL 1.5 V	–	–	334	MHz
Differential I/O	MSIO	MSIOD	DDRIO	Units
LVPECL (input only)	450	–	–	MHz
LVDS 3.3 V	267.5	–	–	MHz
LVDS 2.5 V	267.5	350	–	MHz
RSDS	260	350	–	MHz
BLVDS	250	–	–	MHz
MLVDS	250	–	–	MHz
Mini-LVDS	260	350	–	MHz

Note: Refer to the individual I/O standards for operating conditions.

8.5 Detailed I/O Characteristics

Table 19 • Input Capacitance and Leakage Current

Symbol	Definition	Minimum	Maximum	Units	Notes
C_{IN}	Input capacitance	–	10	pF	–
IIL (dc)	Input Current LOW (Applicable to all digital inputs)	–	10	μA	–
IIH (dc)	Input Current HIGH (Applicable to all digital inputs)	–	10	μA	–
T_{RAMPIN}	Input Ramp Time (Applicable to all digital inputs)	–	50	ns	*

Note: * Voltage ramp must be monotonic.

Table 20 • I/O Weak Pull-Up/Pull-Down Resistances for DDRIO I/O Bank
 Minimum and Maximum Weak Pull-Up/Pull-Down Resistance Values at VOH/VOL Level

	DDRIO I/O Bank				Notes
	R(WEAK PULL-UP) at VOH (Ω)		R(WEAK PULL-DOWN) at VOL (Ω)		
VDDI Domain	Min	Max	Min	Max	
2.5 V	10K	17.8K	9.98K	18K	1, 2
1.8 V	10.3K	19.1K	10.3K	19.5K	1, 2
1.5 V	10.6K	20.2K	10.6K	21.1K	1, 2
1.2 V	11.1K	22.7K	11.2K	24.6K	1, 2

Notes:

- $R(\text{WEAK PULL-DOWN}) = (V_{OLspec}) / I(\text{WEAK PULL-DOWN MAX})$
- $R(\text{WEAK PULL-UP}) = (V_{DDImax} - V_{OHspec}) / I(\text{WEAK PULL-UP MIN})$

Table 21 • I/O Weak Pull-Up/Pull-Down Resistances for MSIO I/O Bank
 Minimum and Maximum Weak Pull-Up/Pull-Down Resistance Values at VOH/VOL Level

	MSIO I/O Bank				Notes
	R(WEAK PULL-UP) at VOH (Ω)		R(WEAK PULL-DOWN) at VOL (Ω)		
VDDI Domain	Min	Max	Min	Max	
3.3 V	9.9K	17.1K	9.98K	17.5K	–
2.5 V	10K	17.6K	10.1K	18.4K	1, 2
1.8 V	10.4K	19.1K	10.4K	20.4K	1, 2
1.5 V	10.7K	20.4K	10.8K	22.2K	1, 2
1.2 V	11.3K	23.2K	11.5K	26.7K	1, 2

Notes:

- $R(\text{WEAK PULL-DOWN}) = (V_{OLspec}) / I(\text{WEAK PULL-DOWN MAX})$
- $R(\text{WEAK PULL-UP}) = (V_{DDImax} - V_{OHspec}) / I(\text{WEAK PULL-UP MIN})$

Table 22 • I/O Weak Pull-Up/Pull-Down Resistances for MSIOD I/O Bank
 Minimum and Maximum Weak Pull-Up/Pull-Down Resistance Values at VOH/VOL Level

	MSIOD I/O Bank				Notes
	R(WEAK PULL-UP) at VOH (Ω)		R(WEAK PULL-DOWN) at VOL (Ω)		
VDDI Domain	Min	Max	Min	Max	
2.5 V	9.6K	16.6K	9.5K	16.4K	1, 2
1.8 V	9.7K	17.3K	9.7K	17.1K	1, 2
1.5 V	9.9K	18K	9.8K	17.6K	1, 2
1.2 V	10.3K	19.6K	10K	19.1K	1, 2

Notes:

- $R(\text{WEAK PULL-DOWN}) = (V_{OLspec}) / I(\text{WEAK PULL-DOWN MAX})$
- $R(\text{WEAK PULL-UP}) = (V_{DDImax} - V_{OHspec}) / I(\text{WEAK PULL-UP MIN})$

Table 23 • Schmitt Trigger Input Hysteresis
 Hysteresis Voltage Value for Schmitt Trigger Mode Input Buffers

Input Buffer Configuration	Hysteresis Value (Typical, unless otherwise noted)
3.3 V LVTTTL / LVCMOS / PCI / PCI-X	$0.05 \times VDDI$ (Worst-case)
2.5 V LVCMOS	$0.05 \times VDDI$ (Worst-case)
1.8 V LVCMOS	$0.1 \times VDDI$ (Worst-case)
1.5 V LVCMOS	60 mV
1.2 V LVCMOS	20 mV

8.6 Single-Ended I/O Standards

8.6.1 Low Voltage Complementary Metal Oxide Semiconductor (LVCMOS)

LVCMOS is a widely used switching standard implemented in CMOS transistors. This standard is defined by JEDEC (JESD 8-5). The LVCMOS standards supported in IGLOO2 FPGAs and SmartFusion2 SoC FPGAs are: LVCMOS12, LVCMOS15, LVCMOS18, LVCMOS25, and LVCMOS33.

8.6.2 3.3 V LVCMOS/LVTTTL

LVCMOS 3.3 V or Low-Voltage Transistor-Transistor Logic (LVTTTL) is a general standard for 3.3 V applications.

8.6.2.1 Minimum and Maximum DC/AC Input and Output Levels Specification

Table 24 • LVTTTL/LVCMOS 3.3 V DC Voltage Specification (Applicable to MSIO I/O Bank Only)

Symbol	Parameters	Conditions	Min	Typ	Max	Units	Notes
LVTTTL/LVCMOS 3.3 V DC Recommended DC Operating Conditions							
VDDI	Supply voltage		3.15	3.3	3.45	V	–
LVTTTL/LVCMOS 3.3 V DC Input Voltage Specification							
VIH (DC)	DC input logic High		2.0	–	3.45	V	–
VIL (DC)	DC input logic Low		–0.3	–	0.8	V	–
IIH (DC)	Input current High		–	–	Table 19 on page 28	–	–
IIL (DC)	Input current Low		–	–	Table 19 on page 28	–	–
Symbol	Parameters	Conditions	Min	Typ	Max	Units	Notes
LVCMOS 3.3 V DC Output Voltage Specification							
VOH	DC output logic High		$VDDI - 0.4$	–	–	V	*
VOL	DC output logic Low		–	–	0.4	V	*
LVTTTL 3.3 V DC Output Voltage Specification							
VOH	DC output logic High		2.4	–	–	V	–
VOL	DC output logic Low		–	–	0.4	V	–
<i>Note: * The VOH/VOL test points selected ensure compliance with LVCMOS 3.3 V JESD8-B requirements.</i>							

Table 25 • LVTTTL/LVCMOS 3.3 V AC Specifications (Applicable to MSIO I/O Bank Only)

Symbol	Parameters	Conditions	Min	Typ	Max	Units
LVTTTL/LVCMOS 3.3 V Maximum Switching Speed						
Dmax	Maximum data rate (for MSIO I/O Bank)	AC loading: 17 pF load, maximum drive/slew	–	–	600	Mbps
LVTTTL/LVCMOS 3.3 V AC Test Parameters Specifications						
Vtrip	Measuring/trip point for data path		–	1.4	–	V
Rent	Resistance for enable path (t_{ZH} , t_{ZL} , t_{HZ} , t_{LZ})		–	2K	–	Ω
Cent	Capacitive loading for enable path (t_{ZH} , t_{ZL} , t_{HZ} , t_{LZ})		–	5	–	pF
Cload	Capacitive loading for data path (t_{DP})		–	5	–	pF

Table 26 • LVTTTL/LVCMOS 3.3 V Transmitter Drive Strength Specifications

Output Drive Selection	VOH (V)	VOL (V)	IOH (at VOH) mA	IOL (at VOL) mA
MSIO I/O Bank				
2 mA	VDDI – 0.4	0.4	2	2
4 mA	VDDI – 0.4	0.4	4	4
8 mA	VDDI – 0.4	0.4	8	8
12 mA	VDDI – 0.4	0.4	12	12
16 mA	VDDI – 0.4	0.4	16	16
20 mA	VDDI – 0.4	0.4	20	20

Note: For a detailed I/V curve, use the corresponding IBIS models: www.microsemi.com/soc/download/ibis/default.aspx.

8.6.2.2 AC Switching Characteristics

Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, VDD = 1.14 V, VDDI = 3.0 V

AC Switching Characteristics for Receiver (Input Buffers)

Table 27 • LVTTTL/LVCMOS 3.3 V Receiver Characteristics

Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, VDD = 1.14 V, Worst-Case VDDI

	On-Die Termination (ODT)	t_{PY}		t_{PYS}		Units
		Speed Grade				
		–1	Std	–1	Std	
LVTTTL/LVCMOS 3.3 V (for MSIO I/O Bank)	None	2.262	2.663	2.289	2.695	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)
Table 28 • LVTTL/LVCMOS 3.3 V Transmitter Characteristics

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

Output Drive Selection	Slew Control	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}^*		t_{LZ}^*		Units
		Speed Grade										
		-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
LVTTL/LVCMOS 3.3 V (for MSIO I/O Bank)												
2 mA	Slow	3.192	3.755	3.47	4.083	2.969	3.494	1.856	2.183	3.337	3.926	ns
4 mA	Slow	2.331	2.742	2.673	3.145	2.526	2.973	3.034	3.569	4.451	5.236	ns
8 mA	Slow	2.135	2.511	2.33	2.741	2.297	2.703	4.532	5.331	4.825	5.676	ns
12 mA	Slow	2.052	2.414	2.107	2.479	2.162	2.544	5.75	6.764	5.445	6.406	ns
16 mA	Slow	2.062	2.425	2.072	2.438	2.145	2.525	5.993	7.05	5.625	6.618	ns
20 mA	Slow	2.148	2.527	1.999	2.353	2.088	2.458	6.262	7.367	5.876	6.913	ns

Note: *Delay increases with drive strength are inherent to built-in slew control circuitry for simultaneous switching output (SSO) management.

8.6.3 2.5 V LVCMOS

LVCMOS 2.5 V is a general standard for 2.5 V applications and is supported in IGLOO2 FPGA and SmartFusion2 SoC FPGAs in compliance to the JEDEC specification JESD8-5A.

8.6.3.1 Minimum and Maximum DC/AC Input and Output Levels Specification

Table 29 • LVCMOS 2.5 V DC Voltage Specification

Symbol	Parameters	Conditions	Min	Typ	Max	Units	Notes
LVCMOS 2.5 V DC Recommended DC Operating Conditions							
VDDI	Supply voltage		2.375	2.5	2.625	V	–
LVCMOS 2.5 V DC Input Voltage Specification							
V_{IH} (DC)	DC input logic High (for MSIOD and DDRIO I/O Banks)		1.7	–	2.625	V	–
V_{IH} (DC)	DC input logic High (for MSIO I/O Bank)		1.7	–	3.45	V	–
V_{IL} (DC)	DC input logic Low		-0.3	–	0.7	V	–
I_{IH} (DC)	Input current High		–	–	Table 19 on page 28		–
I_{IL} (DC)	Input current Low		–	–	Table 19 on page 28		–
LVCMOS 2.5 V DC Output Voltage Specification							
V_{OH}	DC output logic High		$V_{DDI} - 0.4$	–	–	V	*
V_{OL}	DC output logic Low		–	–	0.4	V	*

Note: *The V_{OH}/V_{OL} test points selected ensure compliance with LVCMOS 2.5 V JEDEC8-5A requirements.

Table 30 • LVC MOS 2.5 V AC Specifications

Symbol	Parameters	Conditions	Min	Typ	Max	Units
LVC MOS 2.5 V AC Minimum and Maximum Switching Speed						
Dmax	Maximum data rate (for DDRIO I/O Bank)	AC loading: 17 pF load, maximum drive/slew	–	–	400	Mbps
Dmax	Maximum data rate (for MSIO I/O Bank)	AC loading: 17 pF load, maximum drive/slew	–	–	410	Mbps
Dmax	Maximum data rate (for MSIOD I/O Bank)	AC loading: 17 pF load, maximum drive/slew	–	–	420	Mbps
LVC MOS 2.5 V AC Calibrated Impedance Option						
Rodt_cal	Supported output driver calibrated impedance (for DDRIO I/O Bank)		–	75, 60, 50, 33, 25, 20	–	Ω
LVC MOS 2.5 V AC Test Parameters Specifications						
Vtrip	Measuring/trip point for data path		–	1.2	–	V
Rent	Resistance for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	2K	–	Ω
Cent	Capacitive loading for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	5	–	pF
Cload	Capacitive loading for data path (t _{DP})		–	5	–	pF

Table 31 • LVC MOS 2.5 V Transmitter Drive Strength Specifications

Output Drive Selection			VOH (V)	VOL (V)	IOH (at VOH) mA	IOL (at VOL) mA
MSIO I/O Bank	MSIOD I/O Bank	DDRIO I/O Bank (With Software Default Fixed Code)	Min	Max		
2 mA	2 mA	2 mA	VDDI – 0.4	0.4	2	2
4 mA	4 mA	4 mA	VDDI – 0.4	0.4	4	4
6 mA	6 mA	6 mA	VDDI – 0.4	0.4	6	6
8 mA	8 mA	8 mA	VDDI – 0.4	0.4	8	8
12 mA	12 mA	12 mA	VDDI – 0.4	0.4	12	12
16 mA	N/A	16 mA	VDDI – 0.4	0.4	16	16

Note: For board design considerations, output slew rates extraction, detailed output buffer resistances and I/V Curve use the corresponding IBIS models located at: www.microsemi.com/soc/download/ibis/default.aspx.

8.6.3.2. AC Switching Characteristics

Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, $V_{DDI} = 2.375\text{ V}$

AC Switching Characteristics for Receiver (Input Buffers)

Table 32 • LVC MOS 2.5 V Receiver Characteristics

Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case V_{DDI}

	On-Die Termination (ODT)	t_{PY}		t_{PYS}		Units
		Speed Grade				
		-1	Std	-1	Std	
LVC MOS 2.5 V (for DDRIO I/O Bank)	None	1.823	2.145	1.932	2.274	ns
LVC MOS 2.5 V (for MSIO I/O Bank)	None	2.486	2.925	2.495	2.935	ns
LVC MOS 2.5 V (for MSIOD I/O Bank)	None	2.29	2.694	2.305	2.712	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Table 33 • LVC MOS 2.5 V Transmitter Characteristics

Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case V_{DDI}

Output Drive Selection	Slew Control	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}^*		t_{LZ}^*		Units
		Speed Grade										
		-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
LVC MOS 2.5 V (for DDRIO I/O Bank)												
2 mA	Slow	3.657	4.302	3.393	3.991	3.675	4.323	3.894	4.582	3.552	4.18	ns
	Medium	3.374	3.97	3.139	3.693	3.396	3.995	3.635	4.277	3.253	3.828	ns
	Medium fast	3.239	3.811	3.036	3.572	3.261	3.836	3.519	4.141	3.128	3.681	ns
	Fast	3.224	3.793	3.029	3.563	3.246	3.818	3.512	4.132	3.119	3.67	ns
4 mA	Slow	3.095	3.641	2.705	3.182	3.088	3.633	4.738	5.575	4.348	5.116	ns
	Medium	2.825	3.324	2.488	2.927	2.823	3.321	4.492	5.285	4.063	4.781	ns
	Medium fast	2.701	3.178	2.384	2.804	2.698	3.173	4.364	5.135	3.945	4.642	ns
	Fast	2.69	3.165	2.377	2.796	2.687	3.161	4.359	5.129	3.94	4.636	ns
6 mA	Slow	2.919	3.434	2.491	2.93	2.902	3.414	5.085	5.983	4.674	5.5	ns
	Medium	2.65	3.118	2.279	2.681	2.642	3.108	4.845	5.701	4.375	5.148	ns
	Medium fast	2.529	2.975	2.176	2.56	2.521	2.965	4.724	5.558	4.259	5.011	ns
	Fast	2.516	2.96	2.168	2.551	2.508	2.95	4.717	5.55	4.251	5.002	ns
8 mA	Slow	2.863	3.368	2.427	2.855	2.844	3.346	5.196	6.114	4.769	5.612	ns
	Medium	2.599	3.058	2.217	2.608	2.59	3.047	4.952	5.827	4.471	5.261	ns
	Medium fast	2.483	2.921	2.114	2.487	2.473	2.91	4.832	5.685	4.364	5.134	ns
	Fast	2.467	2.902	2.106	2.478	2.457	2.89	4.826	5.678	4.348	5.116	ns
12 mA	Slow	2.747	3.232	2.296	2.701	2.724	3.204	5.39	6.342	4.938	5.81	ns
	Medium	2.493	2.934	2.102	2.473	2.483	2.921	5.166	6.078	4.65	5.471	ns
	Medium fast	2.382	2.803	2.006	2.36	2.371	2.789	5.067	5.962	4.546	5.349	ns
	Fast	2.369	2.787	1.999	2.352	2.357	2.773	5.063	5.958	4.538	5.339	ns

Table 33 • LVCMOS 2.5 V Transmitter Characteristics (continued)
 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

Output Drive Selection	Slew Control	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}^*		t_{LZ}^*		Units
		Speed Grade										
		-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
16 mA	Slow	2.677	3.149	2.213	2.604	2.649	3.116	5.575	6.56	5.08	5.977	ns
	Medium	2.432	2.862	2.028	2.386	2.421	2.848	5.372	6.32	4.801	5.649	ns
	Medium fast	2.324	2.734	1.937	2.278	2.311	2.718	5.297	6.233	4.7	5.531	ns
	Fast	2.313	2.721	1.929	2.269	2.3	2.706	5.296	6.231	4.699	5.529	ns
LVCMOS 2.5 V (for MSIO I/O Bank)												
2 mA	Slow	3.48	4.095	3.855	4.534	3.785	4.453	2.12	2.494	3.45	4.059	ns
4 mA	Slow	2.583	3.039	3.042	3.579	3.138	3.691	4.143	4.874	4.687	5.513	ns
6 mA	Slow	2.392	2.815	2.669	3.139	2.82	3.317	4.909	5.775	5.083	5.98	ns
8 mA	Slow	2.309	2.717	2.565	3.017	2.74	3.223	5.812	6.837	5.523	6.497	ns
12 mA	Slow	2.333	2.745	2.437	2.867	2.626	3.089	6.131	7.213	5.712	6.72	ns
16 mA	Slow	2.412	2.838	2.335	2.747	2.533	2.979	6.54	7.694	6.007	7.067	ns
LVCMOS 2.5 V (for MSIOD I/O Bank)												
2 mA	Slow	2.206	2.596	2.678	3.15	2.64	3.106	4.935	5.805	4.74	5.576	ns
4 mA	Slow	1.835	2.159	2.242	2.637	2.256	2.654	5.413	6.368	5.15	6.059	ns
6 mA	Slow	1.709	2.01	2.132	2.508	2.167	2.549	5.813	6.838	5.499	6.469	ns
8 mA	Slow	1.63	1.918	1.958	2.303	2.012	2.367	6.226	7.324	5.816	6.842	ns
12 mA	Slow	1.648	1.939	1.86	2.187	1.921	2.259	6.519	7.669	6.027	7.09	ns
<i>Note: *Delay increases with drive strength are inherent to built-in slew control circuitry for simultaneous switching output (SSO) management.</i>												

8.6.4 1.8 V LVCMOS

LVCMOS 1.8 is a general standard for 1.8 V applications and is supported in IGLOO2 FPGAs and SmartFusion2 SoC FPGAs in compliance to the JEDEC specification JESD8-7A.

8.6.4.1 Minimum and Maximum DC/AC Input and Output Levels Specification

Table 34 • LVCMOS 1.8 V DC Voltage Specification

Symbols	Parameters	Conditions	Min	Typ	Max	Units
LVCMOS 1.8 V DC Recommended Operating Conditions						
VDDI	Supply voltage		1.710	1.8	1.89	V
LVCMOS 1.8 V DC Input Voltage Specification						
VIH (DC)	DC input logic High (for MSIOD and DDRIO I/O Banks)		$0.65 \times V_{DDI}$	–	1.89	V
VIH (DC)	DC input logic High (for MSIO I/O Bank)		$0.65 \times V_{DDI}$	–	3.45	V
VIL (DC)	DC input logic Low		–0.3	–	$0.35 \times V_{DDI}$	V
IIH (DC)	Input current High		–	–	Table 19 on page 28	–
IIL (DC)	Input current Low		–	–	Table 19 on page 28	–

Table 34 • LVCMOS 1.8 V DC Voltage Specification (continued)

LVCMOS 1.8 V DC Output Voltage Specification						
VOH	DC output logic High	VDDI – 0.45	–	–	V	
VOL	DC output logic Low	–	–	0.45	V	

Table 35 • LVCMOS 1.8 V AC Specifications

Symbols	Parameters	Conditions	Min	Typ	Max	Units	Notes
LVCMOS 1.8 V Minimum and Maximum AC Switching Speed							
Dmax	Maximum data rate (for DDRIO I/O Bank)	AC loading: 17 pF load, maximum drive/slew	–	–	400	Mbps	*
Dmax	Maximum data rate (for MSIO I/O Bank)	AC loading: 17 pF load, maximum drive/slew	–	–	295	Mbps	–
Dmax	Maximum data rate (for MSIOD I/O Bank)	AC loading: 17 pF load, maximum drive/slew	–	–	400	Mbps	*
LVCMOS 1.8 V AC Calibrated Impedance Option							
Rodt_cal	Supported output driver calibrated impedance (for DDRIO I/O Bank)		–	75, 60, 50, 33, 25, 20	–	Ω	–
LVCMOS 1.8 V AC Test Parameters Specifications							
Vtrip	Measuring/trip point for data path		–	0.9	–	V	–
Rent	Resistance for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	2k	–	Ω	–
Cent	Capacitive loading for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	5	–	pF	–
Cload	Capacitive loading for data path (t _{DP})		–	5	–	pF	–
<i>Note: *Maximum Data Rate applies for Drive Strength 8mA and above, All Slews</i>							

Table 36 • LVCMOS 1.8 V Transmitter Drive Strength Specifications

Output Drive Selection			VOH (V)	VOL (V)	IOH (at VOH) mA	IOL (at VOL) mA	Notes
MSIO I/O Bank	MSIOD I/O Bank	DDRIO I/O Bank	Min	Max			
2 mA	2 mA	2 mA	VDDI – 0.45	0.45	2	2	–
4 mA	4 mA	4 mA	VDDI – 0.45	0.45	4	4	–
6 mA	6 mA	6 mA	VDDI – 0.45	0.45	6	6	–
8 mA	8 mA	8 mA	VDDI – 0.45	0.45	8	8	–
10 mA	10 mA	10 mA	VDDI – 0.45	0.45	10	10	–
12 mA	N/A	12 mA	VDDI – 0.45	0.45	12	12	–
N/A	N/A	16 mA	VDDI – 0.45	0.45	16	16	*
<i>Note: *16mA Drive Strengths, All Slews, meets LPDDR JEDEC Electrical Compliance</i>							

8.6.4.2. AC Switching Characteristics

Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, $V_{DDI} = 1.71\text{ V}$

AC Switching Characteristics for Receiver (Input Buffers)

Table 37 • LVC MOS 1.8 V Receiver Characteristics

Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	On-Die Termination (ODT)	t_{PY}		t_{PYS}		Units
		Speed Grade				
		-1	Std	-1	Std	
LVC MOS 1.8 V (for DDRIO I/O Bank with FIXED CODES)	None	1.968	2.315	2.099	2.47	ns
LVC MOS 1.8 V (for MSIO I/O Bank)	None	2.898	3.411	2.883	3.393	ns
	50	3.05	3.59	3.044	3.583	ns
	75	2.999	3.53	2.987	3.516	ns
	150	2.947	3.469	2.933	3.452	ns
LVC MOS 1.8 V (for MSIOD I/O Bank)	None	2.611	3.071	2.598	3.057	ns
	50	2.775	3.264	2.775	3.265	ns
	75	2.72	3.2	2.712	3.19	ns
	150	2.666	3.137	2.655	3.123	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Table 38 • LVC MOS 1.8 V Transmitter Characteristics

Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

Output Drive Selection	Slew Control	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}^*		t_{LZ}^*		Units
		Speed Grade										
		-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
LVC MOS 1.8 V (for DDRIO I/O Bank with Fixed Code)												
2 mA	Slow	4.234	4.981	3.646	4.29	4.245	4.995	4.908	5.774	4.434	5.216	ns
	Medium	3.824	4.498	3.282	3.861	3.834	4.511	4.625	5.441	4.116	4.843	ns
	Medium fast	3.627	4.267	3.111	3.66	3.637	4.279	4.481	5.272	3.984	4.687	ns
	Fast	3.605	4.241	3.097	3.644	3.615	4.253	4.472	5.262	3.973	4.674	ns
4 mA	Slow	3.923	4.615	3.314	3.9	3.918	4.61	5.403	6.356	4.894	5.757	ns
	Medium	3.518	4.138	2.961	3.484	3.515	4.135	5.121	6.025	4.561	5.366	ns
	Medium fast	3.321	3.907	2.783	3.275	3.317	3.903	4.966	5.843	4.426	5.206	ns
	Fast	3.301	3.883	2.77	3.259	3.296	3.878	4.957	5.831	4.417	5.196	ns
6 mA	Slow	3.71	4.364	3.104	3.652	3.702	4.355	5.62	6.612	5.08	5.977	ns
	Medium	3.333	3.921	2.779	3.27	3.325	3.913	5.346	6.289	4.777	5.62	ns
	Medium fast	3.155	3.712	2.62	3.083	3.146	3.702	5.21	6.13	4.657	5.479	ns
	Fast	3.134	3.688	2.608	3.068	3.125	3.677	5.202	6.12	4.648	5.468	ns

Table 38 • LVCMOS 1.8 V Transmitter Characteristics (continued)
 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

Output Drive Selection	Slew Control	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}^*		t_{LZ}^*		Units
		Speed Grade										
		-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
8 mA	Slow	3.619	4.258	3.007	3.538	3.607	4.244	5.815	6.841	5.249	6.175	ns
	Medium	3.246	3.819	2.686	3.16	3.236	3.807	5.542	6.52	4.936	5.807	ns
	Medium fast	3.066	3.607	2.525	2.971	3.054	3.593	5.405	6.359	4.811	5.66	ns
	Fast	3.046	3.584	2.513	2.957	3.034	3.57	5.401	6.353	4.803	5.651	ns
10 mA	Slow	3.498	4.115	2.878	3.386	3.481	4.096	6.046	7.113	5.444	6.404	ns
	Medium	3.138	3.692	2.569	3.023	3.126	3.678	5.782	6.803	5.129	6.034	ns
	Medium fast	2.966	3.489	2.414	2.841	2.951	3.472	5.666	6.665	5.013	5.897	ns
	Fast	2.945	3.464	2.401	2.826	2.93	3.448	5.659	6.658	5.003	5.886	ns
12 mA	Slow	3.417	4.02	2.807	3.303	3.401	4.002	6.083	7.156	5.464	6.428	ns
	Medium	3.076	3.618	2.519	2.964	3.063	3.604	5.828	6.856	5.176	6.089	ns
	Medium fast	2.913	3.427	2.376	2.795	2.898	3.41	5.725	6.736	5.072	5.966	ns
	Fast	2.894	3.405	2.362	2.78	2.879	3.388	5.715	6.724	5.064	5.957	ns
16 mA	Slow	3.366	3.96	2.751	3.237	3.348	3.939	6.226	7.324	5.576	6.56	ns
	Medium	3.03	3.565	2.47	2.906	3.017	3.55	5.981	7.036	5.282	6.214	ns
	Medium fast	2.87	3.377	2.328	2.739	2.854	3.358	5.895	6.935	5.18	6.094	ns
	Fast	2.853	3.357	2.314	2.723	2.837	3.338	5.889	6.929	5.177	6.09	ns
LVCMOS 1.8 V (for MSIO I/O Bank)												
2 mA	Slow	3.441	4.047	4.165	4.9	4.413	5.192	4.891	5.755	5.138	6.044	ns
4 mA	Slow	3.218	3.786	3.642	4.284	3.941	4.636	5.665	6.665	5.568	6.551	ns
6 mA	Slow	3.141	3.694	3.501	4.118	3.823	4.498	6.587	7.75	6.032	7.096	ns
8 mA	Slow	3.165	3.723	3.319	3.904	3.654	4.298	6.898	8.115	6.216	7.313	ns
10 mA	Slow	3.202	3.767	3.278	3.857	3.616	4.254	7.25	8.529	6.435	7.571	ns
12 mA	Slow	3.277	3.855	3.175	3.736	3.519	4.139	7.392	8.697	6.538	7.692	ns
LVCMOS 1.8 V (for MSIOD I/O Bank)												
2 mA	Slow	2.725	3.206	3.316	3.901	3.484	4.099	5.204	6.123	4.997	5.88	ns
4 mA	Slow	2.242	2.638	2.777	3.267	2.947	3.466	5.729	6.74	5.448	6.41	ns
6 mA	Slow	1.995	2.347	2.466	2.901	2.63	3.094	6.372	7.496	5.987	7.043	ns
8 mA	Slow	2.001	2.354	2.44	2.87	2.6	3.058	6.633	7.804	6.193	7.286	ns
10 mA	Slow	2.025	2.382	2.312	2.719	2.47	2.906	6.94	8.165	6.412	7.544	ns
<i>Note: *Delay increases with drive strength are inherent to built-in slew control circuitry for simultaneous switching output (SSO) management.</i>												

8.6.5 1.5 V LVCMOS

LVCMOS 1.5 is a general standard for 1.5 V applications and is supported in IGLOO2 FPGAs and SmartFusion2 SoC FPGAs in compliance to the JEDEC specification JESD8-11A.

8.6.5.1 Minimum and Maximum DC/AC Input and Output Levels Specification

Table 39 • LVCMOS 1.5 V DC Voltage Specification

Symbols	Parameters	Conditions	Min	Typ	Max	Units
LVCMOS 1.5 V DC Recommended Operating Conditions						
VDDI	Supply voltage		1.425	1.5	1.575	V
LVCMOS 1.5 V DC Input Voltage Specification						
VIH (DC)	DC input logic High for (MSIOD and DDRIO I/O Banks)		$0.65 \times VDDI$	–	1.575	V
VIH (DC)	DC input logic High (for MSIO I/O Bank)		$0.65 \times VDDI$	–	3.45	V
VIL (DC)	DC input logic Low		–0.3	–	$0.35 \times VDDI$	V
IIH (DC)	Input current High		–	–	Table 19 on page 28	–
IIL (DC)	Input current Low		–	–	Table 19 on page 28	–
LVCMOS 1.5 V DC Output Voltage Specification						
VOH	DC output logic High		$VDDI \times 0.75$	–	–	V
VOL	DC output logic Low		–	–	$VDDI \times 0.25$	V

Table 40 • LVCMOS 1.5 V AC Specifications

Symbols	Parameters	Conditions	Min	Typ	Max	Units
LVCMOS 1.5 V AC Minimum and Maximum Switching Speed						
Dmax	Maximum data rate (for DDRIO I/O Bank)	AC loading: 17 pF load, maximum drive/slew	–	–	235	Mbps
Dmax	Maximum data rate (for MSIO I/O Bank)	AC loading: 17 pF load, maximum drive/slew	–	–	160	Mbps
Dmax	Maximum data rate (for MSIOD I/O Bank)	AC loading: 17 pF load, maximum drive/slew	–	–	220	Mbps
LVCMOS 1.5 V AC Calibrated Impedance Option						
Rodt_cal	Supported output driver calibrated impedance (for DDRIO I/O Bank)		–	75, 60, 50, 40	–	Ω
LVCMOS 1.5 V AC Test Parameters Specifications						
Vtrip	Measuring/trip point		–	0.75	–	V
Rent	Resistance for enable path (t_{ZH} , t_{ZL} , t_{HZ} , t_{LZ})		–	2K	–	Ω
Cent	Capacitive loading for enable path (t_{ZH} , t_{ZL} , t_{HZ} , t_{LZ})		–	5	–	pF
Cload	Capacitive loading for data path (t_{DP})		–	5	–	pF

Table 41 • LVC MOS 1.5 V Transmitter Drive Strength Specifications

Output Drive Selection			VOH (V)	VOL (V)	IOH (at VOH) mA	IOL (at VOL) mA
MSIO I/O Bank	MSIOD I/O Bank	DDRIO I/O Bank	Min	Max		
2 mA	2 mA	2 mA	VDDI × 0.75	VDDI × 0.25	2	2
4 mA	4 mA	4 mA	VDDI × 0.75	VDDI × 0.25	4	4
6 mA	6 mA	6 mA	VDDI × 0.75	VDDI × 0.25	6	6
8 mA	N/A	8 mA	VDDI × 0.75	VDDI × 0.25	8	8
N/A	N/A	10 mA	VDDI × 0.75	VDDI × 0.25	10	10
N/A	N/A	12 mA	VDDI × 0.75	VDDI × 0.25	12	12

Note: For a detailed I/V curve, use the corresponding IBIS models: www.microsemi.com/soc/download/ibis/default.aspx.

8.6.5.2 AC Switching Characteristics

Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, VDD = 1.14 V, VDDI = 1.425 V

AC Switching Characteristics for Receiver (Input Buffers)

Table 42 • LVC MOS 1.5 V Receiver Characteristics

Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, VDD = 1.14 V, Worst-Case VDDI

	On-Die Termination (ODT)	t_{PY}		t_{PYS}		Units
		Speed Grade				
		-1	Std	-1	Std	
LVC MOS 1.5 V (for DDRIO I/O Bank with FIXED CODES)	None	2.051	2.413	2.086	2.455	ns
LVC MOS 1.5 V (for MSIO I/O Bank)	None	3.311	3.896	3.285	3.865	ns
	50	3.654	4.299	3.623	4.263	ns
	75	3.533	4.156	3.501	4.119	ns
	150	3.415	4.018	3.388	3.986	ns
LVC MOS 1.5 V (for MSIOD I/O Bank)	None	2.959	3.481	2.93	3.447	ns
	50	3.298	3.88	3.268	3.845	ns
	75	3.162	3.719	3.128	3.68	ns
	150	3.053	3.592	3.021	3.554	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Table 43 • LVCMOS 1.5 V Transmitter Characteristics

Worst-Case Commercial Conditions: T_J = 85°C, VDD = 1.14 V, Worst-Case VDDI

Output Drive Selection	Slew Control	t _{DP}		t _{ZL}		t _{ZH}		t _{HZ} *		t _{LZ} *		Units
		Speed Grade										
		-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
LVCMOS 1.5 V (for DDRIO I/O Bank)												
2 mA	Slow	5.122	6.026	4.31	5.07	5.145	6.052	5.258	6.186	4.672	5.496	ns
	Medium	4.58	5.389	3.86	4.54	4.6	5.411	4.977	5.855	4.357	5.126	ns
	Medium fast	4.323	5.086	3.629	4.269	4.341	5.107	4.804	5.652	4.228	4.974	ns
	Fast	4.296	5.054	3.609	4.245	4.314	5.075	4.791	5.636	4.219	4.963	ns
4 mA	Slow	4.449	5.235	3.707	4.361	4.443	5.227	6.058	7.127	5.458	6.421	ns
	Medium	3.961	4.66	3.264	3.839	3.954	4.651	5.778	6.797	5.116	6.018	ns
	Medium fast	3.729	4.387	3.043	3.579	3.72	4.376	5.63	6.624	4.981	5.86	ns
	Fast	3.704	4.358	3.027	3.56	3.695	4.347	5.624	6.617	4.973	5.851	ns
6 mA	Slow	4.244	4.993	3.465	4.076	4.233	4.979	6.39	7.518	5.736	6.748	ns
	Medium	3.774	4.44	3.05	3.587	3.762	4.426	6.114	7.193	5.397	6.35	ns
	Medium fast	3.544	4.17	2.839	3.339	3.529	4.152	5.978	7.033	5.27	6.2	ns
	Fast	3.519	4.14	2.82	3.317	3.504	4.122	5.965	7.017	5.259	6.187	ns
8 mA	Slow	4.099	4.823	3.311	3.894	4.087	4.807	6.584	7.746	5.854	6.888	ns
	Medium	3.656	4.301	2.927	3.443	3.642	4.284	6.311	7.425	5.553	6.533	ns
	Medium fast	3.437	4.044	2.731	3.213	3.42	4.023	6.182	7.273	5.435	6.394	ns
	Fast	3.41	4.012	2.715	3.193	3.393	3.991	6.178	7.269	5.425	6.383	ns
10 mA	Slow	4.029	4.74	3.238	3.809	4.015	4.723	6.732	7.921	5.965	7.018	ns
	Medium	3.601	4.237	2.867	3.372	3.586	4.218	6.473	7.615	5.669	6.669	ns
	Medium fast	3.384	3.981	2.672	3.143	3.365	3.958	6.351	7.471	5.55	6.529	ns
	Fast	3.357	3.949	2.655	3.123	3.338	3.927	6.345	7.464	5.54	6.518	ns
12 mA	Slow	3.974	4.675	3.196	3.759	3.958	4.656	6.842	8.049	6.068	7.139	ns
	Medium	3.55	4.176	2.827	3.326	3.534	4.157	6.584	7.746	5.751	6.766	ns
	Medium fast	3.345	3.935	2.638	3.103	3.325	3.911	6.488	7.633	5.641	6.637	ns
	Fast	3.316	3.902	2.621	3.083	3.297	3.878	6.486	7.63	5.626	6.619	ns
LVCMOS 1.5 V (for MSIO I/O Bank)												
2 mA	Slow	4.423	5.203	5.397	6.35	5.686	6.69	5.609	6.599	5.561	6.542	ns
4 mA	Slow	4.05	4.765	4.503	5.298	4.92	5.788	7.358	8.657	6.525	7.677	ns
6 mA	Slow	4.081	4.801	4.259	5.012	4.699	5.528	7.659	9.011	6.709	7.893	ns
8 mA	Slow	4.234	4.98	4.068	4.786	4.521	5.319	8.218	9.668	7.05	8.294	ns

Table 43 • LVC MOS 1.5 V Transmitter Characteristics (continued)
 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

Output Drive Selection	Slew Control	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}^*		t_{LZ}^*		Units
		Speed Grade										
		-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
LVC MOS 1.5 V (for MSIOD I/O Bank)												
2 mA	Slow	2.735	3.218	3.371	3.966	3.618	4.257	6.03	7.095	5.705	6.712	ns
4 mA	Slow	2.426	2.854	2.992	3.521	3.221	3.79	6.738	7.927	6.298	7.41	ns
6 mA	Slow	2.433	2.862	2.81	3.306	3.031	3.566	7.123	8.38	6.596	7.76	ns

*Note: *Delay increases with drive strength are inherent to built-in slew control circuitry for simultaneous switching output (SSO) management.*

8.6.6 1.2 V LVC MOS

LVC MOS 1.2 is a general standard for 1.2 V applications and is supported in IGLOO2 FPGAs and SmartFusion2 SoC FPGAs in compliance to the JEDEC specification JESD8-12A.

8.6.6.1 Minimum and Maximum DC/AC Input and Output Levels Specification

Table 44 • LVC MOS 1.2 V DC Voltage Specification

Symbols	Parameters	Conditions	Min	Typ	Max	Units	Notes
LVC MOS 1.2 V DC Recommended DC Operating Conditions							
VDDI	Supply voltage		1.140	1.2	1.26	V	–
LVC MOS 1.2 V DC Input Voltage Specification							
VIH (DC)	DC input logic High (for MSIOD and DDRIO I/O Banks)		$0.65 \times V_{DDI}$	–	1.26	V	–
VIH (DC)	DC input logic High (for MSIO I/O Bank)		$0.65 \times V_{DDI}$	–	3.45	V	–
VIL (DC)	DC input logic Low		–0.3	–	$0.35 \times V_{DDI}$	V	–
IIH (DC)	Input current High		–	–	Table 19 on page 28	–	–
IIL (DC)	Input current Low		–	–	Table 19 on page 28	–	–
LVC MOS 1.2 V DC Output Voltage Specification							
VOH	DC output logic High		$V_{DDI} \times 0.75$	–	–	V	–
VOL	DC output logic Low		–	–	$V_{DDI} \times 0.25$	V	–

Table 45 • LVC MOS 1.2 V AC Specifications

Symbols	Parameters	Conditions	Min	Typ	Max	Units
LVC MOS 1.2 V Minimum and Maximum AC Switching Speed						
Dmax	Maximum data rate (for DDRIO I/O Bank)	AC loading: 17 pF load, maximum drive/slew	–	–	200	Mbps
Dmax	Maximum data rate (for MSIO I/O Bank)	AC loading: 17 pF load, maximum drive/slew	–	–	120	Mbps
Dmax	Maximum data rate (for MSIOD I/O Bank)	AC loading: 17 pF load, maximum drive/slew	–	–	160	Mbps

Table 45 • LVC MOS 1.2 V AC Specifications (continued)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
LVC MOS 1.2 V AC Calibrated Impedance Option						
Rodt_cal	Supported output driver calibrated impedance (for DDRIO I/O Bank)		–	75, 60, 50, 40	–	Ω
LVC MOS 1.2 V AC Test Parameters Specifications						
Vtrip	Measuring/trip point		–	0.6	–	V
Rent	Resistance for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	2K	–	Ω
Cent	Capacitive loading for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	5	–	pF
Cload	Capacitive loading for data path (t _{DP})		–	5	–	pF

Table 46 • LVC MOS 1.2 V Transmitter Drive Strength Specifications

Output Drive Selection			VOH (V)	VOL (V)	IOH (at VOH) mA	IOL (at VOL) mA
MSIO I/O Bank	MSIOD I/O Bank	DDRIO I/O Bank	Min	Max		
2 mA	2 mA	2 mA	VDDI × 0.75	VDDI × 0.25	2	2
4 mA	4 mA	4 mA	VDDI × 0.75	VDDI × 0.25	4	4
N/A	N/A	6 mA	VDDI × 0.75	VDDI × 0.25	6	6

Note: For a detailed I/V curve, use the corresponding IBIS models: www.microsemi.com/soc/download/ibis/default.aspx.

8.6.6.2 AC Switching Characteristics

Worst Commercial-Case Conditions: T_J = 85°C, VDD = 1.14 V, VDDI = 1.14 V

AC Switching Characteristics for Receiver (Input Buffers)

Table 47 • LVC MOS 1.2 V Receiver Characteristics

Worst-Case Commercial Conditions: T_J = 85°C, VDD = 1.14 V, Worst-Case VDDI

	On-Die Termination (ODT)	t _{py}		t _{pys}		Units
		Speed Grade				
		–1	Std	–1	Std	
LVC MOS 1.2 V (for DDRIO I/O Bank with Fixed Code)	None	2.448	2.88	2.466	2.901	ns
LVC MOS 1.2 V (for MSIO I/O Bank)	None	4.714	5.545	4.675	5.5	ns
	50	6.668	7.845	6.579	7.74	ns
	75	5.832	6.862	5.76	6.777	ns
	150	5.162	6.073	5.111	6.014	ns
LVC MOS 1.2 V (for MSIOD I/O Bank)	None	4.154	4.887	4.114	4.84	ns
	50	6.918	8.139	6.806	8.008	ns
	75	5.613	6.603	5.533	6.509	ns
	150	4.716	5.549	4.657	5.479	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)
Table 48 • LVCMOS 1.2 V Transmitter Characteristics

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

Output Drive Selection	Slew Control	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}^*		t_{LZ}^*		Units
		Speed Grade										
		-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
LVCMOS 1.2 V (for DDRIO I/O Bank)												
2 mA	Slow	6.713	7.897	5.362	6.308	6.723	7.909	7.233	8.51	6.375	7.499	ns
	Medium	5.912	6.955	4.616	5.43	5.915	6.959	6.887	8.102	6.009	7.069	ns
	Medium fast	5.5	6.469	4.231	4.978	5.5	6.471	6.672	7.849	5.835	6.865	ns
	Fast	5.462	6.426	4.194	4.935	5.463	6.427	6.646	7.819	5.828	6.857	ns
4 mA	Slow	6.109	7.186	4.708	5.539	6.098	7.174	8.005	9.418	7.033	8.274	ns
	Medium	5.355	6.299	4.034	4.746	5.338	6.28	7.637	8.985	6.672	7.849	ns
	Medium fast	4.953	5.826	3.685	4.336	4.932	5.802	7.44	8.752	6.499	7.646	ns
	Fast	4.911	5.777	3.658	4.303	4.89	5.754	7.427	8.737	6.488	7.632	ns
6 mA	Slow	5.89	6.929	4.506	5.301	5.874	6.911	8.337	9.808	7.315	8.605	ns
	Medium	5.176	6.089	3.862	4.543	5.155	6.065	7.986	9.394	6.943	8.168	ns
	Medium fast	4.792	5.637	3.523	4.145	4.765	5.606	7.808	9.186	6.775	7.97	ns
	Fast	4.754	5.593	3.486	4.101	4.728	5.563	7.777	9.149	6.769	7.963	ns
LVCMOS 1.2 V (for MSIO I/O Bank)												
2 mA	Slow	6.746	7.937	7.458	8.774	8.172	9.614	9.867	11.608	8.393	9.874	ns
4 mA	Slow	7.068	8.315	6.678	7.857	7.474	8.793	10.986	12.924	9.043	10.638	ns
LVCMOS 1.2 V (for MSIOD I/O Bank)												
2 mA	Slow	3.883	4.568	4.868	5.726	5.329	6.269	7.994	9.404	7.527	8.855	ns
4 mA	Slow	3.774	4.44	4.188	4.926	4.613	5.426	8.972	10.555	8.315	9.782	ns
<i>Note:</i> *Delay increases with drive strength are inherent to built-in slew control circuitry for simultaneous switching output (SSO) management.												

8.6.7 3.3 V PCI/PCIX

Peripheral Component Interface (PCI) for 3.3 V standards specify support for 33 MHz and 66 MHz PCI bus applications.

8.6.7.1 Minimum and Maximum DC/AC Input and Output Levels Specification

Table 49 • PCI/PCI-X DC Voltage Specification (Applicable to MSIO Bank Only)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
PCI/PCIX DC Recommended Operating Conditions						
VDDI	Supply voltage		3.15	3.3	3.45	V
PCI/PCIX DC Input Voltage Specification						
VI	DC input voltage		0	–	3.45	V
IIH(DC)	Input current High		–	–	Table 19 on page 28	–
IIL(DC)	Input current Low		–	–	Table 19 on page 28	–
PCI/PCIX DC Output Voltage Specification						
VOH	DC output logic High		Per PCI Specification			V
VOL	DC output logic Low		Per PCI Specification			V

Table 50 • PCI/PCI-X AC Specifications (Applicable to MSIO Bank Only)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
PCI/PCI-X Minimum and Maximum AC Switching Speed						
Dmax	Maximum data rate (MSIO I/O Bank)	AC Loading: per JEDEC specifications	–	–	630	Mbps
PCI/PCI-X AC Test Parameters Specifications						
Vtrip	Measuring/trip point for data path (falling edge)		–	0.615 × VDDI	–	V
Vtrip	Measuring/trip point for data path (rising edge)		–	0.285 × VDDI	–	V
Rtt_test	Resistance for data test path		–	25	–	Ω
Rent	Resistance for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	2K	–	Ω
Cent	Capacitive loading for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	5	–	pF
Cload	Capacitive loading for data path (t _{DP})		–	10	–	pF

8.6.7.2 AC Switching Characteristics

Worst Commercial-Case Conditions: T_J = 85°C, VDD = 1.14 V, VDDI = 3.0 V

AC Switching Characteristics for Receiver (Input Buffers)

Table 51 • PCI/PCIX AC Switching Characteristics for Receiver (Input Buffers)

Worst-Case Commercial Conditions: T_J = 85°C, VDD = 1.14 V, Worst-Case VDDI

	On-Die Termination (ODT)	t _{py}		t _{pys}		Units
		Speed Grade				
		–1	Std	–1	Std	
PCI/PCIX (for MSIO I/O Bank)	None	2.229	2.623	2.238	2.633	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)
Table 52 • PCI/PCIX AC switching Characteristics for Transmitter (Output Buffers)

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}		t_{LZ}		Units
	Speed Grade										
	-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
PCI/PCIX (for MSIO I/O Bank)	2.146	2.525	2.043	2.404	2.084	2.452	6.095	7.171	5.558	6.539	ns

8.7 Memory Interface and Voltage Referenced I/O Standards

8.7.1 High-Speed Transceiver Logic (HSTL)

The High-Speed Transceiver Logic (HSTL) standard is a general purpose high-speed bus standard sponsored by IBM (EIA/JESD8-6). IGLOO2 FPGA and SmartFusion2 SoC FPGA devices support two classes of the 1.5 V HSTL. These differential versions of the standard require a differential amplifier input buffer and a push-pull output buffer.

8.7.1.1 Minimum and Maximum DC/AC Input and Output Levels Specification

Table 53 • HSTL DC Voltage Specification (Applicable to DDRIO I/O Bank Only)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
HSTL Recommended DC Operating Conditions						
VDDI	Supply voltage		1.425	1.5	1.575	V
VTT	Termination voltage		0.698	0.750	0.803	V
VREF	Input reference voltage		0.698	0.750	0.803	V
HSTL DC Input Voltage Specification						
VIH (DC)	DC input logic High		$V_{REF} + 0.1$	–	1.575	V
VIL (DC)	DC input logic Low		–0.3	–	$V_{REF} - 0.1$	V
IIH (DC)	Input current High		–	–	Table 19 on page 28	–
IIL (DC)	Input current Low		–	–	Table 19 on page 28	–
HSTL DC Output Voltage Specification						
HSTL Class I						
VOH	DC output logic High		$V_{DDI} - 0.4$	–	–	V
VOL	DC output logic Low		–	–	0.4	V
IOH at VOH	Output minimum source DC current (MSIO and DDRIO I/O Banks)		–8.0	–	–	mA
IOL at VOL	Output minimum sink current (MSIO and DDRIO I/O Banks)		8.0	–	–	mA
HSTL Class II (Applicable to DDRIO I/O Bank Only)						
VOH	DC output logic High		$V_{DDI} - 0.4$	–	–	V
VOL	DC output logic Low		–	–	0.4	V
IOH at VOH	Output minimum source DC current		–16.0	–	–	mA

Table 53 • HSTL DC Voltage Specification (Applicable to DDRIO I/O Bank Only) (continued)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
IOL at VOL	Output minimum sink current		16.0	–	–	mA
HSTL DC Differential Voltage Specifications						
VID (DC)	DC input differential voltage		0.2	–	–	V

Table 54 • HSTL AC Specifications (Applicable to DDRIO Bank Only)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
HSTL AC Differential Voltage Specifications						
VDIFF	AC input differential voltage		0.4	–	–	V
Vx	AC differential cross point voltage		0.68	–	0.9	V
HSTL Minimum and Maximum AC Switching Speed						
Dmax	Maximum data rate	AC loading: per JEDEC specifications	–	–	400	Mbps
HSTL Impedance Specification						
Rref	Supported output driver calibrated impedance (for DDRIO I/O Bank)	Reference resistance = 191 Ω	–	25.5, 47.8	–	Ω
RTT	Effective impedance value (ODT for DDRIO I/O Bank only)	Reference resistance = 191 Ω	–	47.8	–	Ω
HSTL AC Test Parameters Specification						
Vtrip	Measuring/trip point for data path		–	0.75	–	V
Rent	Resistance for enable path (t_{ZH} , t_{ZL} , t_{HZ} , t_{LZ})		–	2K	–	Ω
Cent	Capacitive loading for enable path (t_{ZH} , t_{ZL} , t_{HZ} , t_{LZ})		–	5	–	pF
Rtt_test	Reference resistance for data test path for HSTL15 Class I (t_{DP})		–	50	–	Ω
Rtt_test	Reference resistance for data test path for HSTL15 Class II (t_{DP})		–	25	–	Ω
Clod	Capacitive loading for data path (t_{DP})		–	5	–	pF

8.7.1.2 AC Switching Characteristics

AC Switching Characteristics for Receiver (Input Buffers)

Table 55 • HSTL Receiver Characteristics

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	On-Die Termination (ODT)	t_{PY}		Units
		Speed Grade		
		–1	Std	
HSTL (for DDRIO I/O Bank with Fixed Code)				
Pseudo differential	None	1.605	1.888	ns
	47.8	1.614	1.898	ns
True differential	None	1.622	1.909	ns
	47.8	1.628	1.916	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Table 56 • HSTL Transmitter Characteristics

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}		t_{LZ}		Units
	Speed Grade										
	-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
HSTL Class I (for DDRIO I/O Bank)											
Single-ended	2.6	3.059	2.514	2.958	2.514	2.958	2.431	2.86	2.431	2.86	ns
Differential	2.621	3.083	2.648	3.115	2.647	3.113	2.925	3.442	2.923	3.44	ns
HSTL Class II (for DDRIO I/O Bank)											
Single-ended	2.511	2.954	2.488	2.927	2.49	2.93	2.409	2.833	2.411	2.836	ns
Differential	2.528	2.974	2.552	3.003	2.551	3.001	2.897	3.409	2.896	3.408	ns

8.7.2 Stub-Series Terminated Logic

Stub-Series Terminated Logic (SSTL) for 2.5 V (SSTL2), 1.8 V (SSTL18), and 1.5 V (SSTL15) is supported in IGLOO2 and SmartFusion2 SoC FPGAs. SSTL2 is defined by JEDEC standard JESD8-9B and SSTL18 is defined by JEDEC standard JESD8-15. IGLOO2 SSTL I/O configurations are designed to meet double data rate standards DDR/2/3 for general purpose memory buses. Double data rate standards are designed to meet their JEDEC specifications as defined by JEDEC standard JESD79F for DDR, JEDEC standard JESD79-2F for DDR, JEDEC standard JESD79-3D for DDR3, and JEDEC standard JESD209A for LPDDR.

8.7.3 Stub-Series Terminated Logic 2.5 V (SSTL2)

SSTL2 Class I and Class II are supported in IGLOO2 and SmartFusion2 SoC FPGAs and also comply with reduced and full drive of double data rate (DDR) standards. IGLOO2 and SmartFusion2 SoC FPGA I/Os supports both standards for single-ended signaling and differential signaling for SSTL2. This standard requires a differential amplifier input buffer and a push-pull output buffer.

8.7.3.1 Minimum and Maximum DC/AC Input and Output Levels Specification

Table 57 • DDR1/SSTL2 DC Voltage Specification

Symbols	Parameters	Conditions	Min	Typ	Max	Units
DDR/SSTL2 DC Recommended Operating Conditions						
VDDI	Supply voltage		2.375	2.5	2.625	V
VTT	Termination voltage		1.164	1.250	1.339	V
VREF	Input reference voltage		1.164	1.250	1.339	V
DDR/SSTL2 DC Input Voltage Specification						
VIH (DC)	DC input logic High		VREF + 0.15	–	2.625	V
VIL (DC)	DC input logic Low		–0.3	–	VREF – 0.15	V
IIH (DC)	Input current High		–	–	Table 19 on page 28	–
IIL (DC)	Input current Lo		–	–	Table 19 on page 28	–
DDR/SSTL2 DC Output Voltage Specification						
SSTL2 Class I (DDR Reduced Drive)						
VOH	DC output logic High		VTT + 0.608	–	–	V
VOL	DC output logic Low		–	–	VTT – 0.608	V
IOH at VOH	Output minimum source DC current		8.1	–	–	mA
IOL at VOL	Output minimum sink current		–8.1	–	–	mA
SSTL2 Class II (DDR Full Drive) – Applicable to MSIO and DDRIO I/O Banks Only						
VOH	DC output logic High		VTT + 0.81	–	–	V
VOL	DC output logic Low		–	–	VTT – 0.81	V
IOH at VOH	Output minimum source DC current		16.2	–	–	mA
IOL at VOL	Output minimum sink current		–16.2	–	–	mA
SSTL2 DC Differential Voltage Specification						
VID (DC)	DC input differential voltage		0.3	–	–	V

Table 58 • DDR1/SSTL2 AC Specifications

Symbols	Parameters	Conditions	Min	Typ	Max	Units
SSTL2 AC Differential Voltage Specification						
VDIFF (AC)	AC input differential voltage		0.7	–	–	V
Vx (AC)	AC differential cross point voltage		0.5 × VDDI – 0.2	–	0.5 × VDDI + 0.2	V
SSTL2 Minimum and Maximum AC Switching Speeds						
Dmax	Maximum data rate (for DDRIO I/O Bank)	AC loading: per JEDEC specifications	–	–	400	Mbps
Dmax	Maximum data rate (for MSIO I/O Bank)	AC loading: 17pF load	–	–	575	Mbps

Table 58 • DDR1/SSTL2 AC Specifications (continued)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
Dmax	Maximum data rate (for MSIOD I/O Bank)	AC loading: 3 pF / 50 Ω load	–	–	700	Mbps
		AC loading: 17pF load	–	–	510	Mbps
SSTL2 Impedance Specifications						
–	Supported output driver calibrated impedance (for DDRIO I/O Bank)	Reference resistor = 150 Ω	–	20, 42	–	Ω
AC Test Parameters Specifications						
Vtrip	Measuring/trip point for data path		–	1.25	–	V
Rent	Resistance for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	2K	–	Ω
Cent	Capacitive loading for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	5	–	pF
Rtt_test	Reference resistance for data test path for SSTL2 Class I (t _{DP})		–	50	–	Ω
Rtt_test	Reference resistance for data test path for SSTL2 Class II (t _{DP})		–	25	–	Ω
Cload	Capacitive loading for data path (t _{DP})		–	5	–	pF

8.7.3.2 AC Switching Characteristics

 Worst Commercial-Case Conditions: T_J = 85°C, VDD = 1.14 V, VDDI = 2.375 V

AC Switching Characteristics for Receiver (Input Buffers)

Table 59 • DDR1/SSTL2 Receiver Characteristics

 Worst-Case Commercial Conditions: T_J = 85°C, VDD = 1.14 V, Worst-Case VDDI

	On-Die Termination (ODT)	t _{py}		Units
		Speed Grade		
		–1	Std	
SSTL2 (for DDRIO I/O Bank)				
Pseudo differential	None	1.549	1.821	ns
True differential	None	1.589	1.87	ns
SSTL2 (for MSIO I/O Bank)				
Pseudo differential	None	2.798	3.293	ns
True differential	None	2.733	3.215	ns
SSTL2 (for MSIOD I/O Bank)				
Pseudo differential	None	2.476	2.913	ns
True differential	None	2.475	2.911	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)
Table 60 • DDR1/SSTL2 Transmitter Characteristics

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}		t_{LZ}		Units
	Speed Grade										
	-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
SSTL2 Class I (for DDRIO I/O Bank)											
Single-ended	2.26	2.66	1.99	2.341	1.985	2.335	2.135	2.512	2.13	2.505	ns
Differential	2.26	2.658	2.202	2.591	2.201	2.589	2.393	2.815	2.392	2.814	ns
SSTL2 Class I (for MSIO I/O Bank)											
Single-ended	2.055	2.417	2.037	2.396	2.03	2.388	2.068	2.433	2.061	2.425	ns
Differential	2.192	2.58	2.434	2.864	2.425	2.852	2.164	2.545	2.156	2.536	ns
SSTL2 Class I (for MSIOD I/O Bank)											
Single-ended	1.512	1.779	1.462	1.72	1.462	1.72	1.676	1.972	1.676	1.971	ns
Differential	1.676	1.971	1.774	2.087	1.766	2.077	1.854	2.181	1.845	2.171	ns
SSTL2 Class II (for DDRIO I/O Bank)											
Single-ended	2.122	2.497	1.906	2.243	1.902	2.237	2.061	2.424	2.056	2.418	ns
Differential	2.127	2.501	2.042	2.402	2.043	2.403	2.363	2.78	2.365	2.781	ns
SSTL2 Class I (for MSIO I/O Bank)											
Single-ended	2.29	2.693	1.988	2.338	1.978	2.326	1.989	2.34	1.979	2.328	ns
Differential	2.418	2.846	2.304	2.711	2.297	2.702	2.131	2.506	2.124	2.499	ns

8.7.4 Stub-Series Terminated Logic 1.8 V (SSTL18)

SSTL18 Class I and Class II are supported in IGLOO2 and SmartFusion2 SoC FPGAs, and also comply with the reduced and full drive double data rate (DDR2) standard. IGLOO2 and SmartFusion2 SoC FPGA I/Os support both standards for single-ended signaling and differential signaling for SSTL18. This standard requires a differential amplifier input buffer and a push-pull output buffer.

8.7.4.1 Minimum and Maximum DC/AC Input and Output Levels Specification
Table 61 • SSTL18 DC Minimum and Maximum DC Input and Output Levels

Symbols	Parameters	Conditions	Min	Typ	Max	Units	Notes
SSTL18 DC Recommended DC Operating Conditions							
VDDI	Supply voltage		1.71	1.8	1.89	V	–
VTT	Termination voltage		0.838	0.900	0.964	V	–
VREF	Input reference voltage		0.838	0.900	0.964	V	–
SSTL18 DC Input Voltage Specification							
VIH (DC)	DC input logic High		VREF + 0.125	–	1.89	V	–
VIL (DC)	DC input logic Low		–0.3	–	VREF – 0.125	V	–
IIH (DC)	Input current High		–	–	Table 19 on page 28	–	–

Note: *To meet JEDEC Electrical Compliance, use DDR2 Full Drive Transmitter.

Table 61 • SSTL18 DC Minimum and Maximum DC Input and Output Levels (continued)

Symbols	Parameters	Conditions	Min	Typ	Max	Units	Notes
IIL (DC)	Input current Low		–	–	Table 19 on page 28	–	–
SSTL18 DC Output Voltage Specification							
SSTL18 Class I (DDR2 Reduced Drive)							
VOH	DC output logic High		VTT + 0.603	–	–	V	–
VOL	DC output logic Low		–	–	VTT– 0.603	V	–
IOH at VOH	Output minimum source DC current (DDRIO I/O Bank only)		6.5	–	–	mA	–
IOL at VOL	Output minimum sink current (DDRIO I/O Bank only)		–6.5	–	–	mA	–
SSTL18 Class II (DDR2 Full Drive)							
VOH	DC output logic High		VTT + 0.603	–	–	V	–
VOL	DC output logic Low		–	–	VTT– 0.603	V	–
IOH at VOH	Output minimum source DC current (DDRIO I/O Bank only)		13.4	–	–	mA	–
IOL at VOL	Output minimum sink current (DDRIO I/O Bank only)		–13.4	–	–	mA	–
SSTL18 DC Differential Voltage Specification							
VID (DC)	DC input differential voltage		0.3	–	–	V	–
<i>Note: *To meet JEDEC Electrical Compliance, use DDR2 Full Drive Transmitter.</i>							

Table 62 • SSTL18 AC Specifications (Applicable to DDRIO Bank Only)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
SSTL18 AC Differential Voltage Specification						
VDIFF (AC)	AC input differential voltage		0.5	–	–	V
Vx (AC)	AC differential cross point voltage		$0.5 \times VDDI - 0.175$	–	$0.5 \times VDDI + 0.175$	V
SSTL18 Minimum and Maximum AC Switching Speed						
Dmax	Maximum data rate (for DDRIO I/O Bank)	AC loading: per JEDEC specification	–	–	667	Mbps
SSTL18 Impedance Specifications						
Rref	Supported output driver calibrated impedance (for DDRIO I/O Bank)	Reference resistor = 150 Ω	–	20, 42	–	Ω
RTT	Effective impedance value (ODT)	Reference resistor = 150 Ω	–	50, 75, 150	–	Ω
SSTL18 AC Test Parameters Specifications						
Vtrip	Measuring/trip point for data path		–	0.9	–	V
Rent	Resistance for enable path (t_{ZH} , t_{ZL} , t_{HZ} , t_{LZ})		–	2K	–	Ω
Cent	Capacitive loading for enable path (t_{ZH} , t_{ZL} , t_{HZ} , t_{LZ})		–	5	–	pF

Table 62 • SSTL18 AC Specifications (Applicable to DDRIO Bank Only) (continued)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
Rtt_test	Reference resistance for data test path for SSTL18 Class I (t_{DP})		–	50	–	Ω
Rtt_test	Reference resistance for data test path for SSTL18 Class II (t_{DP})		–	25	–	Ω
Cload	Capacitive loading for data path (t_{DP})		–	5	–	pF

8.7.4.2 AC Switching Characteristics

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, $V_{DDI} = 1.71\text{ V}$

AC Switching Characteristics for Receiver (Input Buffers)

Table 63 • DDR2/SSTL18 Receiver Characteristics

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case V_{DDI}

	On-Die Termination (ODT)	t_{PY}		Units
		Speed Grade		
		–1	Std	
SSTL18 (for DDRIO I/O Bank with Fixed Code)				
Pseudo differential	None	1.567	1.844	ns
True differential	None	1.588	1.869	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Table 64 • DDR2/SSTL18 Transmitter Characteristics

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case V_{DDI}

	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}		t_{LZ}		Units
	Speed Grade										
	–1	Std	–1	Std	–1	Std	–1	Std	–1	Std	
SSTL18 Class I (for DDRIO I/O Bank)											
Single-ended	2.383	2.804	2.23	2.623	2.229	2.622	2.202	2.591	2.201	2.59	ns
Differential	2.413	2.84	2.797	3.29	2.797	3.29	2.282	2.685	2.282	2.685	ns
SSTL18 Class II (for DDRIO I/O Bank)											
Single-ended	2.281	2.683	2.196	2.584	2.195	2.583	2.171	2.555	2.17	2.554	ns
Differential	2.315	2.724	2.698	3.173	2.698	3.173	2.242	2.639	2.242	2.639	ns

8.7.5 Stub-Series Terminated Logic 1.5 V (SSTL15)

SSTL15 Class I and Class II are supported in IGLOO2 FPGAs and SmartFusion2 SoC FPGAs, and also comply with the reduced and full drive double data rate (DDR3) standard. IGLOO2 FPGA and SmartFusion2 SoC FPGA I/Os supports both standards for single-ended signaling and differential signaling for SSTL18. This standard requires a differential amplifier input buffer and a push-pull output buffer.

8.7.5.1 Minimum and Maximum DC/AC Input and Output Levels Specification

Table 65 • SSTL15 DC Voltage Specification (for DDRIO I/O Bank Only)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
SSTL15 DC Recommended DC Operating Conditions						
VDDI	Supply voltage		1.425	1.5	1.575	V
VTT	Termination voltage		0.698	0.750	0.803	V
VREF	Input reference voltage		0.698	0.750	0.803	V
SSTL15 DC Input Voltage Specification						
VIH(DC)	DC input logic High		VREF + 0.1	–	1.575	V
VIL(DC)	DC input logic Low		–0.3	–	VREF – 0.1	V
IIH (DC)	Input current High		–	–	Table 19 on page 28	–
IIL (DC)	Input current Low		–	–	Table 19 on page 28	–
SSTL15 DC Output Voltage Specification						
DDR3/SSTL15 Class I (DDR3 Reduced Drive)						
VOH	DC output logic High		0.8 × VDDI	–	–	V
VOL	DC output logic Low		–	–	0.2 × VDDI	V
IOH at VOH	Output minimum source DC current		6.5	–	–	mA
IOL at VOL	Output minimum sink current		–6.5	–	–	mA
DDR3/SSTL15 Class II (DDR3 Full Drive)						
VOH	DC output logic High		0.8 × VDDI	–	–	V
VOL	DC output logic Low		–	–	0.2 × VDDI	V
IOH at VOH	Output minimum source DC current		7.6	–	–	mA
IOL at VOL	Output minimum sink current		–7.6	–	–	mA
SSTL15 Differential Voltage Specification						
VID	DC input differential voltage		0.2	–	–	V
<i>Note: *To meet JEDEC Electrical Compliance, use DDR3 Full Drive Transmitter.</i>						

Table 66 • SSTL15 AC Specifications (for DDRIO I/O Bank Only)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
SSTL15 Differential Voltage Specification						
V _{DIFF} (AC)	AC input differential voltage		0.3	–	–	V
V _x (AC)	AC differential cross point voltage		0.5 × V _{DDI} – 0.150	–	0.5 × V _{DDI} + 0.150	V
SSTL15 Minimum and Maximum AC Switching Speed (for DDRIO I/O Banks only)						
D _{max}	Maximum data rate	AC loading: per JEDEC specifications	–	–	667	Mbps
SSTL15 AC Calibrated Impedance Option						
R _{ref}	Supported output driver calibrated impedance	Reference resistor = 240 Ω	–	34, 40	–	Ω
R _{TT}	Effective impedance value (ODT)	Reference resistor = 240 Ω	–	20, 30, 40, 60, 120	–	Ω
SSTL15 AC Test Parameters Specifications						
V _{trip}	Measuring/trip point for data path		–	0.75	–	V
R _{ent}	Resistance for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	2K	–	Ω
C _{ent}	Capacitive loading for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	5	–	pF
R _{tt_test}	Reference resistance for data test path for SSTL15 Class I (t _{DP})		–	50	–	Ω
R _{tt_test}	Reference resistance for data test path for SSTL15 Class II (t _{DP})		–	25	–	Ω
C _{load}	Capacitive loading for data path (t _{DP})		–	5	–	pF

8.7.5.2 AC Switching Characteristics

Worst Commercial-Case Conditions: T_J = 85°C, V_{DD} = 1.14 V, V_{DDI} = 1.425 V

AC Switching Characteristics for Receiver (Input Buffers)

Table 67 • DDR3/SSTL15 Receiver Characteristics

Worst-Case Commercial Conditions: T_J = 85°C, V_{DD} = 1.14 V, Worst-Case V_{DDI}

	On-Die Termination (ODT)	t _{py}		Units
		Speed Grade		
		–1	Std	
DDR3/SSTL15 (for DDRIO I/O Bank – with Calibration Only)				
Pseudo differential	None	1.605	1.888	ns
	20	1.616	1.901	ns
	30	1.613	1.897	ns
	40	1.611	1.895	ns
	60	1.609	1.893	ns
	120	1.607	1.89	ns

Table 67 • DDR3/SSTL15 Receiver Characteristics (continued)
 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	On-Die Termination (ODT)	t_{PY}		Units
		Speed Grade		
		-1	Std	
True differential	None	1.623	1.91	ns
	20	1.637	1.926	ns
	30	1.63	1.918	ns
	40	1.626	1.914	ns
	60	1.622	1.91	ns
	120	1.619	1.905	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Table 68 • DDR3/SSTL15 Transmitter Characteristics
 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}		t_{LZ}		Units
	Speed Grade										
	-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
DDR3 Reduced Drive/SSTL15 Class I (for DDRIO I/O Bank)											
Single-ended	2.533	2.98	2.522	2.967	2.523	2.968	2.427	2.855	2.428	2.856	ns
Differential	2.555	3.005	3.073	3.615	3.073	3.615	2.416	2.843	2.416	2.843	ns
DDR3 Full Drive/SSTL15 Class II (for DDRIO I/O Bank)											
Single-ended	2.53	2.977	2.514	2.958	2.516	2.96	2.422	2.849	2.425	2.852	ns
Differential	2.552	3.002	2.591	3.048	2.59	3.047	2.882	3.391	2.881	3.39	ns

8.7.6 Low Power Double Data Rate (LPDDR)

LPDDR reduced and full drive low power double data rate standards are supported in IGLOO2 FPGA and SmartFusion2 SoC FPGA I/Os. This standard requires a differential amplifier input buffer and a push-pull output buffer.

8.7.6.1 Minimum and Maximum DC/AC Input and Output Levels Specification

Table 69 • LPDDR DC Voltage Specification

Symbols	Parameters	Conditions	Min	Typ	Max	Units	Notes
Recommended DC Operating Conditions							
VDDI	Supply voltage		1.71	1.8	1.89	V	–
VTT	Termination voltage		0.838	0.900	0.964	V	–
VREF	Input reference voltage		0.838	0.900	0.964	V	–
LPDDR DC Input Voltage Specification							
VIH (DC)	DC input logic High		$0.7 \times V_{DDI}$	–	1.89	V	–
VIL (DC)	DC input logic Low		–0.3	–	$0.3 \times V_{DDI}$	V	–
IIH (DC)	Input current High		–	–	Table 19 on page 28	–	–

Table 69 • LPDDR DC Voltage Specification (continued)

Symbols	Parameters	Conditions	Min	Typ	Max	Units	Notes
IIL (DC)	Input current Low		–	–	Table 19 on page 28	–	–
LPDDR DC Output Voltage Specification Reduced Drive							
VOH	DC output logic High		$0.9 \times VDDI$	–	–	V	–
VOL	DC output logic Low		–	–	$0.1 \times VDDI$	V	–
IOH at VOH	Output minimum source DC current		0.1	–	–	mA	–
IOL at VOL	Output minimum sink current		–0.1	–	–	mA	–
LPDDR DC Output Voltage Specification Full Drive							
VOH	DC output logic High		$0.9 \times VDDI$	–	–	V	–
VOL	DC output logic Low		–	–	$0.1 \times VDDI$	V	–
IOH at VOH	Output minimum source DC current		0.1	–	–	mA	–
IOL at VOL	Output minimum sink current		–0.1	–	–	mA	–
LPDDR Differential Voltage Specification							
VID (DC)	DC input differential voltage		$0.4 \times VDDI$	–	–	V	–
<i>Note: *To meet JEDEC Electrical Compliance, use LPDDR Full Drive Transmitter.</i>							

Table 70 • LPDDR AC Specifications (for DDRIO I/O Banks Only)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
LPDDR AC Differential Voltage Specification						
VDIFF	AC input differential voltage		$0.6 \times VDDI$	–	–	V
V _x	AC differential cross point voltage		$0.4 \times VDDI$	–	$0.6 \times VDDI$	V
LPDDR AC Specifications						
Dmax	Maximum data rate	AC loading: per JEDEC specifications	–	–	400	Mbps
LPDDR AC Calibrated Impedance Option						
Rref	Supported output driver calibrated impedance	Reference resistor = 150 Ω	–	20, 42	–	Ω
Rtt	Effective impedance value (ODT)	Reference resistor = 150 Ω	–	50, 70, 150	–	Ω
LPDDR AC Test Parameters Specifications						
Vtrip	Measuring/trip point for data path		–	0.9	–	V
Rent	Resistance for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	2K	–	Ω
Cent	Capacitive loading for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	5	–	pF
Rtt_test	Reference resistance for data test path for LPDDR (t _{DP})		–	50	–	Ω
Cload	Capacitive loading for data path (t _{DP})		–	5	–	Ω

8.7.6.2 AC Switching Characteristics

Table 71 • LPDDR Receiver Characteristics

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	On-Die Termination (ODT)	t_{py}		Units
		Speed Grade		
		-1	Std	
LPDDR (for DDRIO I/O Bank with FIXED CODES)				
Pseudo differential	None	1.568	1.845	ns
True differential	None	1.588	1.869	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Table 72 • LPDDR Transmitter Characteristics

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	t_{DP}		t_{ENZL}		t_{ENZH}		t_{ENHZ}		t_{ENLZ}		Units
	Speed Grade										
	-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
LPDDR Reduced Drive for DDRIO I/O Bank											
Single-ended	2.383	2.804	2.23	2.623	2.229	2.622	2.202	2.591	2.201	2.59	ns
Differential	2.396	2.819	2.764	3.252	2.764	3.252	2.255	2.653	2.255	2.653	ns
LPDDR Full Drive for DDRIO I/O Bank											
Single-ended	2.281	2.683	2.196	2.584	2.195	2.583	2.171	2.555	2.17	2.554	ns
Differential	2.298	2.703	2.288	2.692	2.288	2.692	2.593	3.051	2.593	3.051	ns

8.7.6.3 Minimum and Maximum DC/AC Input and Output Levels Specification using LPDDR-LVCMOS 1.8 V Mode

Table 73 • LPDDR-LVCMOS 1.8 V Mode (Minimum and Maximum DC Input and Output Levels)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
LPDDR-LVCMOS 1.8 V Recommended DC Operating Conditions						
VDDI	Supply Voltage		1.710	1.8	1.89	V
LPDDR-LVCMOS 1.8 V Mode DC Input Voltage Specification						
$V_{IH}(dc)$	DC input Logic HIGH (for MSIOD and DDRIO I/O Banks)		$0.65 \times V_{DDI}$	–	1.89	V
$V_{IH}(dc)$	DC input Logic HIGH (for MSIO I/O Bank)		$0.65 \times V_{DDI}$	–	3.45	V
$V_{IL}(dc)$	DC input Logic LOW		-0.3	–	$0.35 \times V_{DDI}$	V
$I_{IH}(dc)$	Input current HIGH		–	–	Table 19 on page 28	–
$I_{IL}(dc)$	Input current LOW		–	–	Table 19 on page 28	–
LPDDR-LVCMOS 1.8V Mode DC Output Voltage Specification						
V_{OH}	DC output Logic HIGH		$V_{DDI} - 0.45$	–	–	V
V_{OL}	DC output Logic LOW		–	–	0.45	V

Table 74 • LPDDR-LVCMOS 1.8 V Minimum and Maximum AC Switching Speeds

Symbols	Parameters	Conditions	Min	Typ	Max	Units
Dmax	Maximum Data Rate (for DDRIO I/O Bank)	AC Loading: 17pF Load, 8mA Drive and Above/All Slew	–	–	400	Mbps

Table 75 • LPDDR-LVCMOS 1.8 V Minimum and Maximum AC Input and Output Levels

Symbols	Parameters	Conditions	Min	Typ	Max	Units
LPDDR - LVCMOS 1.8 V Calibrated Impedance Option						
Rodt_cal	Supported Output Driver Calibrated Impedance (for DDRIO I/O Bank)		–	75,60,50,33,25,20	–	Ω
LPDDR- LVCMOS 1.8V AC Test Parameters Specifications						
Vtrip	Measuring/Trip Point for data path		–	0.9	–	V
Rent	Resistance for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	2K	–	Ω
Cent	Capacitive Loading for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	5	–	pF
Cload	Capacitive Loading for data path (t _{DP})		–	5	–	pF

Table 76 • LPDDR-LVCMOS 1.8 V Mode Transmitter Drive Strength Specification

Output Drive Selection	VOH (V) Min	VOL (V) Max	IOH (at VOH) mA	IOL (at VOL) mA	Notes
DDRIO Bank					
2 mA	VDDI – 0.45	0.45	2	2	–
4 mA	VDDI – 0.45	0.45	4	4	–
6 mA	VDDI – 0.45	0.45	6	6	–
8 mA	VDDI – 0.45	0.45	8	8	–
10 mA	VDDI – 0.45	0.45	10	10	–
12 mA	VDDI – 0.45	0.45	12	12	–
16 mA	VDDI – 0.45	0.45	16	16	*

*Note: *16mA Drive Strengths, All Slews, meet LPDDR JEDEC electrical compliance*

Table 77 • LPDDR-LVCMOS 1.8V AC Switching Characteristics for Receiver (Input Buffers)

	ODT (On Die Termination)	Speed Grade				Units
		–1	Std	–1	Std	
LPDDR-LVCMOS 1.8 mode (for DDRIO I/O Bank with Fixed Code)	None	1.968	2.315	2.099	2.47	ns

Table 78 • LPDDR-LVCMOS 1.8 V AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Output Drive Selection	Slew Control	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}^*		t_{LZ}^*		Units
		Speed Grade										
		-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
LPDDR-LVCMOS 1.8 V Mode (for DDRIO I/O Bank)												
2 mA	slow	4.234	4.981	3.646	4.29	4.245	4.995	4.908	5.774	4.434	5.216	ns
	medium	3.824	4.498	3.282	3.861	3.834	4.511	4.625	5.441	4.116	4.843	ns
	medium_fast	3.627	4.267	3.111	3.66	3.637	4.279	4.481	5.272	3.984	4.687	ns
	fast	3.605	4.241	3.097	3.644	3.615	4.253	4.472	5.262	3.973	4.674	ns
4 mA	slow	3.923	4.615	3.314	3.9	3.918	4.61	5.403	6.356	4.894	5.757	ns
	medium	3.518	4.138	2.961	3.484	3.515	4.135	5.121	6.025	4.561	5.366	ns
	medium_fast	3.321	3.907	2.783	3.275	3.317	3.903	4.966	5.843	4.426	5.206	ns
	fast	3.301	3.883	2.77	3.259	3.296	3.878	4.957	5.831	4.417	5.196	ns
6 mA	slow	3.71	4.364	3.104	3.652	3.702	4.355	5.62	6.612	5.08	5.977	ns
	medium	3.333	3.921	2.779	3.27	3.325	3.913	5.346	6.289	4.777	5.62	ns
	medium_fast	3.155	3.712	2.62	3.083	3.146	3.702	5.21	6.13	4.657	5.479	ns
	fast	3.134	3.688	2.608	3.068	3.125	3.677	5.202	6.12	4.648	5.468	ns
8 mA	slow	3.619	4.258	3.007	3.538	3.607	4.244	5.815	6.841	5.249	6.175	ns
	medium	3.246	3.819	2.686	3.16	3.236	3.807	5.542	6.52	4.936	5.807	ns
	medium_fast	3.066	3.607	2.525	2.971	3.054	3.593	5.405	6.359	4.811	5.66	ns
	fast	3.046	3.584	2.513	2.957	3.034	3.57	5.401	6.353	4.803	5.651	ns
10 mA	slow	3.498	4.115	2.878	3.386	3.481	4.096	6.046	7.113	5.444	6.404	ns
	medium	3.138	3.692	2.569	3.023	3.126	3.678	5.782	6.803	5.129	6.034	ns
	medium_fast	2.966	3.489	2.414	2.841	2.951	3.472	5.666	6.665	5.013	5.897	ns
	fast	2.945	3.464	2.401	2.826	2.93	3.448	5.659	6.658	5.003	5.886	ns
12 mA	slow	3.417	4.02	2.807	3.303	3.401	4.002	6.083	7.156	5.464	6.428	ns
	medium	3.076	3.618	2.519	2.964	3.063	3.604	5.828	6.856	5.176	6.089	ns
	medium_fast	2.913	3.427	2.376	2.795	2.898	3.41	5.725	6.736	5.072	5.966	ns
	fast	2.894	3.405	2.362	2.78	2.879	3.388	5.715	6.724	5.064	5.957	ns
16 mA	slow	3.366	3.96	2.751	3.237	3.348	3.939	6.226	7.324	5.576	6.56	ns
	medium	3.03	3.565	2.47	2.906	3.017	3.55	5.981	7.036	5.282	6.214	ns
	medium_fast	2.87	3.377	2.328	2.739	2.854	3.358	5.895	6.935	5.18	6.094	ns
	fast	2.853	3.357	2.314	2.723	2.837	3.338	5.889	6.929	5.177	6.09	ns

*Note: *Delay increases with drive strength are inherent to built-in slew control circuitry for simultaneous switching output (SSO) management).*

8.8. Differential I/O Standards

Configuration of the I/O modules as a differential pair is handled by Microsemi SoC Products Group Libero software when the user instantiates a differential I/O macro in the design. Differential I/Os can also be used in conjunction with the embedded Input register (InReg), Output register (OutReg), Enable register (EnReg), and Double Data Rate registers (DDR).

8.8.1 LVDS

Low-Voltage Differential Signaling (ANSI/TIA/EIA-644) is a high-speed, differential I/O standard.

8.8.1.1 Minimum and Maximum Input and Output Levels

Table 79 • LVDS DC Voltage Specification

Symbols	Parameters	Conditions	Min	Typ	Max	Units
LVDS Recommended DC Operating Conditions						
VDDI	Supply voltage	2.5 V range	2.375	2.5	2.625	V
VDDI	Supply voltage	3.3 V range	3.15	3.3	3.45	V
LVDS DC Input Voltage Specification						
VI	DC Input voltage	2.5 V range	0	–	2.925	V
VI	DC input voltage	3.3 V range	0	–	3.45	V
IIH (DC)	Input current High	–	–	–	Table 19 on page 28	–
IIL (DC)	Input current Low	–	–	–	Table 19 on page 28	–
LVDS DC Output Voltage Specification						
VOH	DC output logic High	–	1.25	1.425	1.6	V
VOL	DC output logic Low	–	0.9	1.075	1.25	V
LVDS Differential Voltage Specification						
VOD	Differential output voltage swing	–	250	350	450	mV
VOCM	Output common mode voltage	–	1.125	1.25	1.375	V
VICM	Input common mode voltage	–	0.05	1.25	2.35	V
VID	Input differential voltage	–	100	350	600	mV

Table 80 • LVDS AC Specifications

Symbols	Parameters	Conditions	Min	Typ	Max	Units
LVDS Minimum and Maximum AC Switching Speed						
Dmax	Maximum data rate (for MSIO I/O Bank)	AC loading: 12 pF / 100 Ω differential load	–	–	535	Mbps
Dmax	Maximum data rate (for MSIOD I/O Bank) no pre-emphasis	AC loading: 10 pF / 100 Ω differential load	–	–	620	Mbps
		AC loading: 2 pF / 100 Ω differential load	–	–	700	Mbps
LVDS Impedance Specification						
Rt	Termination resistance		–	100	–	Ω

Table 80 • LVDS AC Specifications (continued)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
LVDS AC Test Parameters Specifications						
Vtrip	Measuring/trip point for data path		–	Cross point	–	V
Rent	Resistance for enable path (t_{ZH} , t_{ZL} , t_{HZ} , t_{LZ})		–	2K	–	Ω
Cent	Capacitive loading for enable path (t_{ZH} , t_{ZL} , t_{HZ} , t_{LZ})		–	5	–	pF

8.8.1.2 LVDS25 AC Switching Characteristics

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, $V_{DDI} = 2.375\text{ V}$

AC Switching Characteristics for Receiver (Input Buffers)

Table 81 • LVDS25 Receiver Characteristics

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	On-Die Termination (ODT)	t_{PY}		Units
		Speed Grade		
		–1	Std	
LVDS (for MSIO I/O Bank)	None	2.774	3.263	ns
	100	2.775	3.264	ns
LVDS (for MSIOD I/O Bank)	None	2.554	3.004	ns
	100	2.549	2.999	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Table 82 • LVDS25 Transmitter Characteristics

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}		t_{LZ}		Units
	Speed Grade										
	–1	Std	–1	Std	–1	Std	–1	Std	–1	Std	
LVDS (for MSIO I/O Bank)	2.136	2.513	2.416	2.842	2.402	2.825	2.423	2.85	2.409	2.833	ns
LVDS (for MSIOD I/O Bank)											
No pre-emphasis	1.61	1.893	1.749	2.058	1.735	2.041	1.897	2.231	1.866	2.195	ns
Min pre-emphasis	1.527	1.796	1.757	2.067	1.744	2.052	1.905	2.241	1.876	2.207	ns
Med pre-emphasis	1.496	1.76	1.765	2.077	1.751	2.06	1.914	2.252	1.884	2.216	ns

8.8.1.3 LVDS33 AC Switching Characteristics

AC Switching Characteristics for Receiver (Input Buffers)

Table 83 • LVDS33 Receiver Characteristics

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	On Die Termination (ODT)	t_{PY}		Units
		Speed Grade		
		–1	Std	
LVDS33 (for MSIO I/O Bank)	None	2.572	3.025	ns
	100	2.569	3.023	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Table 84 • LVDS33 Transmitter Characteristics

Worst-Case Commercial Conditions: T_J = 85°C, VDD = 1.14 V, Worst-Case VDDI

	t _{DP}		t _{ZL}		t _{ZH}		t _{HZ}		t _{LZ}		Units
	Speed Grade										
	-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
LVDS33 (for MSIO I/O Bank)	1.942	2.284	1.98	2.33	1.97	2.318	1.953	2.298	1.96	2.307	ns

8.8.2 B-LVDS

Bus LVDS (B-LVDS) specifications extend the existing LVDS standard to high-performance multipoint bus applications. Multidrop and multipoint bus configurations may contain any combination of drivers, receivers, and transceivers.

8.8.2.1 Minimum and Maximum DC/AC Input and Output Levels Specification

Table 85 • B-LVDS DC Voltage Specification

Symbols	Parameters	Conditions	Min	Typ	Max	Units
Recommended DC Operating Conditions						
VDDI	Supply voltage		2.375	2.5	2.625	V
Bus-LVDS DC Input Voltage Specification						
V _I	DC input voltage		0	–	2.925	V
I _{IH} (DC)	Input current High		–	–	Table 19 on page 28	–
I _{IL} (DC)	Input current Low		–	–	Table 19 on page 28	–
Bus-LVDS DC Output Voltage Specification (for MSIO I/O Bank Only)						
V _{OH}	DC output logic High		1.25	1.425	1.6	V
V _{OL}	DC output logic Low		0.9	1.075	1.25	V
Bus-LVDS Differential Voltage Specification						
V _{OD}	Differential output voltage swing (for MSIO I/O Bank Only)		65	–	460	mV
V _{OCM}	Output common mode voltage (for MSIO I/O Bank Only)		1.1	–	1.5	V
V _{ICM}	Input common mode voltage		0.05	–	2.4	V
V _{ID}	Input differential voltage		0.1	–	VDDI	V

Table 86 • B-LVDS AC Specifications

Symbols	Parameters	Conditions	Min	Typ	Max	Units
Bus-LVDS Minimum and Maximum AC Switching Speed						
D _{max}	Maximum data rate (for MSIO I/O Bank)	AC loading: 2 pF / 100 Ω differential load	–	–	500	Mbps
Bus-LVDS Impedance Specifications						
R _t	Termination resistance		–	27	–	Ω
Bus-LVDS AC Test Parameters Specifications						
V _{trip}	Measuring/trip point for data path		–	Cross point	–	V

Table 86 • B-LVDS AC Specifications (continued)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
Rent	Resistance for enable path (t_{ZH} , t_{ZL} , t_{HZ} , t_{LZ})		–	2K	–	Ω
Cent	Capacitive loading for enable path (t_{ZH} , t_{ZL} , t_{HZ} , t_{LZ})		–	5	–	pF

8.8.2.2 AC Switching Characteristics

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, $V_{DDI} = 2.375\text{ V}$

AC Switching Characteristics for Receiver (Input Buffers)

Table 87 • B-LVDS AC Switching Characteristics for Receiver (Input Buffers)

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	On-Die Termination (ODT)	t_{PY}		Units
		Speed Grade		
		–1	Std	
Bus-LVDS (for MSIO I/O Bank)	None	2.738	3.221	ns
	100	2.735	3.218	ns
Bus-LVDS (for MSIOD I/O Bank)	None	2.495	2.934	ns
	100	2.495	2.935	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Table 88 • B-LVDS AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}		t_{LZ}		Units
	Speed Grade										
	–1	Std	–1	Std	–1	Std	–1	Std	–1	Std	
Bus-LVDS (for MSIO I/O Bank)	2.258	2.656	2.343	2.756	2.329	2.74	2.12	2.494	2.123	2.497	ns

8.8.3 M-LVDS

M-LVDS specifications extend the existing LVDS standard to high-performance multipoint bus applications. Multidrop and multipoint bus configurations may contain any combination of drivers, receivers, and transceivers.

8.8.3.1 Minimum and Maximum Input and Output Levels

Table 89 • M-LVDS DC Voltage Specification

Symbols	Parameters	Min	Typ	Max	Units	Notes
M-LVDS Recommended DC Operating Conditions						
VDDI	Supply voltage	2.375	2.5	2.625	V	*
M-LVDS DC Input Voltage Specification						
V_I	DC input voltage	0	–	2.925	V	–
IIH (DC)	Input current High	–	–	Table 19 on page 28	–	–
IIL (DC)	Input current Low	–	–	Table 19 on page 28	–	–

Table 89 • M-LVDS DC Voltage Specification (continued)

Symbols	Parameters	Min	Typ	Max	Units	Notes
M-LVDS DC Output Voltage Specification (for MSIO I/O Bank Only)						
VOH	DC output logic High	1.25	1.425	1.6	V	–
VOL	DC output logic Low	0.9	1.075	1.25	V	–
M-LVDS Differential Voltage Specification						
VOD	Differential output voltage swing (for MSIO I/O Bank Only)	300	–	650	mV	–
VOCM	Output common mode voltage (for MSIO I/O Bank Only)	0.3	–	2.1	V	–
VICM	Input common mode voltage	0.3	–	1.2	V	–
VID	Input differential voltage	50	–	2400	mV	–
<i>Note: *Only M-LVDS TYPE I is supported</i>						

Table 90 • M-LVDS AC Specifications

Symbols	Parameters	Conditions	Min	Typ	Max	Units
M-LVDS Minimum and Maximum AC Switching Speed						
Dmax	Maximum data rate (for MSIO I/O Bank)	AC loading: 2 pF / 100 Ω differential load	–	–	500	Mbps
M-LVDS Impedance Specification						
Rt	Termination resistance		–	50	–	Ω
M-LVDS AC Test Parameters Specifications						
VTrip	Measuring/trip point for data path		–	Cross point	–	V
Rent	Resistance for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	2K	–	Ω
Cent	Capacitive loading for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	5	–	pF

8.8.3.2. AC Switching Characteristics

Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, $V_{DDI} = 2.375\text{ V}$

AC Switching Characteristics for Receiver (Input Buffers)

Table 91 • M-LVDS AC Switching Characteristics for Receiver (Input Buffers)

Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case V_{DDI}

	On-Die Termination (ODT)	t_{PY}		Units
		Speed Grade		
		-1	Std	
M-LVDS (for MSIO I/O Bank)	None	2.738	3.221	ns
	100	2.735	3.218	ns
M-LVDS (for MSIOD I/O Bank)	None	2.495	2.934	ns
	100	2.495	2.935	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Table 92 • M-LVDS AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case V_{DDI}

	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}		t_{LZ}		Units
	Speed Grade										
	-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
M-LVDS (for MSIO I/O Bank)	2.258	2.656	2.348	2.762	2.334	2.746	2.123	2.497	2.125	2.5	ns

8.8.4 Mini-LVDS

Mini-LVDS is an unidirectional interface from the timing controller to the column drivers and is designed to the Texas Instruments Standard SLDA007A.

8.8.4.1 Mini-LVDS Minimum and Maximum Input and Output Levels

Table 93 • Mini-LVDS DC Voltage Specification

Symbols	Parameters	Conditions	Min	Typ	Max	Units
Recommended DC Operating Conditions						
V_{DDI}	Supply voltage		2.375	2.5	2.625	V
Mini-LVDS DC Input Voltage Specification						
V_I	DC Input voltage		0	–	2.925	V
Mini-LVDS DC Output Voltage Specification						
V_{OH}	DC output logic High		1.25	1.425	1.6	V
V_{OL}	DC output logic Low		0.9	1.075	1.25	V
Mini-LVDS Differential Voltage Specification						
V_{OD}	Differential output voltage swing		300	–	600	mV
V_{OCM}	Output common mode voltage		1	–	1.4	V
V_{ICM}	Input common mode voltage		0.3	–	1.2	V
V_{ID}	Input differential voltage		100	–	600	mV

Table 94 • Mini-LVDS AC Specifications

Symbols	Parameters	Conditions	Min	Typ	Max	Units
Mini-LVDS Minimum and Maximum AC Switching Speed						
Dmax	Maximum data rate (for MSIO I/O Bank)	AC loading: 2 pF / 100 Ω differential load	–	–	520	Mbps
Dmax	Maximum data rate (for MSIOD I/O Bank)	AC loading: 2 pF / 100 Ω differential load	–	–	700	Mbps
Mini-LVDS Impedance Specification						
Rt	Termination resistance		–	100	–	Ω
Mini-LVDS AC Test Parameters Specifications						
VTrip	Measuring/trip point for data path		–	Cross point	–	V
Rent	Resistance for enable path (t_{ZH} , t_{ZL} , t_{HZ} , t_{LZ})		–	2K	–	Ω
Cent	Capacitive loading for enable path (t_{ZH} , t_{ZL} , t_{HZ} , t_{LZ})		–	5	–	pF

8.8.4.2 AC Switching Characteristics

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, VDD = 1.14 V, VDDI = 2.375 V

AC Switching Characteristics for Receiver (Input Buffers)

Table 95 • Mini-LVDS AC Switching Characteristics for Receiver (Input Buffers)

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, VDD = 1.14 V, Worst-Case VDDI

	On-Die Termination (ODT)	t_{PY}		Units
		Speed Grade		
		–1	Std	
Mini-LVDS (for MSIO I/O Bank)	None	2.855	3.359	ns
	100	2.85	3.353	ns
Mini-LVDS (for MSIOD I/O Bank)	None	2.602	3.061	ns
	100	2.597	3.055	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Table 96 • Mini-LVDS AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

 Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, VDD = 1.14 V, Worst-Case VDDI

	t_{DP}		t_{ZL}		t_{ZH}		t_{HZ}		t_{LZ}		Units
	Speed Grade										
	–1	Std	–1	Std	–1	Std	–1	Std	–1	Std	
Mini-LVDS (for MSIO I/O Bank)	2.097	2.467	2.308	2.715	2.296	2.701	1.964	2.31	1.949	2.293	ns
Mini-LVDS (for MSIOD I/O Bank)											
No pre-emphasis	1.614	1.899	1.562	1.837	1.553	1.826	1.593	1.874	1.578	1.856	ns
Min pre-emphasis	1.604	1.887	1.745	2.053	1.731	2.036	1.892	2.225	1.861	2.189	ns
Med pre-emphasis	1.521	1.79	1.753	2.062	1.737	2.043	1.9	2.235	1.868	2.197	ns
Max pre-emphasis	1.492	1.754	1.762	2.073	1.745	2.052	1.91	2.247	1.876	2.206	ns

8.8.5 RSDS

Reduced Swing Differential Signaling (RSDS) is similar to an LVDS high-speed interface using differential signaling. RSDS has a similar implementation to LVDS devices and is only intended for point-to-point applications.

8.8.5.1 Minimum and Maximum Input and Output Levels

Table 97 • RSDS DC Voltage Specification

Symbols	Parameters	Conditions	Min	Typ	Max	Units
Recommended DC Operating Conditions						
VDDI	Supply voltage		2.375	2.5	2.625	V
RSDS DC Input Voltage Specification						
VI	DC input voltage		0	–	2.925	V
RSDS DC Output Voltage Specification						
VOH	DC output logic High		1.25	1.425	1.6	V
VOL	DC output logic Low		0.9	1.075	1.25	V
RSDS Differential Voltage Specification						
VOD	Differential output voltage swing		100	–	600	mV
VOCM	Output common mode voltage		0.5	–	1.5	V
VICM	Input common mode voltage		0.3	–	1.5	V
VID	Input differential voltage		100	–	600	mV

Table 98 • RSDS AC Specifications

Symbols	Parameters	Conditions	Min	Typ	Max	Units
RSDS Minimum and Maximum AC Switching Speed						
Dmax	Maximum data rate (for MSIO I/O Bank)	AC loading: 2 pF / 100 Ω differential load	–	–	520	Mbps
Dmax	Maximum data rate (for MSIOD I/O Bank)	AC loading: 2 pF / 100 Ω differential load	–	–	700	Mbps
RSDS Impedance Specification						
Rt	Termination resistance		–	100	–	Ω
RSDS AC Test Parameters Specifications						
VTrip	Measuring/trip point for data path		–	Cross point	–	V
Rent	Resistance for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	2K	–	Ω
Cent	Capacitive loading for enable path (t _{ZH} , t _{ZL} , t _{HZ} , t _{LZ})		–	5	–	pF

8.8.5.2. AC Switching Characteristics

Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, $V_{DDI} = 2.375\text{ V}$

AC Switching Characteristics for Receiver (Input Buffers)

Table 99 • RSDS AC Switching Characteristics for Receiver (Input Buffers)

Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case V_{DDI}

	On-Die Termination (ODT)	t_{PY}		Units
		Speed Grade		
		-1	Std	
RSDS (for MSIO I/O Bank)	None	2.855	3.359	ns
	100	2.85	3.353	ns
RSDS (for MSIOD I/O Bank)	None	2.602	3.061	ns
	100	2.597	3.055	ns

AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Table 100 • RSDS AC Switching Characteristics for Transmitter (Output and Tristate Buffers)

Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case V_{DDI}

	t_{DP}	t_{ZL}		t_{ZH}		t_{HZ}		t_{LZ}		Units	
	Speed Grade										
	-1	Std	-1	Std	-1	Std	-1	Std	-1		Std
RSDS (for MSIO I/O Bank)	2.097	2.467	2.303	2.709	2.291	2.695	1.961	2.307	1.947	2.29	ns
RSDS (for MSIOD I/O Bank)											
No pre-emphasis	1.614	1.899	1.559	1.834	1.55	1.823	1.59	1.87	1.575	1.852	ns
Min pre-emphasis	1.604	1.887	1.742	2.05	1.728	2.032	1.889	2.222	1.858	2.185	ns
Med pre-emphasis	1.521	1.79	1.753	2.062	1.737	2.043	1.9	2.235	1.868	2.197	ns
Max pre-emphasis	1.492	1.754	1.762	2.073	1.745	2.052	1.91	2.247	1.876	2.206	ns

8.8.6 LVPECL

Low-Voltage Positive Emitter-Coupled Logic (LVPECL) is another differential I/O standard. It requires that one data bit be carried through two signal lines. Similar to LVDS, two pins are needed. It also requires external resistor termination. IGLOO2 and SmartFusion2 SoC FPGAs support only LVPECL receivers and do not support LVPECL transmitters.

8.8.6.1 Minimum and Maximum Input and Output Levels

Table 101 • LVPECL DC Voltage Specification (Applicable to MSIO I/O Banks Only)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
Recommended DC Operating Conditions						
VDDI	Supply voltage		3.15	3.3	3.45	V
LVPECL DC Input Voltage Specification						
V _I	DC input voltage		0	–	3.45	V
LVPECL Differential Voltage Specification						
V _{ICM}	Input common mode voltage		0.3		2.8	V
V _{DIFF}	Input differential voltage		100	300	1,000	mV

Table 102 • LVPECL Minimum and Maximum AC Switching Speeds (Applicable to MSIO I/O Banks Only)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
LVPECL AC Specifications						
Dmax	Maximum data rate (for MSIO I/O Bank)		–	–	900	Mbps

8.8.6.2 AC Switching Characteristics

Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, $V_{DDI} = 2.375\text{ V}$

AC Switching Characteristics for Receiver (Input Buffers)

Table 103 • LVPECL Receiver Characteristics

Worst-Case Commercial Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$, Worst-Case VDDI

	On-Die Termination (ODT)	t_{PY}		Units
		Speed Grade		
		-1	Std	
LVPECL (for MSIO I/O Bank)	None	2.572	3.025	ns
	100	2.569	3.023	ns

8.9 I/O Register Specifications

8.9.1 Input Register

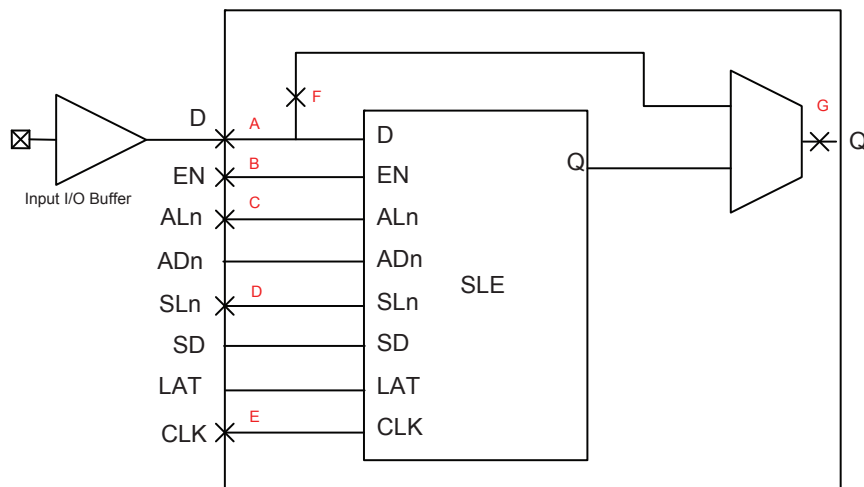


Figure 6 • Timing Model for Input Register

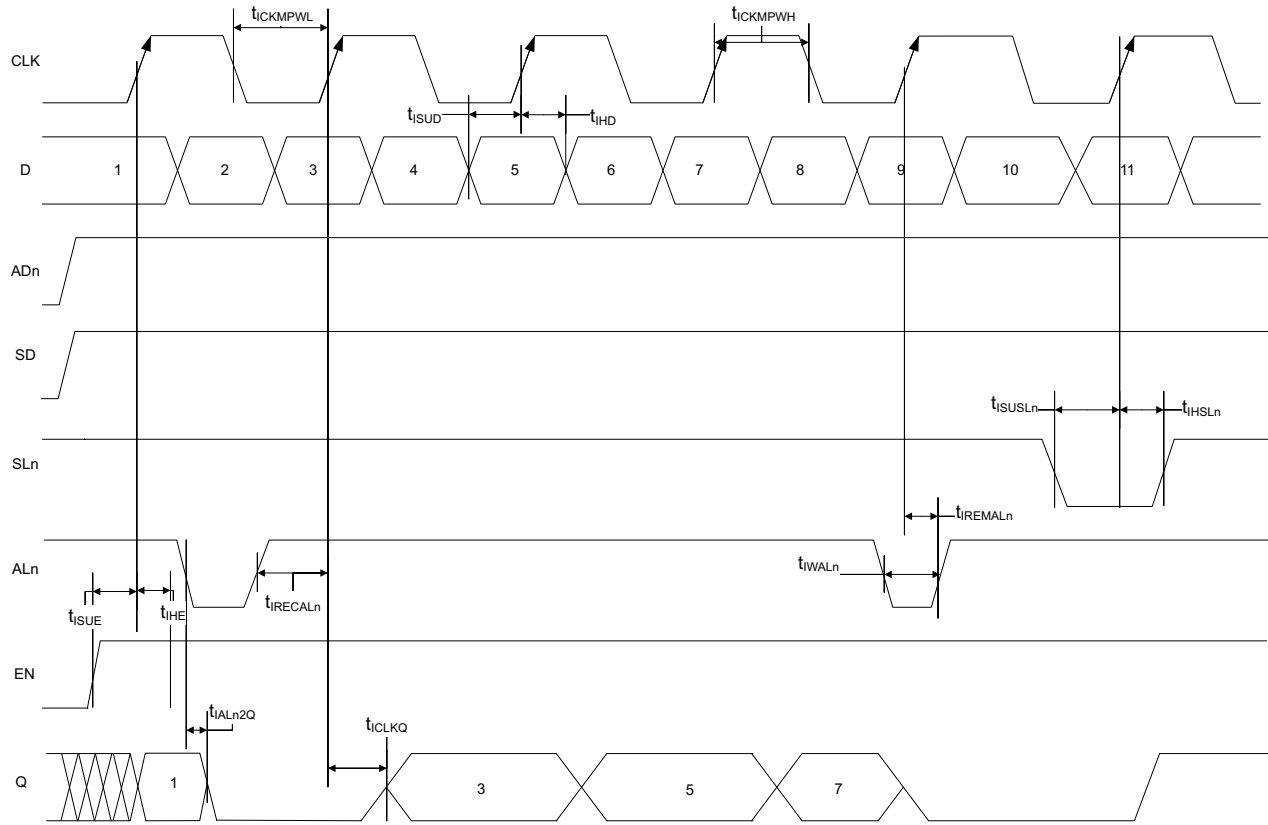


Figure 7 • I/O Register Input Timing Diagram

Table 104 • Input Data Register Propagation Delays
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Measuring Nodes (from, to)*	Speed Grade		Units
			-1	Std	
t_{IBYP}	Bypass Delay of the Input Register	F,G	0.353	0.415	ns
t_{ICLKQ}	Clock-to-Q of the Input Register	E,G	0.16	0.188	ns
t_{ISUD}	Data Setup Time for the Input Register	A, E	0.357	0.421	ns
t_{IHD}	Data Hold Time for the Input Register	A, E	0	0	ns
t_{ISUE}	Enable Setup Time for the Input Register	B, E	0.46	0.542	ns
t_{IHE}	Enable Hold Time for the Input Register	B, E	0	0	ns
t_{ISUSL}	Synchronous Load Setup Time for the Input Register	D, E	0.46	0.542	ns
t_{IHSL}	Synchronous Load Hold Time for the Input Register	D, E	0	0	ns
$t_{IUALn2Q}$	Asynchronous Clear-to-Q of the Input Register ($ADn=1$)	C, G	0.625	0.735	ns
	Asynchronous Preset-to-Q of the Input Register ($ADn=0$)	C, G	0.587	0.69	ns
$t_{IREMALn}$	Asynchronous Load Removal Time for the Input Register	C, E	0	0	ns

Note: *For the derating values at specific junction temperature and voltage supply levels, refer to Table 15 on page 21 for derating values.

Table 104 • Input Data Register Propagation Delays (continued)

Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Measuring Nodes (from, to)*	Speed Grade		Units
			-1	Std	
$t_{IRECALn}$	Asynchronous Load Recovery Time for the Input Register	C, E	0.074	0.087	ns
t_{IWALn}	Asynchronous Load Minimum Pulse Width for the Input Register	C, C	0.304	0.357	ns
$t_{iCKMPWH}$	Clock Minimum Pulse Width High for the Input Register	E, E	0.075	0.088	ns
$t_{iCKMPWL}$	Clock Minimum Pulse Width Low for the Input Register	E, E	0.159	0.187	ns

Note: *For the derating values at specific junction temperature and voltage supply levels, refer to Table 15 on page 21 for derating values.

8.9.2 Output/Enable Register

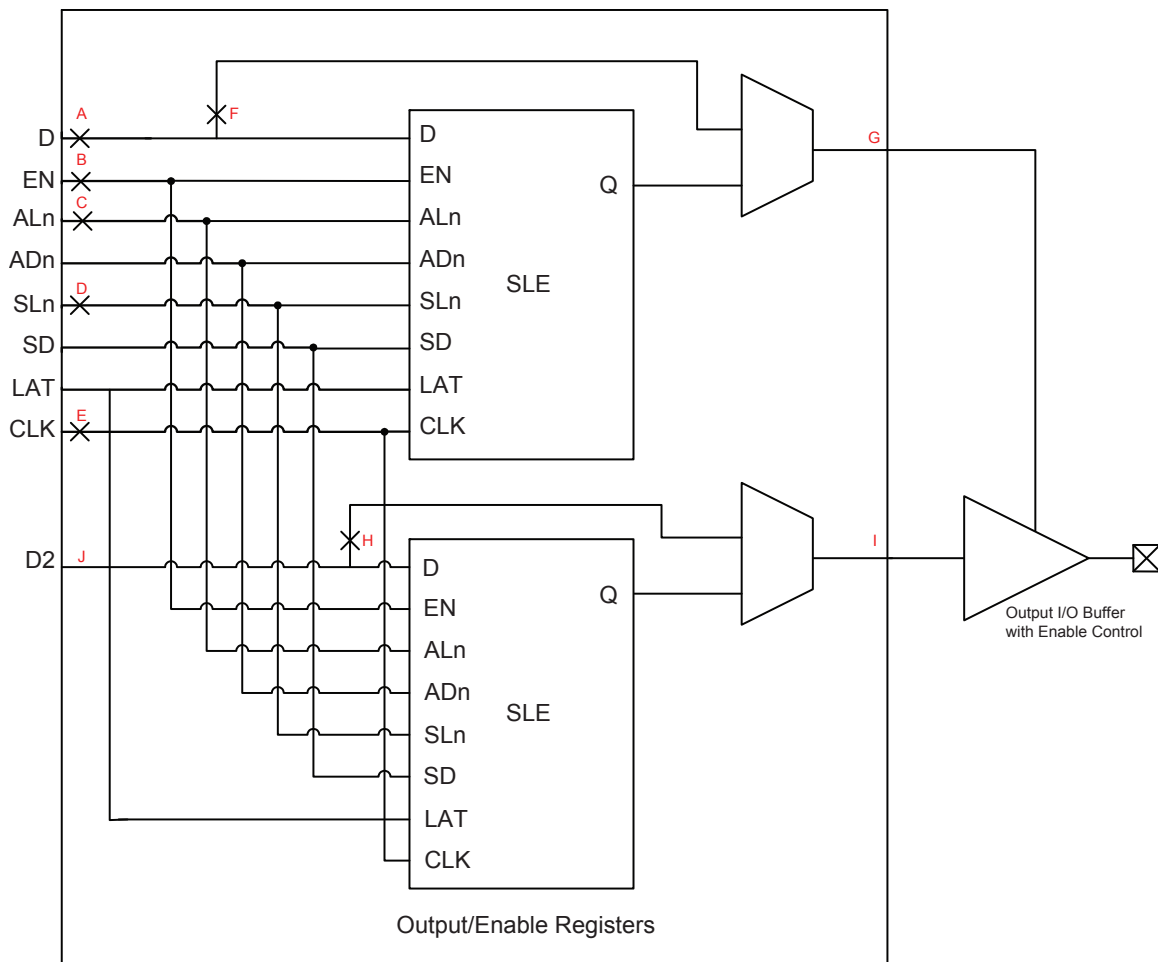


Figure 8 • Timing Model for Output/Enable Register

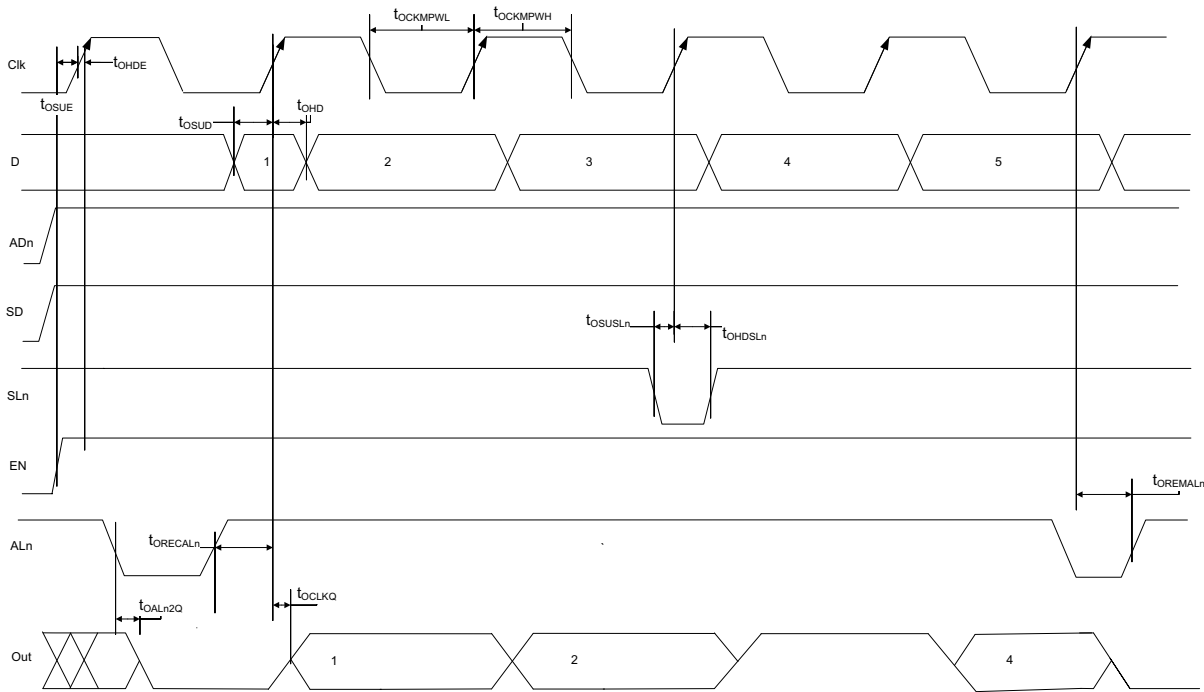


Figure 9 • I/O Register Output Timing Diagram

Table 105 • Output/Enable Data Register Propagation Delays
 Worst Commercial-Case Conditions: $T_j = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Measuring Nodes (from, to)*	Speed Grade		Units
			-1	Std	
t_{OBYP}	Bypass Delay of the Output/Enable Register	F, G or H, I	0.353	0.415	ns
t_{OCLKQ}	Clock-to-Q of the Output/Enable Register	E, G or E, I	0.263	0.309	ns
t_{OSUD}	Data Setup Time for the Output/Enable Register	A, E or J, E	0.19	0.223	ns
t_{OHD}	Data Hold Time for the Output/Enable Register	A, E or J, E	0	0	ns
t_{OSUE}	Enable Setup Time for the Output/Enable Register	B, E	0.419	0.493	ns
t_{OHE}	Enable Hold Time for the Output/Enable Register	B, E	0	0	ns
t_{OSUSL}	Synchronous Load Setup Time for the Output/Enable Register	D, E	0.196	0.231	ns
t_{OHSL}	Synchronous Load Hold Time for the Output/Enable Register	D, E	0	0	ns
t_{OALn2Q}	Asynchronous Clear-to-Q of the Output/Enable Register ($AD_n = 1$)	C, G or C, I	0.505	0.594	ns
	Asynchronous Preset-to-Q of the Output/Enable Register ($AD_n = 0$)	C, G or C, I	0.528	0.621	ns
$t_{OREMALn}$	Asynchronous Load Removal Time for the Output/Enable Register	C, E	0	0	ns
$t_{ORECALn}$	Asynchronous Load Recovery Time for the Output/Enable Register	C, E	0.034	0.04	ns
t_{OWALn}	Asynchronous Load Minimum Pulse Width for the Output/Enable Register	C, C	0.304	0.357	ns

Note: *For the derating values at specific junction temperature and voltage supply levels, refer to Table 15 on page 21 for derating values.

Table 105 • Output/Enable Data Register Propagation Delays (continued)

Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Measuring Nodes (from, to)*	Speed Grade		Units
			-1	Std	
t_{OCLKMPWH}	Clock Minimum Pulse Width High for the Output/Enable Register	E, E	0.075	0.088	ns
t_{OCLKMPWL}	Clock Minimum Pulse Width Low for the Output/Enable Register	E, E	0.159	0.187	ns

Note: *For the derating values at specific junction temperature and voltage supply levels, refer to Table 15 on page 21 for derating values.

8.10 DDR Module Specification

8.10.1 Input DDR Module

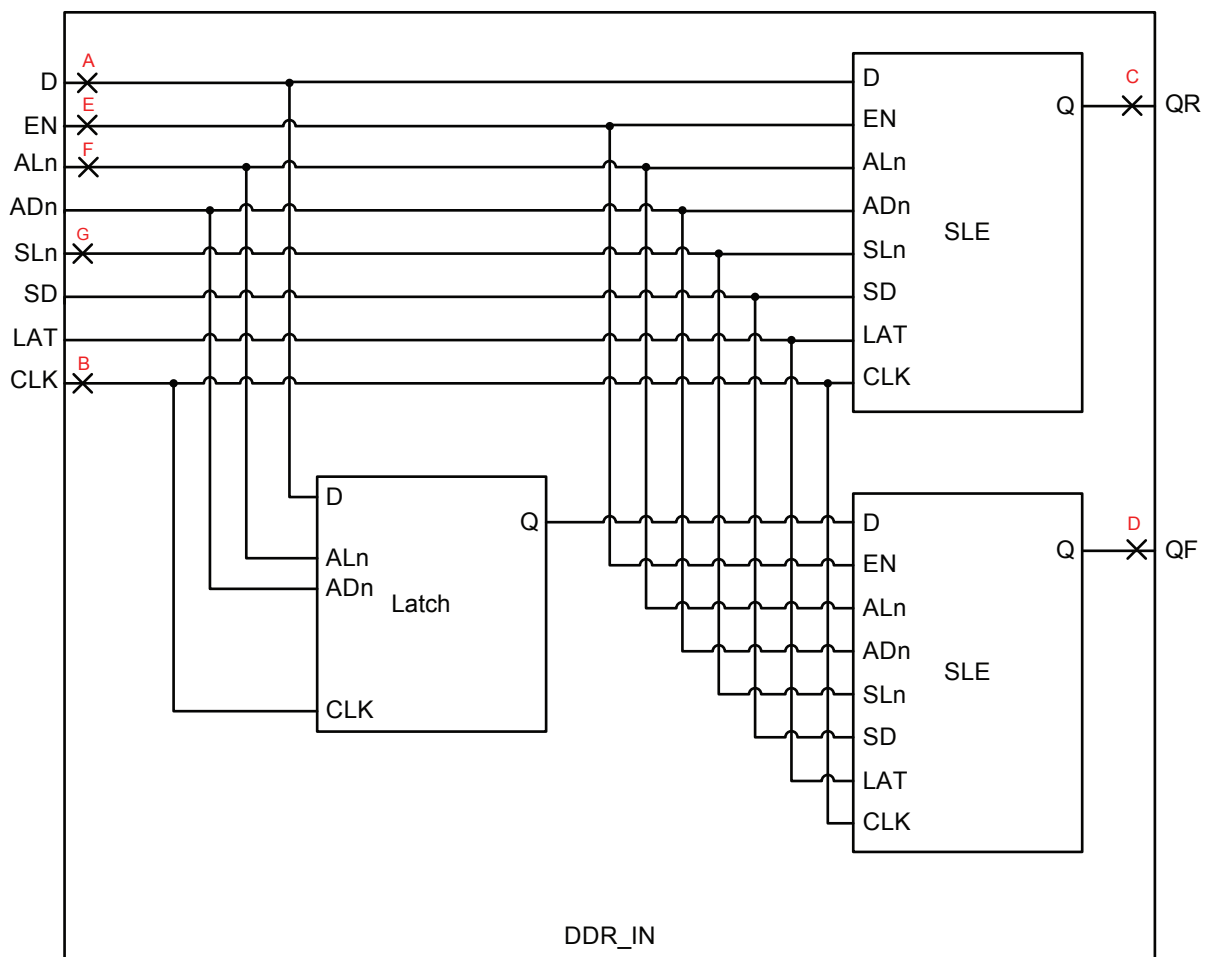


Figure 10 • Input DDR Module

8.10.2 Input DDR Timing Diagram

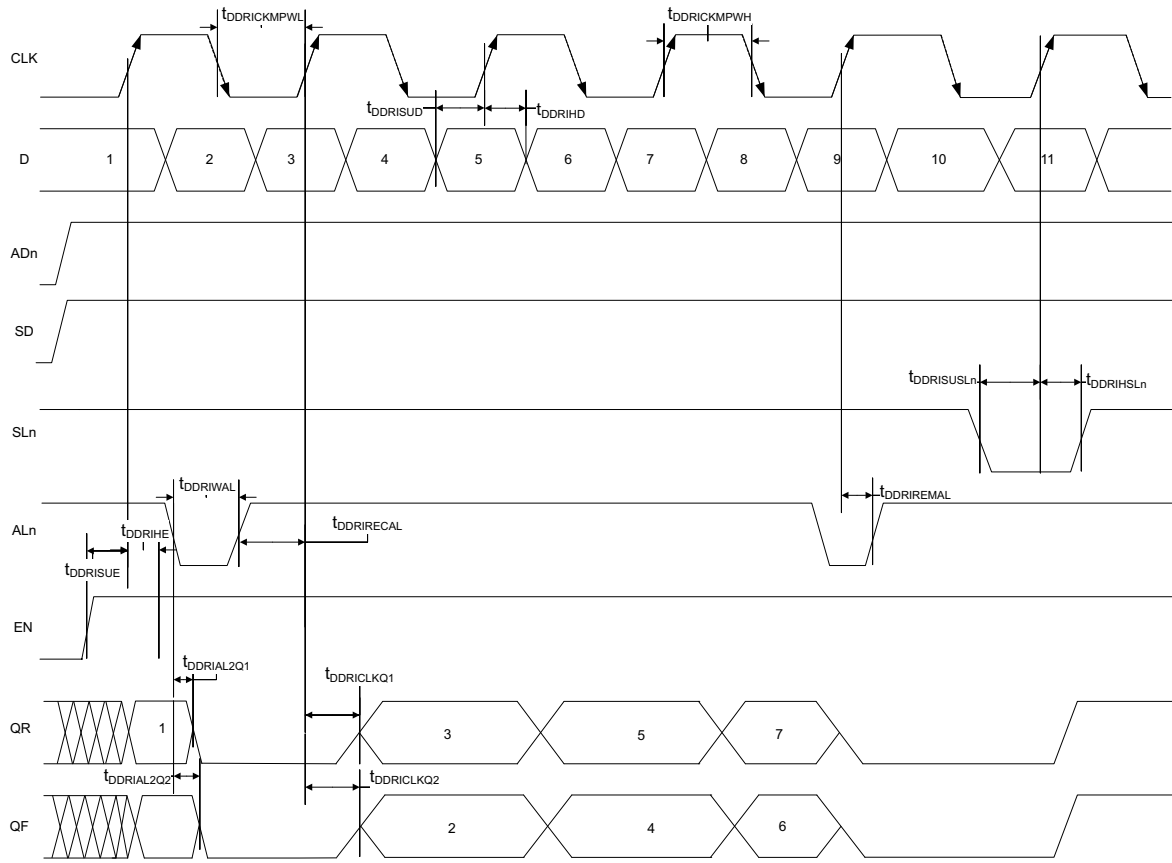


Figure 11 • Input DDR Timing Diagram

8.10.3 Timing Characteristics

Table 106 • Input DDR Propagation Delays
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Measuring Nodes (from, to)	Speed Grade		Units
			-1	Std	
t_{DDRICKQ1}	Clock-to-Out Out_QR for Input DDR	B,C	0.16	0.188	ns
t_{DDRICKQ2}	Clock-to-Out Out_QF for Input DDR	B,D	0.166	0.195	ns
t_{DDRISUD}	Data Setup for Input DDR	A,B	0.357	0.421	ns
t_{DDRIHD}	Data Hold for Input DDR	A,B	0	0	ns
t_{DDRISUE}	Enable Setup for Input DDR	E,B	0.46	0.542	ns
t_{DDRIHE}	Enable Hold for Input DDR	E,B	0	0	ns
t_{DDRISUSL_n}	Synchronous Load Setup for Input DDR	G,B	0.46	0.542	ns
t_{DDRIHSL_n}	Synchronous Load Hold for Input DDR	G,B	0	0	ns
$t_{\text{DDRIAL2Q1}}$	Asynchronous Load-to-Out QR for Input DDR	F,C	0.587	0.69	ns
$t_{\text{DDRIAL2Q2}}$	Asynchronous Load-to-Out QF for Input DDR	F,D	0.541	0.636	ns
$t_{\text{DDRIREMAL}}$	Asynchronous Load Removal time for Input DDR	F,B	0	0	ns
$t_{\text{DDRIRECAL}}$	Asynchronous Load Recovery time for Input DDR	F,B	0.074	0.087	ns
t_{DDRIWAL}	Asynchronous Load Minimum Pulse Width for Input DDR	F,F	0.304	0.357	ns
$t_{\text{DDRICKMPWH}}$	Clock Minimum Pulse Width High for Input DDR	B,B	0.075	0.088	ns
$t_{\text{DDRICKMPWL}}$	Clock Minimum Pulse Width Low for Input DDR	B,B	0.159	0.187	ns

8.10.4 Output DDR Module

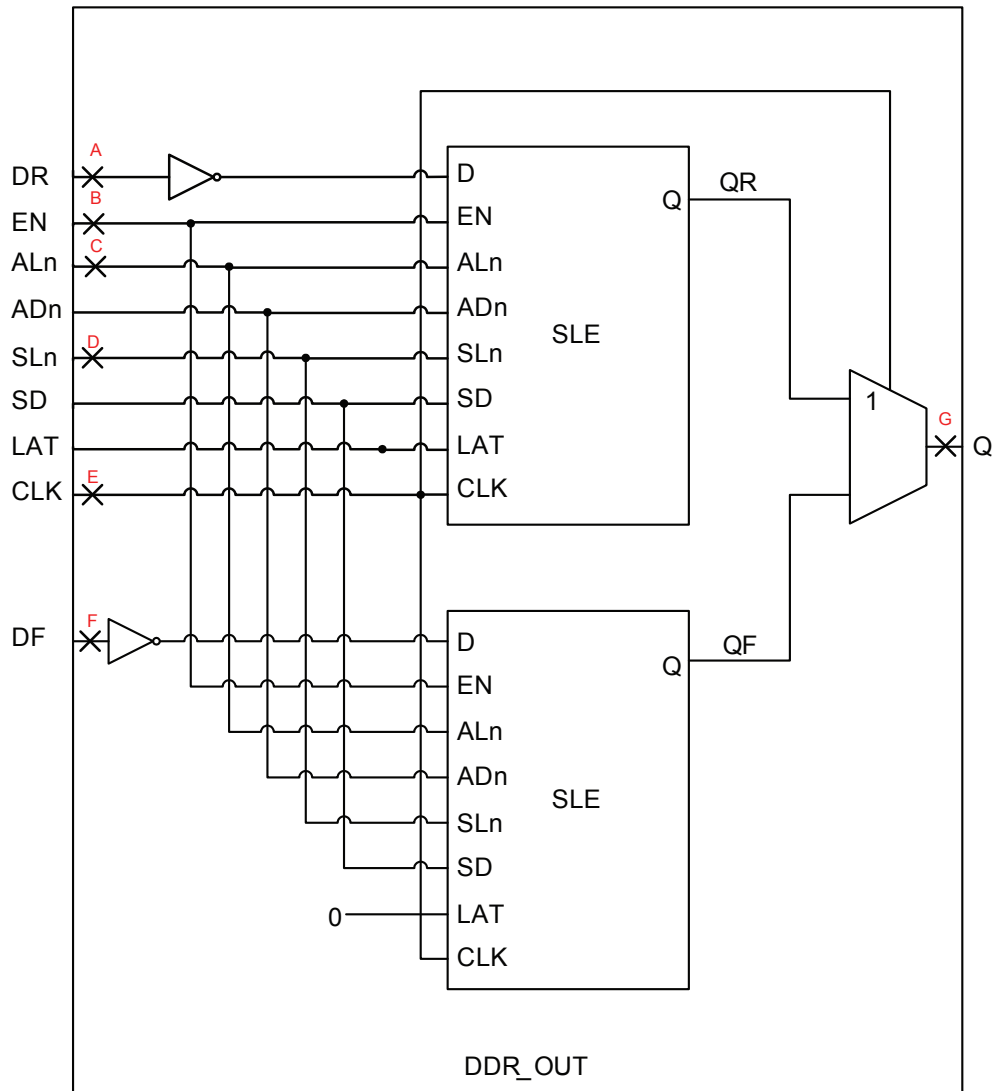


Figure 12 • Output DDR Module

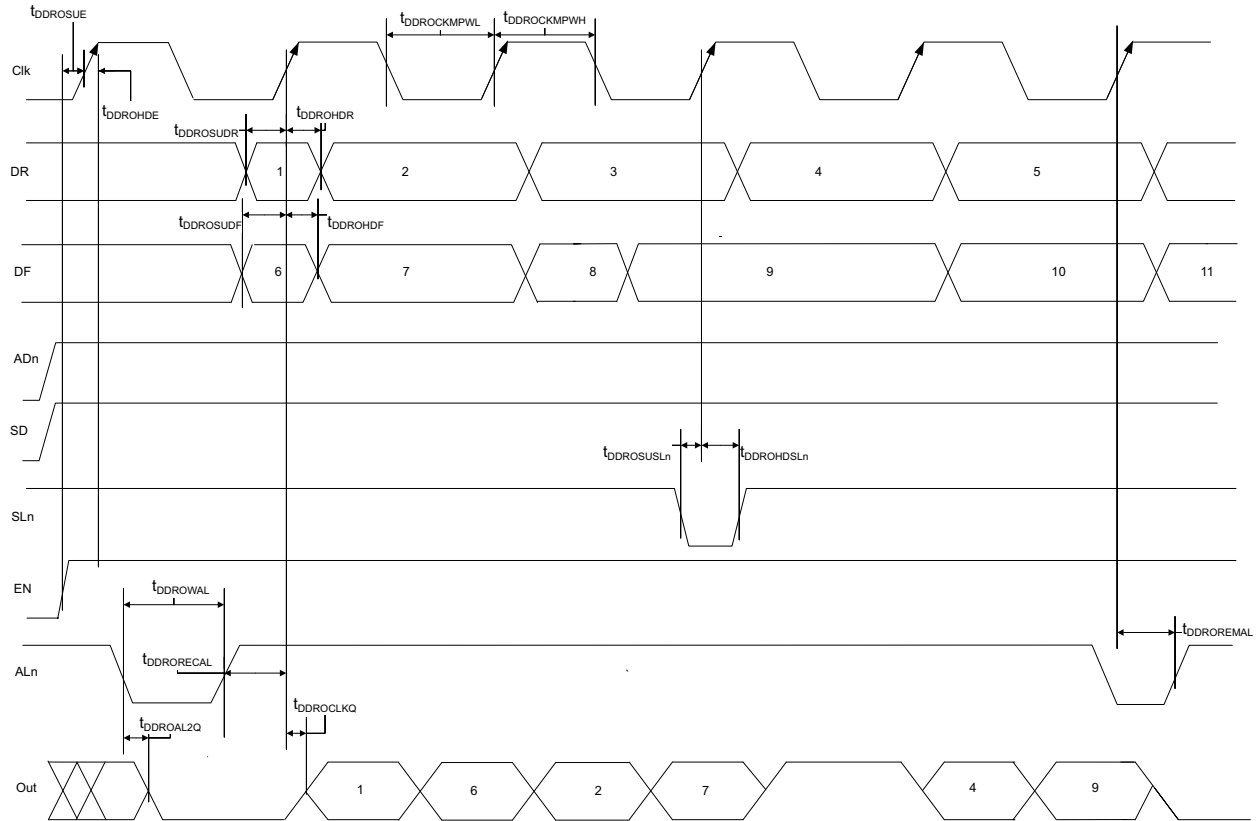


Figure 13 • Output DDR Timing Diagram

8.10.5 Timing Characteristics

Table 107 • Output DDR Propagation Delays
 Worst Commercial-Case Conditions: T_J = 85°C, VDD = 1.14 V

Parameter	Description	Measuring Nodes (from, to)	Speed Grade		Units
			-1	Std	
t _{DDROCLKQ}	Clock-to-Out of DDR for Output DDR	E,G	0.263	0.309	ns
t _{DDROSUDF}	Data_F Data Setup for Output DDR	F,E	0.143	0.168	ns
t _{DDROSUDR}	Data_R Data Setup for Output DDR	A,E	0.19	0.223	ns
t _{DDROHDF}	Data_F Data Hold for Output DDR	F,E	0	0	ns
t _{DDROHDR}	Data_R Data Hold for Output DDR	A,E	0	0	ns
t _{DDROSUE}	Enable Setup for Input DDR	B,E	0.419	0.493	ns
t _{DDROHE}	Enable Hold for Input DDR	B,E	0	0	ns
t _{DDROSUSL_n}	Synchronous Load Setup for Input DDR	D,E	0.196	0.231	ns
t _{DDROHSL_n}	Synchronous Load Hold for Input DDR	D,E	0	0	ns
t _{DDROAL2Q}	Asynchronous Load-to-Out for Output DDR	C,G	0.528	0.621	ns
t _{DDROREMA}	Asynchronous Load Removal time for Output DDR	C,E	0	0	ns
t _{DDRORECA}	Asynchronous Load Recovery time for Output DDR	C,E	0.034	0.04	ns
t _{DDROWAL}	Asynchronous Load Minimum Pulse Width for Output DDR	C,C	0.304	0.357	ns
t _{DDROCKMPWH}	Clock Minimum Pulse Width High for the Output DDR	E,E	0.075	0.088	ns
t _{DDROCKMPWL}	Clock Minimum Pulse Width Low for the Output DDR	E,E	0.159	0.187	ns

9. Logic Element Specifications

9.1 4-input LUT (LUT-4)

The IGLOO2 and SmartFusion2 SoC FPGAs offer a fully permutable 4-input LUT. In this section, timing characteristics are presented for a sample of the library. For more details, refer to the *SmartFusion2 and IGLOO2 Macro Library Guide*.

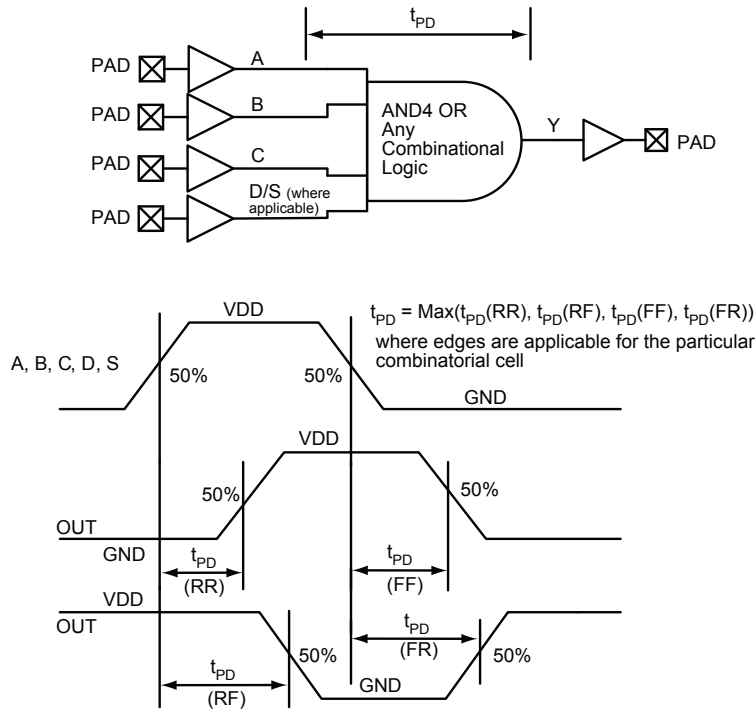


Figure 14 • LUT-4

9.1.1 Timing Characteristics

Table 108 • Combinatorial Cell Propagation Delays
Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Combinatorial Cell	Equation	Parameter	Speed Grade		Units
			-1	Std	
INV	$Y = !A$	t_{PD}	0.1	0.118	ns
AND2	$Y = A \cdot B$	t_{PD}	0.164	0.193	ns
NAND2	$Y = !(A \cdot B)$	t_{PD}	0.147	0.173	ns
OR2	$Y = A + B$	t_{PD}	0.164	0.193	ns
NOR2	$Y = !(A + B)$	t_{PD}	0.147	0.173	ns
XOR2	$Y = A \oplus B$	t_{PD}	0.164	0.193	ns
XOR3	$Y = A \oplus B \oplus C$	t_{PD}	0.225	0.265	ns
AND3	$Y = A \cdot B \cdot C$	t_{PD}	0.209	0.246	ns
AND4	$Y = A \cdot B \cdot C \cdot D$	t_{PD}	0.287	0.338	ns

9.2 Sequential Module

IGLOO2 and SmartFusion2 SoC FPGAs offer a separate flip-flop which can be used independently from the LUT. The flip-flop can be configured as a register or a latch and has a data input and optional enable, synchronous load (clear or preset), and asynchronous load (clear or preset), and asynchronous load (clear or preset).

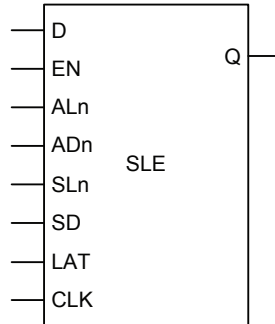


Figure 15 • Sequential Module

Figure 16 shows a configuration with SD = 0 (synchronous clear) and ADn = 1 (asynchronous clear) for a flip-flop (LAT = 0).

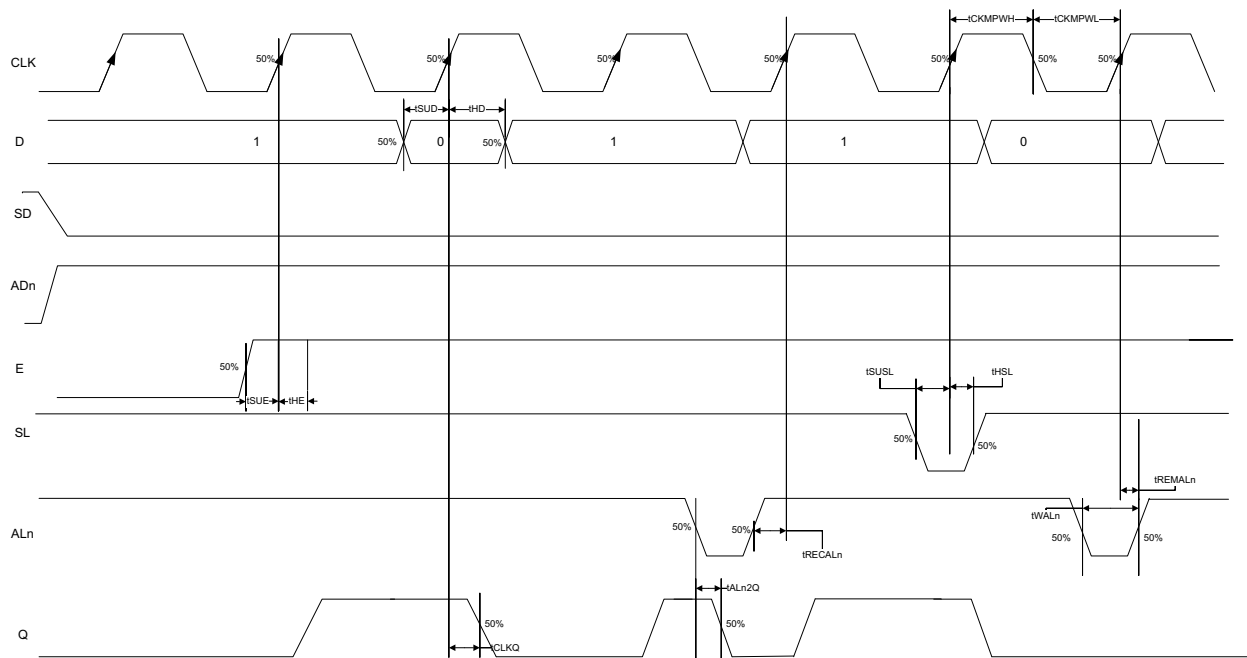


Figure 16 • Sequential Module Timing Diagram

9.2.1 Timing Characteristics

Table 109 • Register Delays

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade		Units
		-1	Std	
t_{CLKQ}	Clock-to-Q of the Core register	0.108	0.127	ns
t_{SUD}	Data Setup Time for the Core register	0.254	0.298	ns
t_{HD}	Data Hold Time for the Core register	0	0	ns
t_{SUE}	Enable Setup Time for the Core register	0.335	0.394	ns
t_{HE}	Enable Hold Time for the Core register	0	0	ns
t_{SUSL}	Synchronous Load Setup Time for the Core register	0.335	0.394	ns
t_{HSL}	Synchronous Load Hold Time for the Core register	0	0	ns
t_{ALn2Q}	Asynchronous Clear-to-Q of the Core register ($AD_n = 1$)	0.473	0.556	ns
	Asynchronous Preset-to-Q of the Core register ($AD_n = 0$)	0.451	0.531	ns
$t_{\text{REMA}n}$	Asynchronous Load Removal Time for the Core register	0	0	ns
$t_{\text{RECA}n}$	Asynchronous Load Recovery Time for the Core register	0.353	0.415	ns
$t_{\text{WAL}n}$	Asynchronous Load Minimum Pulse Width for the Core register	0.266	0.313	ns
t_{CKMPWH}	Clock Minimum Pulse Width High for the Core register	0.065	0.077	ns
t_{CKMPWL}	Clock Minimum Pulse Width Low for the Core register	0.139	0.164	ns

10. Global Resource Characteristics

The IGLOO2 and SmartFusion2 SoC FPGA devices offer a powerful, low skew global routing network which provides an effective clock distribution throughout the FPGA fabric. Refer to the [UG0445: IGLOO2 FPGA and SmartFusion2 SoC FPGA Fabric User Guide](#) for the positions of various global routing resources.

Table 110 • 150 Device Global Resource

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{RCKL}	Input Low Delay for Global Clock	0.83	0.911	0.831	0.913	ns
t_{RCKH}	Input High Delay for Global Clock	1.457	1.588	1.715	1.869	ns
t_{RCKSW}	Maximum Skew for Global Clock	–	0.131	–	0.154	ns

Table 111 • 090 Device Global Resource
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{RCKL}	Input Low Delay for Global Clock	0.835	0.888	0.833	0.886	ns
Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{RCKH}	Input High Delay for Global Clock	1.405	1.489	1.654	1.752	ns
t_{RCKSW}	Maximum Skew for Global Clock	–	0.084	–	0.098	ns

Table 112 • 050 Device Global Resource
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{RCKL}	Input Low Delay for Global Clock	0.827	0.897	0.826	0.896	ns
t_{RCKH}	Input High Delay for Global Clock	1.419	1.53	1.671	1.8	ns
t_{RCKSW}	Maximum Skew for Global Clock	–	0.111	–	0.129	ns

Table 113 • 025 Device Global Resource
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{RCKL}	Input Low Delay for Global Clock	0.747	0.799	0.745	0.797	ns
t_{RCKH}	Input High Delay for Global Clock	1.294	1.378	1.522	1.621	ns
t_{RCKSW}	Maximum Skew for Global Clock	–	0.084	–	0.099	ns

Table 114 • 010 Device Global Resource
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{RCKL}	Input Low Delay for Global Clock	0.626	0.669	0.627	0.668	ns
t_{RCKH}	Input High Delay for Global Clock	1.112	1.182	1.308	1.393	ns
t_{RCKSW}	Maximum Skew for Global Clock	–	0.07	–	0.085	ns

Table 115 • 005 Device Global Resource
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{RCKL}	Input Low Delay for Global Clock	0.625	0.66	0.628	0.66	ns
t_{RCKH}	Input High Delay for Global Clock	1.126	1.187	1.325	1.397	ns
t_{RCKSW}	Maximum Skew for Global Clock	–	0.061	–	0.072	ns

11. FPGA Fabric SRAM

Refer to the *UG0445: IGLOO2 FPGA and SmartFusion2 SoC FPGA Fabric User Guide* for more information.

11.1 FPGA Fabric Large SRAM (LSRAM)

Table 116 • RAM1K18 – Dual-Port Mode for Depth × Width Configuration 1Kx18
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{CY}	Clock period	2.5	–	2.941	–	ns
$t_{CLKMPWH}$	Clock minimum pulse width High	1.125	–	1.323	–	ns
$t_{CLKMPWL}$	Clock minimum pulse width Low	1.125	–	1.323	–	ns
t_{PLCY}	Pipelined clock period	2.5	–	2.941	–	ns
$t_{PLCLKMPWH}$	Pipelined clock minimum pulse width High	1.125	–	1.323	–	ns
$t_{PLCLKMPWL}$	Pipelined clock minimum pulse width Low	1.125	–	1.323	–	ns
t_{CLK2Q}	Read access time with pipeline register	–	0.334	–	0.393	ns
	Read access time without pipeline register	–	2.273	–	2.674	ns
	Access time with feed-through write timing	–	1.529	–	1.799	ns
t_{ADDRSU}	Address setup time	0.441	–	0.519	–	ns
t_{ADDRHD}	Address hold time	0.274	–	0.322	–	ns
t_{DSU}	Data setup time	0.341	–	0.401	–	ns
t_{DHD}	Data hold time	0.107	–	0.126	–	ns
t_{BLKSU}	Block select setup time	0.207	–	0.244	–	ns
t_{BLKHD}	Block select hold time	0.216	–	0.254	–	ns
t_{BLK2Q}	Block select to out disable time (when pipelined register is disabled)	–	1.529	–	1.799	ns
t_{BLKMPW}	Block select minimum pulse width	0.186	–	0.219	–	ns
t_{RDESU}	Read enable setup time	0.449	–	0.528	–	ns
t_{RDEHD}	Read enable hold time	0.167	–	0.197	–	ns
$t_{RDPLESU}$	Pipelined read enable setup time (A_DOUT_EN, B_DOUT_EN)	0.248	–	0.291	–	ns

Table 116 • RAM1K18 – Dual-Port Mode for Depth × Width Configuration 1Kx18 (continued)

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
$t_{RDPLEHD}$	Pipelined read enable hold time (A_DOUT_EN, B_DOUT_EN)	0.102	–	0.12	–	ns
t_{R2Q}	Asynchronous reset to output propagation delay	–	1.506	–	1.772	ns
t_{RSTREM}	Asynchronous reset removal time	0.506	–	0.595	–	ns
t_{RSTREC}	Asynchronous reset recovery time	0.004	–	0.005	–	ns
t_{RSTMPW}	Asynchronous reset minimum pulse width	0.301	–	0.354	–	ns
$t_{PLRSTREM}$	Pipelined register asynchronous reset removal time	–0.279	–	–0.328	–	ns
$t_{PLRSTREC}$	Pipelined register asynchronous reset recovery time	0.327	–	0.385	–	ns
$t_{PLRSTMPW}$	Pipelined register asynchronous reset minimum pulse width	0.282	–	0.332	–	ns
t_{SRSTSU}	Synchronous reset setup time	0.226	–	0.265	–	ns
t_{SRSTHD}	Synchronous reset hold time	0.036	–	0.043	–	ns
t_{WESU}	Write enable setup time	0.39	–	0.458	–	ns
t_{WEHD}	Write enable hold time	0.242	–	0.285	–	ns
f_{MAX}	Maximum frequency	–	400	–	340	MHz

Table 117 • RAM1K18 – Dual-Port Mode for Depth × Width Configuration 2Kx9

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{CY}	Clock period	2.5	–	2.941	–	ns
$t_{CLKMPWH}$	Clock minimum pulse width High	1.125	–	1.323	–	ns
$t_{CLKMPWL}$	Clock minimum pulse width Low	1.125	–	1.323	–	ns
t_{PLCY}	Pipelined clock period	2.5	–	2.941	–	ns
$t_{PLCLKMPWH}$	Pipelined clock minimum pulse width High	1.125	–	1.323	–	ns
$t_{PLCLKMPWL}$	Pipelined clock minimum pulse width Low	1.125	–	1.323	–	ns
t_{CLK2Q}	Read access time with pipeline register	–	0.334	–	0.393	ns
	Read access time without pipeline register	–	2.273	–	2.674	ns
	Access time with feed-through write timing	–	1.529	–	1.799	ns
t_{ADDRSU}	Address setup time	0.475	–	0.559	–	ns
t_{ADDRHD}	Address hold time	0.274	–	0.322	–	ns
t_{DSU}	Data setup time	0.336	–	0.395	–	ns
t_{DHD}	Data hold time	0.082	–	0.096	–	ns
t_{BLKSU}	Block select setup time	0.207	–	0.244	–	ns
t_{BLKHD}	Block select hold time	0.216	–	0.254	–	ns
t_{BLK2Q}	Block select to out disable time (when pipelined register is disabled)	–	1.529	–	1.799	ns

Table 117 • RAM1K18 – Dual-Port Mode for Depth × Width Configuration 2Kx9 (continued)

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{BLKMPW}	Block select minimum pulse width	0.186	–	0.219	–	ns
t_{RDESU}	Read enable setup time	0.485	–	0.57	–	ns
t_{RDEHD}	Read enable hold time	0.071	–	0.083	–	ns
$t_{RDPLESU}$	Pipelined read enable setup time (A_DOUT_EN, B_DOUT_EN)	0.248	–	0.291	–	ns
$t_{RDPLEHD}$	Pipelined read enable hold time (A_DOUT_EN, B_DOUT_EN)	0.102	–	0.12	–	ns
t_{R2Q}	Asynchronous reset to output propagation delay	–	1.514	–	1.781	ns
t_{RSTREM}	Asynchronous reset removal time	0.506	–	0.595	–	ns
t_{RSTREC}	Asynchronous reset recovery time	0.004	–	0.005	–	ns
t_{RSTMPW}	Asynchronous reset minimum pulse width	0.301	–	0.354	–	ns
$t_{PLRSTREM}$	Pipelined register asynchronous reset removal time	–0.279	–	–0.328	–	ns
$t_{PLRSTREC}$	Pipelined register asynchronous reset recovery time	0.327	–	0.385	–	ns
$t_{PLRSTMPW}$	Pipelined register asynchronous reset minimum pulse width	0.282	–	0.332	–	ns
t_{SRSTSU}	Synchronous reset setup time	0.226	–	0.265	–	ns
t_{SRSTHD}	Synchronous reset hold time	0.036	–	0.043	–	ns
t_{WESU}	Write enable setup time	0.415	–	0.488	–	ns
t_{WEHD}	Write enable hold time	0.048	–	0.057	–	ns
f_{MAX}	Maximum frequency	–	400	–	340	MHz

Table 118 • RAM1K18 – Dual-Port Mode for Depth × Width Configuration 4Kx4

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{CY}	Clock period	2.5	–	2.941	–	ns
$t_{CLKMPWH}$	Clock minimum pulse width High	1.125	–	1.323	–	ns
$t_{CLKMPWL}$	Clock minimum pulse width Low	1.125	–	1.323	–	ns
t_{PLCY}	Pipelined clock period	2.5	–	2.941	–	ns
$t_{PLCLKMPWH}$	Pipelined clock minimum pulse width High	1.125	–	1.323	–	ns
$t_{PLCLKMPWL}$	Pipelined clock minimum pulse width Low	1.125	–	1.323	–	ns
t_{CLK2Q}	Read access time with pipeline register	–	0.323	–	0.38	ns
	Read access time without pipeline register	–	2.273	–	2.673	ns
	Access time with feed-through write timing	–	1.511	–	1.778	ns
t_{ADDRSU}	Address setup time	0.543	–	0.638	–	ns
t_{ADDRHD}	Address hold time	0.274	–	0.322	–	ns
t_{DSU}	Data setup time	0.334	–	0.393	–	ns

Table 118 • RAM1K18 – Dual-Port Mode for Depth × Width Configuration 4Kx4 (continued)
Worst Commercial-Case Conditions: T_J = 85°C, VDD = 1.14 V

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t _{DHD}	Data hold time	0.082	–	0.096	–	ns
t _{BLKSU}	Block select setup time	0.207	–	0.244	–	ns
t _{BLKHd}	Block select hold time	0.216	–	0.254	–	ns
t _{BLK2Q}	Block select to out disable time (when pipelined register is disabled)	–	1.511	–	1.778	ns
t _{BLKMPW}	Block select minimum pulse width	0.186	–	0.219	–	ns
t _{RDESU}	Read enable setup time	0.516	–	0.607	–	ns
t _{RDEHD}	Read enable hold time	0.071	–	0.083	–	ns
t _{RDPLESU}	Pipelined read enable setup time (A_DOUT_EN, B_DOUT_EN)	0.248	–	0.291	–	ns
t _{RDPLEHD}	Pipelined read enable hold time (A_DOUT_EN, B_DOUT_EN)	0.102	–	0.12	–	ns
t _{R2Q}	Asynchronous reset to output propagation delay	–	1.507	–	1.773	ns
t _{RSTREM}	Asynchronous reset removal time	0.506	–	0.595	–	ns
t _{RSTREC}	Asynchronous reset recovery time	0.004	–	0.005	–	ns
t _{RSTMPW}	Asynchronous reset minimum pulse width	0.301	–	0.354	–	ns
t _{PLRSTREM}	Pipelined register asynchronous reset removal time	–0.279	–	–0.328	–	ns
t _{PLRSTREC}	Pipelined register asynchronous reset recovery time	0.327	–	0.385	–	ns
t _{PLRSTMPW}	Pipelined register asynchronous reset minimum pulse width	0.282	–	0.332	–	ns
t _{SRSTSU}	Synchronous reset setup time	0.226	–	0.265	–	ns
t _{SRSTHD}	Synchronous reset hold time	0.036	–	0.043	–	ns
t _{WESU}	Write enable setup time	0.458	–	0.539	–	ns
t _{WEHD}	Write enable hold time	0.048	–	0.057	–	ns
f _{MAX}	Maximum frequency	–	400	–	340	MHz

Table 119 • RAM1K18 – Dual-Port Mode for Depth × Width Configuration 8Kx2
Worst Commercial-Case Conditions: T_J = 85°C, VDD = 1.14 V

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t _{CY}	Clock period	2.5	–	2.941	–	ns
t _{CLKMPWH}	Clock minimum pulse width High	1.125	–	1.323	–	ns
t _{CLKMPWL}	Clock minimum pulse width Low	1.125	–	1.323	–	ns
t _{PLCY}	Pipelined clock period	2.5	–	2.941	–	ns
t _{PLCLKMPWH}	Pipelined clock minimum pulse width High	1.125	–	1.323	–	ns
t _{PLCLKMPWL}	Pipelined clock minimum pulse width Low	1.125	–	1.323	–	ns

Table 119 • RAM1K18 – Dual-Port Mode for Depth × Width Configuration 8Kx2 (continued)

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{CLK2Q}	Read access time with pipeline register	–	0.32	–	0.377	ns
	Read access time without pipeline register	–	2.272	–	2.673	ns
	Access time with feed-through write timing	–	1.511	–	1.778	ns
t_{ADDRSU}	Address setup time	0.612	–	0.72	–	ns
t_{ADDRHD}	Address hold time	0.274	–	0.322	–	ns
t_{DSU}	Data setup time	0.33	–	0.388	–	ns
t_{DHD}	Data hold time	0.082	–	0.096	–	ns
t_{BLKSU}	Block select setup time	0.207	–	0.244	–	ns
t_{BLKHD}	Block select hold time	0.216	–	0.254	–	ns
t_{BLK2Q}	Block select to out disable time (when pipelined register is disabled)	–	1.511	–	1.778	ns
t_{BLKMPW}	Block select minimum pulse width	0.186	–	0.219	–	ns
t_{RDESU}	Read enable setup time	0.529	–	0.622	–	ns
t_{RDEHD}	Read enable hold time	0.071	–	0.083	–	ns
t_{RDPLESU}	Pipelined read enable setup time (A_DOUT_EN, B_DOUT_EN)	0.248	–	0.291	–	ns
t_{RDPLEHD}	Pipelined read enable hold time (A_DOUT_EN, B_DOUT_EN)	0.102	–	0.12	–	ns
t_{R2Q}	Asynchronous reset to output propagation delay	–	1.528	–	1.797	ns
t_{RSTREM}	Asynchronous reset removal time	0.506	–	0.595	–	ns
t_{RSTREC}	Asynchronous reset recovery time	0.004	–	0.005	–	ns
t_{RSTMPW}	Asynchronous reset minimum pulse width	0.301	–	0.354	–	ns
t_{PLRSTREM}	Pipelined register asynchronous reset removal time	–0.279	–	–0.328	–	ns
t_{PLRSTREC}	Pipelined register asynchronous reset recovery time	0.327	–	0.385	–	ns
t_{PLRSTMPW}	Pipelined register asynchronous reset minimum pulse width	0.282	–	0.332	–	ns
t_{SRSTSU}	Synchronous reset setup time	0.226	–	0.265	–	ns
t_{SRSTHD}	Synchronous reset hold time	0.036	–	0.043	–	ns
t_{WESU}	Write enable setup time	0.488	–	0.574	–	ns
t_{WEHD}	Write enable hold time	0.048	–	0.057	–	ns
f_{MAX}	Maximum frequency	–	400	–	340	MHz

Table 120 • RAM1K18 – Dual-Port Mode for Depth × Width Configuration 16Kx1
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{CY}	Clock period	2.5	–	2.941	–	ns
$t_{CLKMPWH}$	Clock minimum pulse width High	1.125	–	1.323	–	ns
$t_{CLKMPWL}$	Clock minimum pulse width Low	1.125	–	1.323	–	ns
t_{PLCY}	Pipelined clock period	2.5	–	2.941	–	ns
$t_{PLCLKMPWH}$	Pipelined clock minimum pulse width High	1.125	–	1.323	–	ns
$t_{PLCLKMPWL}$	Pipelined clock minimum pulse width Low	1.125	–	1.323	–	ns
t_{CLK2Q}	Read access time with pipeline register	–	0.32	–	0.377	ns
	Read access time without pipeline register	–	2.269	–	2.669	ns
	Access time with feed-through write timing	–	1.51	–	1.777	ns
t_{ADDRSU}	Address setup time	0.626	–	0.737	–	ns
t_{ADDRHD}	Address hold time	0.274	–	0.322	–	ns
t_{DSU}	Data setup time	0.322	–	0.378	–	ns
t_{DHD}	Data hold time	0.082	–	0.096	–	ns
t_{BLKSU}	Block select setup time	0.207	–	0.244	–	ns
t_{BLKHD}	Block select hold time	0.216	–	0.254	–	ns
t_{BLK2Q}	Block select to out disable time (when pipelined register is disabled)	–	1.51	–	1.777	ns
t_{BLKMPW}	Block select minimum pulse width	0.186	–	0.219	–	ns
t_{RDESU}	Read enable setup time	0.53	–	0.624	–	ns
t_{RDEHD}	Read enable hold time	0.071	–	0.083	–	ns
$t_{RDPLESU}$	Pipelined read enable setup time (A_DOUT_EN, B_DOUT_EN)	0.248	–	0.291	–	ns
$t_{RDPLEHD}$	Pipelined read enable hold time (A_DOUT_EN, B_DOUT_EN)	0.102	–	0.12	–	ns
t_{R2Q}	Asynchronous reset to output propagation delay	–	1.547	–	1.82	ns
t_{RSTREM}	Asynchronous reset removal time	0.506	–	0.595	–	ns
t_{RSTREC}	Asynchronous reset recovery time	0.004	–	0.005	–	ns
t_{RSTMPW}	Asynchronous reset minimum pulse width	0.301	–	0.354	–	ns
$t_{PLRSTREM}$	Pipelined register asynchronous reset removal time	–0.279	–	–0.328	–	ns
$t_{PLRSTREC}$	Pipelined register asynchronous reset recovery time	0.327	–	0.385	–	ns
$t_{PLRSTMPW}$	Pipelined register asynchronous reset minimum pulse width	0.282	–	0.332	–	ns
t_{SRSTSU}	Synchronous reset setup time	0.226	–	0.265	–	ns
t_{SRSTHD}	Synchronous reset hold time	0.036	–	0.043	–	ns
t_{WESU}	Write enable setup time	0.454	–	0.534	–	ns
t_{WEHD}	Write enable hold time	0.048	–	0.057	–	ns
f_{MAX}	Maximum frequency	–	400	–	340	MHz

Table 121 • RAM1K18 – Two-Port Mode for Depth × Width Configuration 512x36
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{CY}	Clock period	2.5	–	2.941	–	ns
$t_{CLKMPWH}$	Clock minimum pulse width High	1.125	–	1.323	–	ns
$t_{CLKMPWL}$	Clock minimum pulse width Low	1.125	–	1.323	–	ns
t_{PLCY}	Pipelined clock period	2.5	–	2.941	–	ns
$t_{PLCLKMPWH}$	Pipelined clock minimum pulse width High	1.125	–	1.323	–	ns
$t_{PLCLKMPWL}$	Pipelined clock minimum pulse width Low	1.125	–	1.323	–	ns
t_{CLK2Q}	Read access time with pipeline register	–	0.334	–	0.393	ns
	Read access time without pipeline register	–	2.25	–	2.647	ns
t_{ADDRSU}	Address setup time	0.313	–	0.368	–	ns
t_{ADDRHD}	Address hold time	0.274	–	0.322	–	ns
t_{DSU}	Data setup time	0.337	–	0.396	–	ns
t_{DHD}	Data hold time	0.111	–	0.13	–	ns
t_{BLKSU}	Block select setup time	0.207	–	0.244	–	ns
t_{BLKHD}	Block select hold time	0.201	–	0.237	–	ns
t_{BLK2Q}	Block select to out disable time (when pipelined register is disabled)	–	2.25	–	2.647	ns
t_{BLKMPW}	Block select minimum pulse width	0.186	–	0.219	–	ns
t_{RDESU}	Read enable setup time	0.449	–	0.528	–	ns
t_{RDEHD}	Read enable hold time	0.167	–	0.197	–	ns
$t_{RDPLESU}$	Pipelined read enable setup time (A_DOUT_EN, B_DOUT_EN)	0.248	–	0.291	–	ns
$t_{RDPLEHD}$	Pipelined read enable hold time (A_DOUT_EN, B_DOUT_EN)	0.102	–	0.12	–	ns
t_{R2Q}	Asynchronous reset to output propagation delay	–	1.506	–	1.772	ns
t_{RSTREM}	Asynchronous reset removal time	0.506	–	0.595	–	ns
t_{RSTREC}	Asynchronous reset recovery time	0.004	–	0.005	–	ns
t_{RSTMPW}	Asynchronous reset minimum pulse width	0.301	–	0.354	–	ns
$t_{PLRSTREM}$	Pipelined register asynchronous reset removal time	–0.279	–	–0.328	–	ns
$t_{PLRSTREC}$	Pipelined register asynchronous reset recovery time	0.327	–	0.385	–	ns
$t_{PLRSTMPW}$	Pipelined register asynchronous reset minimum pulse width	0.282	–	0.332	–	ns
t_{SRSTSU}	Synchronous reset setup time	0.226	–	0.265	–	ns
t_{SRSTHD}	Synchronous reset hold time	0.036	–	0.043	–	ns
t_{WESU}	Write enable setup time	0.39	–	0.458	–	ns
t_{WEHD}	Write enable hold time	0.242	–	0.285	–	ns
f_{MAX}	Maximum frequency	–	400	–	340	MHz

11.2. FPGA Fabric Micro SRAM (uSRAM)

Table 122 • uSRAM (RAM64x18) in 64x18 Mode
 Worst Commercial-Case Conditions: T_j = 85°C, VDD = 1.14 V

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t _{CY}	Read clock period	4	–	4	–	ns
t _{CLKMPWH}	Read clock minimum pulse width High	1.8	–	1.8	–	ns
t _{CLKMPWL}	Read clock minimum pulse width Low	1.8	–	1.8	–	ns
t _{PLCY}	Read pipeline clock period	4	–	4	–	ns
t _{PLCLKMPWH}	Read pipeline clock minimum pulse width High	1.8	–	1.8	–	ns
t _{PLCLKMPWL}	Read pipeline clock minimum pulse width Low	1.8	–	1.8	–	ns
t _{CLK2Q}	Read access time with pipeline register	–	0.266	–	0.313	ns
	Read access time without pipeline register	–	1.677	–	1.973	ns
t _{ADDRSU}	Read address setup time in synchronous mode	0.301	–	0.354	–	ns
	Read address setup time in asynchronous mode	1.856	–	2.184	–	ns
t _{ADDRHD}	Read address hold time in synchronous mode	0.091	–	0.107	–	ns
	Read address hold time in asynchronous mode	–0.778	–	–0.915	–	ns
t _{RDENSU}	Read enable setup time	0.278	–	0.327	–	ns
t _{RDENHD}	Read enable hold time	0.057	–	0.067	–	ns
t _{BLKSU}	Read block select setup time	1.839	–	2.163	–	ns
t _{BLKHD}	Read block select hold time	–0.65	–	–0.765	–	ns
t _{BLK2Q}	Read block select to out disable time (when pipelined register is disabled)	–	2.036		2.396	ns
t _{RSTREM}	Read asynchronous reset removal time (pipelined clock)	–0.023	–	–0.027	–	ns
	Read asynchronous reset removal time (non-pipelined clock)	0.046	–	0.054	–	ns
t _{RSTREC}	Read asynchronous reset recovery time (pipelined clock)	0.507	–	0.597	–	ns
	Read asynchronous reset recovery time (non-pipelined clock)	0.236	–	0.278	–	ns
t _{R2Q}	Read asynchronous reset to output propagation delay (with pipelined register enabled)	–	0.839		0.987	ns
t _{SRSTSU}	Read synchronous reset setup time	0.271	–	0.319	–	ns
t _{SRSTHD}	Read synchronous reset hold time	0.061	–	0.071	–	ns
t _{CCY}	Write clock period	4	–	4	–	ns
t _{CCLKMPWH}	Write clock minimum pulse width High	1.8	–	1.8	–	ns
t _{CCLKMPWL}	Write clock minimum pulse width Low	1.8	–	1.8	–	ns
t _{BLKCSU}	Write block setup time	0.404	–	0.476	–	ns
t _{BLKCHD}	Write block hold time	0.007	–	0.008	–	ns
t _{DINCSU}	Write input data setup time	0.115	–	0.135	–	ns
t _{DINCHD}	Write input data hold time	0.15	–	0.177	–	ns

Table 122 • uSRAM (RAM64x18) in 64x18 Mode (continued)

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{ADDRCSU}	Write address setup time	0.088	–	0.104	–	ns
t_{ADDRCHD}	Write address hold time	0.128	–	0.15	–	ns
t_{WECSU}	Write enable setup time	0.397	–	0.467	–	ns
t_{WECHD}	Write enable hold time	–0.026		–0.03	–	ns
f_{MAX}	Maximum frequency	–	250	–	250	MHz

Table 123 • uSRAM (RAM64x16) in 64x16 Mode

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{CY}	Read clock period	4	–	4	–	ns
t_{CLKMPWH}	Read clock minimum pulse width High	1.8	–	1.8	–	ns
t_{CLKMPWL}	Read clock minimum pulse width Low	1.8	–	1.8	–	ns
t_{PLCY}	Read pipeline clock period	4	–	4	–	ns
$t_{\text{PLCLKMPWH}}$	Read pipeline clock minimum pulse width High	1.8	–	1.8	–	ns
$t_{\text{PLCLKMPWL}}$	Read pipeline clock minimum pulse width Low	1.8	–	1.8	–	ns
t_{CLK2Q}	Read access time with pipeline register	–	0.266	–	0.313	ns
	Read access time without pipeline register	–	1.677	–	1.973	ns
t_{ADDRSU}	Read address setup time in synchronous mode	0.301	–	0.354	–	ns
	Read address setup time in asynchronous mode	1.856	–	2.184	–	ns
t_{ADDRHD}	Read address hold time in synchronous mode	0.091	–	0.107	–	ns
	Read address hold time in asynchronous mode	–0.778	–	–0.915	–	ns
t_{RDENSU}	Read enable setup time	0.278	–	0.327	–	ns
t_{RDENHD}	Read enable hold time	0.057	–	0.067	–	ns
t_{BLKSU}	Read block select setup time	1.839	–	2.163	–	ns
t_{BLKHD}	Read block select hold time	–0.65	–	–0.765	–	ns
t_{BLK2Q}	Read block select to out disable time (when pipelined register is disabled)	–	2.036	–	2.396	ns
t_{RSTREM}	Read asynchronous reset removal time (pipelined clock)	–0.023	–	–0.027	–	ns
	Read asynchronous reset removal time (non-pipelined clock)	0.046	–	0.054	–	ns
t_{RSTREC}	Read asynchronous reset recovery time (pipelined clock)	0.507	–	0.597	–	ns
	Read asynchronous reset recovery time (non-pipelined clock)	0.236	–	0.278	–	ns
t_{R2Q}	Read asynchronous reset to output propagation delay (with pipelined register enabled)	–	0.835	–	0.983	ns

Table 123 • uSRAM (RAM64x16) in 64x16 Mode (continued)

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{SRSTSU}	Read synchronous reset setup time	0.271	–	0.319	–	ns
t_{SRSTHD}	Read synchronous reset hold time	0.061	–	0.071	–	ns
t_{CCY}	Write clock period	4	–	4	–	ns
$t_{CCLKMPWH}$	Write clock minimum pulse width High	1.8	–	1.8	–	ns
$t_{CCLKMPWL}$	Write clock minimum pulse width Low	1.8	–	1.8	–	ns
t_{BLKCSU}	Write block setup time	0.404	–	0.476	–	ns
t_{BLKCHD}	Write block hold time	0.007	–	0.008	–	ns
t_{DINCSU}	Write input data setup time	0.115	–	0.135	–	ns
t_{DINCHD}	Write input data hold time	0.15	–	0.177	–	ns
$t_{ADDRCSU}$	Write address setup time	0.088	–	0.104	–	ns
$t_{ADDRCHD}$	Write address hold time	0.128	–	0.15	–	ns
t_{WECSU}	Write enable setup time	0.397	–	0.467	–	ns
t_{WECHD}	Write enable hold time	–0.026	–	–0.03	–	ns
f_{MAX}	Maximum frequency	–	250	–	250	MHz

Table 124 • uSRAM (RAM128x9) in 128x9 Mode

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{CY}	Read clock period	4	–	4	–	ns
$t_{CLKMPWH}$	Read clock minimum pulse width High	1.8	–	1.8	–	ns
$t_{CLKMPWL}$	Read clock minimum pulse width Low	1.8	–	1.8	–	ns
t_{PLCY}	Read pipeline clock period	4	–	4	–	ns
$t_{PLCLKMPWH}$	Read pipeline clock minimum pulse width High	1.8	–	1.8	–	ns
$t_{PLCLKMPWL}$	Read pipeline clock minimum pulse width Low	1.8	–	1.8	–	ns
t_{CLK2Q}	Read access time with pipeline register	–	0.266	–	0.313	ns
	Read access time without pipeline register	–	1.677	–	1.973	ns
t_{ADDRSU}	Read address setup time in synchronous mode	0.301	–	0.354	–	ns
	Read address setup time in asynchronous mode	1.856	–	2.184	–	ns
t_{ADDRHD}	Read address hold time in synchronous mode	0.091	–	0.107	–	ns
	Read address hold time in asynchronous mode	–0.778	–	–0.915	–	ns
t_{RDENSU}	Read enable setup time	0.278	–	0.327	–	ns
t_{RDENHD}	Read enable hold time	0.057	–	0.067	–	ns
t_{BLKSU}	Read block select setup time	1.839	–	2.163	–	ns

Table 124 • uSRAM (RAM128x9) in 128x9 Mode (continued)

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{BLKHD}	Read block select hold time	-0.65	-	-0.765	-	ns
t_{BLK2Q}	Read block select to out disable time (when pipelined register is disabled)	-	2.036	-	2.396	ns
t_{RSTREM}	Read asynchronous reset removal time (pipelined clock)	-0.023	-	-0.027	-	ns
	Read asynchronous reset removal time (non-pipelined clock)	0.046	-	0.054	-	ns
t_{RSTREC}	Read asynchronous reset recovery time (pipelined clock)	0.507	-	0.597	-	ns
	Read asynchronous reset recovery time (non-pipelined clock)	0.236	-	0.278	-	ns
t_{R2Q}	Read asynchronous reset to output propagation delay (with pipelined register enabled)		0.835		0.982	ns
t_{SRSTSU}	Read synchronous reset setup time	0.271	-	0.319	-	ns
t_{SRSTHD}	Read synchronous reset hold time	0.061	-	0.071	-	ns
t_{CCY}	Write clock period	4	-	4	-	ns
$t_{CCLKMPWH}$	Write clock minimum pulse width High	1.8	-	1.8	-	ns
$t_{CCLKMPWL}$	Write clock minimum pulse width Low	1.8	-	1.8	-	ns
t_{BLKCSU}	Write block setup time	0.404	-	0.476	-	ns
t_{BLKCHD}	Write block hold time	0.007	-	0.008	-	ns
t_{DINCSU}	Write input data setup time	0.115	-	0.135	-	ns
t_{DINCHD}	Write input data hold time	0.15	-	0.177	-	ns
$t_{ADDRCSU}$	Write address setup time	0.088	-	0.104	-	ns
$t_{ADDRCHD}$	Write address hold time	0.128	-	0.15	-	ns
t_{WECSU}	Write enable setup time	0.397	-	0.467	-	ns
t_{WECHD}	Write enable hold time	-0.026	-	-0.03	-	ns
f_{MAX}	Maximum frequency	-	250	-	250	MHz

Table 125 • uSRAM (RAM128x8) in 128x8 Mode

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{CY}	Read clock period	4	-	4	-	ns
$t_{CLKMPWH}$	Read clock minimum pulse width High	1.8	-	1.8	-	ns
$t_{CLKMPWL}$	Read clock minimum pulse width Low	1.8	-	1.8	-	ns
t_{PLCY}	Read pipeline clock period	4	-	4	-	ns
$t_{PLCLKMPWH}$	Read pipeline clock minimum pulse width High	1.8	-	1.8	-	ns
$t_{PLCLKMPWL}$	Read pipeline clock minimum pulse width Low	1.8	-	1.8	-	ns

Table 125 • uSRAM (RAM128x8) in 128x8 Mode (continued)
Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{CLK2Q}	Read access time with pipeline register	–	0.266	–	0.313	ns
	Read access time without pipeline register	–	1.677	–	1.973	ns
t_{ADDRSU}	Read address setup time in synchronous mode	0.301	–	0.354	–	ns
	Read address setup time in asynchronous mode	1.856	–	2.184	–	ns
t_{ADDRHHD}	Read address hold time in synchronous mode	0.091	–	0.107	–	ns
	Read address hold time in asynchronous mode	–0.778	–	–0.915	–	ns
t_{RDENSU}	Read enable setup time	0.278	–	0.327	–	ns
t_{RDENHD}	Read enable hold time	0.057	–	0.067	–	ns
t_{BLKSU}	Read block select setup time	1.839	–	2.163	–	ns
t_{BLKHHD}	Read block select hold time	–0.65	–	–0.765	–	ns
t_{BLK2Q}	Read block select to out disable time (when pipelined register is disabled)		2.036		2.396	ns
t_{RSTREM}	Read asynchronous reset removal time (pipelined clock)	–0.023	–	–0.027	–	ns
	Read asynchronous reset removal time (non-pipelined clock)	0.046	–	0.054	–	ns
t_{RSTREC}	Read asynchronous reset recovery time (pipelined clock)	0.507	–	0.597	–	ns
	Read asynchronous reset recovery time (non-pipelined clock)	0.236	–	0.278	–	ns
t_{R2Q}	Read asynchronous reset to output propagation delay (with pipelined register enabled)	–	0.835	–	0.982	ns
t_{SRSTSU}	Read synchronous reset setup time	0.271	–	0.319	–	ns
t_{SRSTHD}	Read synchronous reset hold time	0.061	–	0.071	–	ns
t_{CCY}	Write clock period	4	–	4	–	ns
t_{CCLKMPWH}	Write clock minimum pulse width High	1.8	–	1.8	–	ns
t_{CCLKMPWL}	Write clock minimum pulse width Low	1.8	–	1.8	–	ns
t_{BLKCSU}	Write block setup time	0.404	–	0.476	–	ns
t_{BLKCHD}	Write block hold time	0.007	–	0.008	–	ns
t_{DINCSU}	Write input data setup time	0.115	–	0.135	–	ns
t_{DINCHD}	Write input data hold time	0.15	–	0.177	–	ns
t_{ADDRCSU}	Write address setup time	0.088	–	0.104	–	ns
t_{ADDRCHD}	Write address hold time	0.128	–	0.15	–	ns
t_{WECSU}	Write enable setup time	0.397	–	0.467	–	ns
t_{WECHD}	Write enable hold time	–0.026	–	–0.03	–	ns
f_{MAX}	Maximum frequency	–	250	–	250	MHz

Table 126 • uSRAM (RAM256x4) in 256x4 Mode
Worst Commercial-Case Conditions: T_J = 85°C, VDD = 1.14 V

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t _{CY}	Read clock period	4	–	4	–	ns
t _{CLKMPWH}	Read clock minimum pulse width High	1.8	–	1.8	–	ns
t _{CLKMPWL}	Read clock minimum pulse width Low	1.8	–	1.8	–	ns
t _{PLCY}	Read pipeline clock period	4	–	4	–	ns
t _{PLCLKMPWH}	Read pipeline clock minimum pulse width High	1.8	–	1.8	–	ns
t _{PLCLKMPWL}	Read pipeline clock minimum pulse width Low	1.8	–	1.8	–	ns
t _{CLK2Q}	Read access time with pipeline register	–	0.27		0.31	ns
	Read access time without pipeline register	–	1.75		2.06	ns
t _{ADDRSU}	Read address setup time in synchronous mode	0.301	–	0.354	–	ns
	Read address setup time in asynchronous mode	1.931	–	2.272	–	ns
t _{ADDRHD}	Read address hold time in synchronous mode	0.121	–	0.142	–	ns
	Read address hold time in asynchronous mode	–0.65	–	–0.76	–	ns
t _{RDENSU}	Read enable setup time	0.278	–	0.327	–	ns
t _{RDENHD}	Read enable hold time	0.057	–	0.067	–	ns
t _{BLKSU}	Read block select setup time	1.839	–	2.163	–	ns
t _{BLKHD}	Read block select hold time	–0.65		–0.77		ns
t _{BLK2Q}	Read block select to out disable time (when pipelined register is disabled)	–	2.09	–	2.46	ns
t _{RSTREM}	Read asynchronous reset removal time (pipelined clock)	–0.02	–	–0.03	–	ns
	Read asynchronous reset removal time (non-pipelined clock)	0.046	–	0.054	–	ns
t _{RSTREC}	Read asynchronous reset recovery time (pipelined clock)	0.507	–	0.597	–	ns
	Read asynchronous reset recovery time (non-pipelined clock)	0.236	–	0.278	–	ns
t _{R2Q}	Read asynchronous reset to output propagation delay (with pipelined register enabled)	–	0.83	–	0.98	ns
t _{SRSTSU}	Read synchronous reset setup time	0.271	–	0.319	–	ns
t _{SRSTHD}	Read synchronous reset hold time	0.061	–	0.071	–	ns
t _{CCY}	Write clock period	4	–	4	–	ns
t _{CCLKMPWH}	Write clock minimum pulse width High	1.8	–	1.8	–	ns
t _{CCLKMPWL}	Write clock minimum pulse width Low	1.8	–	1.8	–	ns
t _{BLKCSU}	Write block setup time	0.404	–	0.476	–	ns
t _{BLKCHD}	Write block hold time	0.007	–	0.008	–	ns
t _{DINCSU}	Write input data setup time	0.101	–	0.118	–	ns
t _{DINCHD}	Write input data hold time	0.137	–	0.161	–	ns
t _{ADDRCSU}	Write address setup time	0.088	–	0.104	–	ns

Table 126 • uSRAM (RAM256x4) in 256x4 Mode (continued)

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{ADDRCHD}	Write address hold time	0.245	–	0.288	–	ns
t_{WECSU}	Write enable setup time	0.397	–	0.467	–	ns
t_{WECHD}	Write enable hold time	–0.03	–	–0.03	–	ns
f_{MAX}	Maximum frequency	–	250	–	250	MHz

Table 127 • uSRAM (RAM512x2) in 512x2 Mode

 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{CY}	Read clock period	4	–	4	–	ns
t_{CLKMPWH}	Read clock minimum pulse width High	1.8	–	1.8	–	ns
t_{CLKMPWL}	Read clock minimum pulse width Low	1.8	–	1.8	–	ns
t_{PLCY}	Read pipeline clock period	4	–	4	–	ns
$t_{\text{PLCLKMPWH}}$	Read pipeline clock minimum pulse width High	1.8	–	1.8	–	ns
$t_{\text{PLCLKMPWL}}$	Read pipeline clock minimum pulse width Low	1.8	–	1.8	–	ns
t_{CLK2Q}	Read access time with pipeline register	–	0.27	–	0.31	ns
	Read access time without pipeline register	–	1.76	–	2.08	ns
t_{ADDRSU}	Read address setup time in synchronous mode	0.301	–	0.354	–	ns
	Read address setup time in asynchronous mode	1.96	–	2.306	–	ns
t_{ADDRHD}	Read address hold time in synchronous mode	0.137	–	0.161	–	ns
	Read address hold time in asynchronous mode	–0.58	–	–0.68	–	ns
t_{RDENSU}	Read enable setup time	0.278	–	0.327	–	ns
t_{RDENHD}	Read enable hold time	0.057	–	0.067	–	ns
t_{BLKSU}	Read block select setup time	1.839	–	2.163	–	ns
t_{BLKHD}	Read block select hold time	–0.65	–	–0.77	–	ns
t_{BLK2Q}	Read block select to out disable time (when pipelined register is disabled)	–	2.14	–	2.52	ns
t_{RSTREM}	Read asynchronous reset removal time (pipelined clock)	–0.02	–	–0.03	–	ns
	Read asynchronous reset removal time (non-pipelined clock)	0.046	–	0.054	–	ns
t_{RSTREC}	Read asynchronous reset recovery time (pipelined clock)	0.507	–	0.597	–	ns
	Read asynchronous reset recovery time (non-pipelined clock)	0.236	–	0.278	–	ns
t_{R2Q}	Read asynchronous reset to output propagation delay (with pipelined register enabled)	–	0.83	–	0.98	ns
t_{SRSTSU}	Read synchronous reset setup time	0.271	–	0.319	–	ns

Table 127 • uSRAM (RAM512x2) in 512x2 Mode (continued)
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{SRSTHD}	Read synchronous reset hold time	0.061	–	0.071	–	ns
t_{CCY}	Write clock period	4	–	4	–	ns
$t_{CCLKMPWH}$	Write clock minimum pulse width High	1.8	–	1.8	–	ns
$t_{CCLKMPWL}$	Write clock minimum pulse width Low	1.8	–	1.8	–	ns
t_{BLKCSU}	Write block setup time	0.404	–	0.476	–	ns
t_{BLKCHD}	Write block hold time	0.007	–	0.008	–	ns
t_{DINCSU}	Write input data setup time	0.101	–	0.118	–	ns
t_{DINCHD}	Write input data hold time	0.137	–	0.161	–	ns
$t_{ADDRCSU}$	Write address setup time	0.088	–	0.104	–	ns
$t_{ADDRCHD}$	Write address hold time	0.247	–	0.29	–	ns
t_{WECSU}	Write enable setup time	0.397	–	0.467	–	ns
t_{WECHD}	Write enable hold time	–0.03	–	–0.03	–	ns
f_{MAX}	Maximum frequency	–	250	–	250	MHz

Table 128 • uSRAM (RAM1024x1) in 1024x1 Mode
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{CY}	Read clock period	4	–	4	–	ns
$t_{CLKMPWH}$	Read clock minimum pulse width High	1.8	–	1.8	–	ns
$t_{CLKMPWL}$	Read clock minimum pulse width Low	1.8	–	1.8	–	ns
t_{PLCY}	Read pipeline clock period	4	–	4	–	ns
$t_{PLCLKMPWH}$	Read pipeline clock minimum pulse width High	1.8	–	1.8	–	ns
$t_{PLCLKMPWL}$	Read pipeline clock minimum pulse width Low	1.8	–	1.8	–	ns
t_{CLK2Q}	Read access time with pipeline register	–	0.27	–	0.31	ns
	Read access time without pipeline register	–	1.78	–	2.1	ns
t_{ADDRSU}	Read address setup time in synchronous mode	0.301	–	0.354	–	ns
	Read address setup time in asynchronous mode	1.978	–	2.327	–	ns
t_{ADDRHD}	Read address hold time in synchronous mode	0.137	–	0.161	–	ns
	Read address hold time in asynchronous mode	–0.6	–	–0.71	–	ns
t_{RDENSU}	Read enable setup time	0.278	–	0.327	–	ns
t_{RDENHD}	Read enable hold time	0.057	–	0.067	–	ns
t_{BLKSU}	Read block select setup time	1.839	–	2.163	–	ns
t_{BLKHD}	Read block select hold time	–0.65	–	–0.77	–	ns

Table 128 • uSRAM (RAM1024x1) in 1024x1 Mode (continued)
Worst Commercial-Case Conditions: T_J = 85°C, VDD = 1.14 V

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t _{BLK2Q}	Read block select to out disable time (when pipelined register is disabled)	-	2.16	-	2.54	ns
t _{RSTREM}	Read asynchronous reset removal time (pipelined clock)	-0.02	-	-0.03	-	ns
	Read asynchronous reset removal time (non-pipelined clock)	0.046	-	0.054	-	ns
t _{RSTREC}	Read asynchronous reset recovery time (pipelined clock)	0.507	-	0.597	-	ns
	Read asynchronous reset recovery time (non-pipelined clock)	0.236	-	0.278	-	ns
t _{R2Q}	Read asynchronous reset to output propagation delay (with pipelined register enabled)	-	0.83	-	0.98	ns
t _{SRSTSU}	Read synchronous reset setup time	0.271	-	0.319	-	ns
t _{SRSTHD}	Read synchronous reset hold time	0.061	-	0.071	-	ns
t _{CCY}	Write clock period	4	-	4	-	ns
t _{CCLKMPWH}	Write clock minimum pulse width High	1.8	-	1.8	-	ns
t _{CCLKMPWL}	Write clock minimum pulse width Low	1.8	-	1.8	-	ns
t _{BLKCSU}	Write block setup time	0.404	-	0.476	-	ns
t _{BLKCHD}	Write block hold time	0.007	-	0.008	-	ns
t _{DINCSU}	Write input data setup time	0.003	-	0.004	-	ns
t _{DINCHD}	Write input data hold time	0.137	-	0.161	-	ns
t _{ADDRCSU}	Write address setup time	0.088	-	0.104	-	ns
t _{ADDRCHD}	Write address hold time	0.247	-	0.29	-	ns
t _{WECSU}	Write enable setup time	0.397	-	0.467	-	ns
t _{WECHD}	Write enable hold time	-0.03	-	-0.03	-	ns
f _{MAX}	Maximum frequency	-	250	-	250	MHz

Table 129 • Programming Times
 Typical Conditions: T_J = 25°C, VDD = 1.2 V

			JTAG		2 Step IAP			MSS/Cortex-M3 ISP (SmartFusion2 Only)			Auto Progr ammi ng	Auto Updat e	Progr ammi ng Reco very	
	Device	Image size Bytes	Progra m	Verify	Auth entic ate	Progr am	Verify	Auth entic ate	Progr am	Verify	SPI CLK = 100 kHz	SPI CLK = 25 MHz	SPI CLK = 12.5 MHz	Units
											Progr am	Progr am	Progr am	
Fabric Only	M2S005 /M2GL0 05	302672	22	10	4	17	6	6	19	8	47	27	28	Sec
	M2S010 /M2GL0 10	568784	28	18	7	23	12	10	26	14	77	35	35	Sec
	M2S025 /M2GL0 25	1223504	51	26	14	33	23	21	39	29	150	42	41	Sec
	M2S050 /M2GL0 50	2424832	66	54	29	52	40	39	60	50	33*	Not Supp orted	Not Supp orted	Sec
	M2S060 /M2GL0 60	2418896	77	54	39	61	50	44	65	54	291	83	82	Sec
	M2S090 /M2GL0 90	3645968	113	126	60	84	73	66	90	79	427	109	108	Sec
	M2S150 /M2GL1 50	6139184	155	193	100	132	120	108	140	128	708	157	160	Sec

Table 129 • Programming Times
 Typical Conditions: T_J = 25°C, VDD = 1.2 V

		JTAG			2 Step IAP			MSS/Cortex-M3 ISP (SmartFusion2 Only)			Auto Programming	Auto Update	Programming Recovery	
	Device	Image size Bytes	Program	Verify	Authenticate	Program	Verify	Authenticate	Program	Verify	SPI CLK = 100 kHz	SPI CLK = 25 MHz	SPI CLK = 12.5 MHz	Units
											Program	Program	Program	
eNVM Only	M2S005 /M2GL005	137536	39	4	2	37	5	3	42	4	41	48	49	Sec
	M2S010 /M2GL010	274816	78	9	4	76	11	4	82	7	86	87	87	Sec
	M2S025 /M2GL025	274816	78	9	4	78	10	4	82	8	87	85	86	Sec
	M2S050 /M2GL050	278528	84	8	3	85	9	4	80	8	85	Not Supported	Not Supported	Sec
	M2S060 /M2GL060	268480	76	8	5	76	22	6	80	8	78	86	86	Sec
	M2S090 /M2GL090	544496	154	15	10	152	43	10	157	15	154	162	162	Sec
	M2S150 /M2GL150	544496	155	15	10	153	44	10	158	15	161	161	161	Sec

Table 129 • Programming Times
 Typical Conditions: T_J = 25°C, VDD = 1.2 V

		JTAG			2 Step IAP			MSS/Cortex-M3 ISP (SmartFusion2 Only)			Auto Progr ammi ng	Auto Updat e	Progr ammi ng Reco very	
		Image size Bytes	Progra m	Verify	Auth entic ate	Progr am	Verify	Auth entic ate	Progr am	Verify	SPI CLK = 100 kHz	SPI CLK = 25 MHz	SPI CLK = 12.5 MHz	Units
Device	Progr am										Progr am	Progr am		
Fabric-t-eNVM	M2S005 /M2GL0 05	439296	59	11	6	56	11	9	61	11	87	67	66	Sec
	M2S010 /M2GL0 10	842688	107	20	11	100	21	15	107	21	161	113	113	Sec
	M2S025 /M2GL0 25	1497408	120	35	19	113	32	26	121	35	229	120	121	Sec
	M2S050 /M2GL0 50	2695168	162	59	32	136	48	43	141	55	112	Not Supp orted	Not Supp orted	Sec
	M2S060 /M2GL0 60	2686464	158	70	43	137	70	48	143	60	368	161	158	Sec
	M2S090 /M2GL0 90	4190208	266	147	68	236	115	75	244	91	582	261	260	Sec
	M2S150 /M2GL1 50	6682768	316	231	109	286	162	117	296	141	867	309	310	Sec

Notes:

- *Auto Programming in 050 device is done through SC_SPI, and SPI CLK is set to 6.25 MHz.
- External SPI flash part# AT25DF641-s3H is used during this measurement.

Table 130 • Programming Times
Worst-Case Conditions: T_J = 100°C, VDD = 1.14 V

			JTAG		2 Step IAP			MSS/Cortex-M3 ISP (SmartFusion2 Only)			Auto Programming	Auto Update	Programming Recovery	
	Device	Image size Bytes	Program	Verify	Authenticate	Program	Verify	Authenticate	Program	Verify	SPI CLK = 100 kHz	SPI CLK = 25 MHz	SPI CLK = 12.5 MHz	Units
											Program	Program	Program	
Fabric Only	M2S005 /M2GL005	302672	44	10	4	39	6	6	41	8	69	49	50	sec
	M2S010 /M2GL010	568784	50	18	7	45	12	10	48	14	99	57	57	sec
	M2S025 /M2GL025	1223504	73	26	14	55	23	21	61	29	150	64	63	sec
	M2S050 /M2GL050	2424832	88	54	29	74	40	39	82	50	55*	Not Supported	Not Supported	sec
	M2S060 /M2GL060	2418896	99	54	39	83	50	44	87	54	313	105	104	sec
	M2S090 /M2GL090	3645968	135	126	60	106	73	66	112	79	449	131	130	sec
	M2S150 /M2GL150	6139184	177	193	100	154	120	108	162	128	730	179	183	sec

Table 130 • Programming Times
 Worst-Case Conditions: T_J = 100°C, VDD = 1.14 V

			JTAG		2 Step IAP			MSS/Cortex-M3 ISP (SmartFusion2 Only)			Auto Progr ammi ng	Auto Upda te	Progr ammi ng Reco very	
	Device	Image size Bytes	Progra m	Verify	Authe nticat e	Progr am	Verify	Authe nticat e	Progr am	Verify	SPI CLK = 100 kHz	SPI CLK = 25 MHz	SPI CLK = 12.5 MHz	Units
											Progr am	Progr am	Progr am	
eNVM Only	M2S005 /M2GL0 05	137536	61	4	2	59	5	3	64	4	63	70	71	sec
	M2S010 /M2GL0 10	274816	100	9	4	98	11	4	104	7	108	109	109	sec
	M2S025 /M2GL0 25	274816	100	9	4	100	10	4	104	8	109	107	108	sec
	M2S050 /M2GL0 50	2,78,528	106	8	3	107	9	4	102	8	107	Not Supp orted	Not Supp orted	sec
	M2S060 /M2GL0 60	268480	98	8	5	98	22	6	102	8	100	108	108	sec
	M2S090 /M2GL0 90	544496	176	15	10	174	43	10	179	15	176	184	184	sec
	M2S150 /M2GL1 50	544496	177	15	10	175	44	10	180	15	183	183	183	sec

Table 130 • Programming Times
Worst-Case Conditions: T_J = 100°C, VDD = 1.14 V

			JTAG		2 Step IAP			MSS/Cortex-M3 ISP (SmartFusion2 Only)			Auto Programming	Auto Update	Programming Recovery	
	Device	Image size Bytes	Program	Verify	Authenticate	Program	Verify	Authenticate	Program	Verify	SPI CLK = 100 kHz	SPI CLK = 25 MHz	SPI CLK = 12.5 MHz	Units
											Program	Program	Program	
Fabric + eNVM	M2S005 /M2GL005	439296	71	11	6	78	11	9	83	11	109	89	88	sec
	M2S010 /M2GL010	842688	129	20	11	122	21	15	129	21	183	135	135	sec
	M2S025 /M2GL025	1497408	142	35	19	135	32	26	143	35	251	142	143	sec
	M2S050 /M2GL050	2695168	184	59	32	158	48	43	163	55	134	Not Supported	Not Supported	sec
	M2S060 /M2GL060	2686464	180	70	43	159	70	48	165	60	390	183	180	sec
	M2S090 /M2GL090	4190208	288	147	68	258	115	75	266	91	604	283	282	sec
	M2S150 /M2GL150	6682768	338	231	109	308	162	117	318	141	889	331	332	sec

Notes:

- *Auto Programming in 050 device is done through SC_SPI, and SPI CLK is set to 6.25 MHz.
- External SPI flash part# AT25DF641-s3H is used during this measurement.

12. Embedded NVM (eNVM) Characteristics

Table 131 • eNVM Read Performance

Worst-Case Conditions: VDD = 1.14 V, VPPNVM = VPP = 2.375 V

Symbol	Description	Operating Temperature Range						Unit
		-55°C to 125°C		-40°C to 100°C		0°C to 85°C		
T _j	Junction Temperature Range	-55°C to 125°C		-40°C to 100°C		0°C to 85°C		°C
Speed grade	–	-1	Std	-1	Std	-1	Std	-
F _{MAXREAD}	eNVM Maximum Read Frequency	25	25	25	25	25	25	MHz

Table 132 • eNVM Page Programming

Worst-Case Conditions: VDD = 1.14 V, VPPNVM = VPP = 2.375 V

Symbol	Description	Operating Temperature Range						Unit
		-55°C to 125°C		-40°C to 100°C		0°C to 85°C		
T _j	Junction Temperature Range	-55°C to 125°C		-40°C to 100°C		0°C to 85°C		°C
Speed grade	–	-1	Std	-1	Std	-1	Std	-
t _{PAGEPGM}	eNVM Page Programming Time	40	40	40	40	40	40	ms

13. SRAM PUF

For more details on static random-access memory (SRAM) physical unclonable functions (PUF) services, refer to [AC434: Using SRAM PUF System Service in SmartFusion2 - Libero SoC v11.7 Application Note](#).

Table 133 • SRAM PUF

 Worst-Case Industrial Conditions: T_j = 100°C, VDD = 1.14 V

Service	PUF Off		PUF On		Units
	Typ	Max	Typ	Max	
Create Activation Code	709.1	746.4	754.4	762.5	ms
Delete Activation Code	1329.3	1399.3	1414.1	1429.3	ms
Create Intrinsic KeyCode	656.6	691.1	698.5	706.0	ms
Create Extrinsic KeyCode	656.6	691.1	698.5	706.0	ms
Get Number of Keys	1.3	1.4	1.4	1.4	ms
Export (KC0, KC1)	998.0	1050.5	1061.7	1073.1	ms
Export 2 KeyCodes	2020.2	2126.5	2149.2	2172.3	ms
Export 4 KeyCodes	3065.7	3227.0	3261.3	3296.4	ms
Export 8 KeyCodes	5101.0	5369.5	5426.6	5485.0	ms
Export 16 KeyCodes	9212.1	9697.0	9800.1	9905.5	ms
Import (KC0, KC1)	39.7	41.8	42.2	42.7	ms
Import 2 KeyCodes	50.1	52.7	53.3	53.9	ms
Import 4 KeyCodes	60.6	63.8	64.5	65.2	ms
Import 8 KeyCodes	80.9	85.1	86.1	87.0	ms
Import 16 KeyCodes	123.8	130.4	131.7	133.2	ms
Delete KeyCode	552.5	581.6	587.8	594.1	ms
Fetch Key	31.4	33.0	33.4	33.7	ms

Table 133 • SRAM PUF (continued)

 Worst-Case Industrial Conditions: $T_J = 100^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Service	PUF Off		PUF On		Units
	Typ	Max	Typ	Max	
Fetch ECC Key	20.0	21.1	21.3	21.5	ms
Get Seed	2.0	2.1	2.2	2.2	ms

14. Crystal Oscillator

Table 134 describes the electrical characteristics of the crystal oscillator in the IGLOO2 FPGA and SmartFusion2 SoC FPGAs.

Table 134 • Electrical Characteristics of the Crystal Oscillator – High Gain Mode (20 MHz)

Parameter	Description	Condition	Min	Typ	Max	Units
FXTAL	Operating frequency	–	–	20	–	MHz
ACCXTAL	Accuracy	005, 010, 025, 050, 060, and 090 Devices	–	–	0.0047	%
		150 Devices	–	–	0.0058	%
CYCXTAL	Output duty cycle	–	–	49–51	47–53	%
JITPERXTAL	Output Period Jitter (peak to peak)	–	–	200	300	ps
JITCYCXTAL	Output Cycle to Cycle Jitter (peak to peak)	010, 025, 050, and 060 Devices	–	200	300	ps
		150 Devices	–	250	410	ps
		005 and 090 Devices	–	250	550	ps
IDYNXTAL	Operating current	010, 050, and 060 Devices	–	1.5	–	mA
		005, 025, 090, and 150 Devices	–	1.65	–	mA
VIHXTAL	Input logic level High	–	0.9 VPP	–	–	V
VILXTAL	Input logic level Low	–	–	–	0.1 VPP	V
SUXTAL	Startup time (with regard to stable oscillator output)	005, 010, 025, and 050 Devices	–	–	0.8	ms
		090 and 150 Devices	–	–	1.0	ms

Table 135 • Electrical Characteristics of the Crystal Oscillator – Medium Gain Mode (2 MHz)

Parameter	Description	Condition	Min	Typ	Max	Units
FXTAL	Operating frequency	–	–	2	–	MHz
ACCXTAL	Accuracy	050 Devices	–	–	0.00105	%
		005, 010, 025, 090, and 150 Devices	–	–	0.003	%
		060 Devices	–	–	0.004	%
CYCXTAL	Output duty cycle	–	–	49–51	47–53	%
JITPERXTAL	Output Period Jitter (peak to peak)	–	–	1	5	ns

Table 135 • Electrical Characteristics of the Crystal Oscillator – Medium Gain Mode (2 MHz) (continued)

Parameter	Description	Condition	Min	Typ	Max	Units
JITCYCXTAL	Output Cycle to Cycle Jitter (peak to peak)	–	–	1	5	ns
IDYNXTAL	Operating current	–	–	0.3	–	mA
VIHXTAL	Input logic level High	–	0.9 VPP	–	–	V
VILXTAL	Input logic level Low	–	–	–	0.1 VPP	V
SUXTAL	Startup time (with regard to stable oscillator output)	010 and 050 Devices	–	–	4.5	ms
		005 and 025 Devices	–	–	5	ms
		090 and 150 Devices	–	–	7	ms

Table 136 • Electrical Characteristics of the Crystal Oscillator – Low Gain Mode (32 kHz)

Parameter	Description	Condition	Min	Typ	Max	Units
FXTAL	Operating frequency	–	–	32	–	kHz
ACCXTAL	Accuracy	005, 010, 025, 050, 060, and 090 Devices	–	–	0.004	%
		150 Devices	–	–	0.005	%
CYCXTAL	Output duty cycle	–	–	49–51	47–53	%
JITPERXTAL	Output Period Jitter (peak to peak)	–	–	150	300	ns
JITCYCXTAL	Output Cycle to Cycle Jitter (peak to peak)	–	–	150	300	ns
IDYNXTAL	Operating current	010 and 050 Devices	–	0.044	–	mA
		005, 025, 060, 090, and 150 Devices	–	0.060	–	mA
VIHXTAL	Input logic level High	–	0.9 VPP	–	–	V
VILXTAL	Input logic level Low	–	–	–	0.1 VPP	V
SUXTAL	Startup time (with regard to stable oscillator output)	005, 025, 050, 090, and 150 Devices	–	–	115	ms
		010 Devices	–	–	126	ms

15. On-Chip Oscillator

Table 137 and Table 138 describe the electrical characteristics of the available on-chip oscillators in the IGLOO2 FPGAs and SmartFusion2 SoC FPGAs.

Table 137 • Electrical Characteristics of the 50 MHz RC Oscillator

Parameter	Description	Condition	Min	Typ	Max	Units
F50RC	Operating frequency	–	–	50	–	MHz
ACC50RC	Accuracy	050 Devices	–	1	4	%
		005, 025, and 060 Devices	–	1	5	%
		090 Devices	–	1	6.3	%
		010 and 150 Devices	–	1	7.1	%
CYC50RC	Output duty cycle	–	–	49–51	46.5–53.5	%
JIT50RC	Output jitter (peak to peak)	Period Jitter				
		005, 010, 050, and 060 Devices	–	200	300	ps
		150 Devices	–	200	400	ps
		025 and 090 Devices	–	300	500	ps
		Cycle-to-Cycle Jitter				
		005 and 050 Devices	–	200	300	ps
		010, 060, and 150 Devices	–	320	420	ps
025 and 090 Devices	–	320	850	ps		
IDYN50RC	Operating current	–	–	6.5	–	mA

Table 138 • Electrical Characteristics of the 1 MHz RC Oscillator

Parameter	Description	Condition	Min	Typ	Max	Units
F1RC	Operating frequency	–	–	1	–	MHz
ACC1RC	Accuracy	005, 010, 025, and 050 Devices	–	1	3	%
		060, and 150 Devices	–	1	4.5	%
		090 Devices	–	1	5.6	%
CYC1RC	Output duty cycle	005, 010, 025, 050, 060, 090 and 150 Devices	–	49–51	46.5–53.5	%
		060 Devices	–	49-51	46.0-54.0	%
JIT1RC	Output jitter (peak to peak)	Period Jitter				
		005, 010, 025, and 050 Devices	–	10	20	ns
		060, 090 and 150 Devices	–	10	28	ns
		Cycle-to-Cycle Jitter				
		005, 010, and 050 Devices	–	10	20	ns
		025, 060, and 150 Devices	–	10	35	ns
090 Devices	–	10	45	ns		
IDYN1RC	Operating current	–	–	0.1	–	mA

Table 138 • Electrical Characteristics of the 1 MHz RC Oscillator (continued)

Parameter	Description	Condition	Min	Typ	Max	Units
SU1RC	Startup time	050, 090, and 150 Devices	–	–	17	μs
		005, 010, and 025 Devices	–	–	18	μs

16. Clock Conditioning Circuits (CCC)

Table 139 • IGLOO2 and SmartFusion2 SoC FPGAs CCC/PLL Specification

 Worst-Case Industrial Conditions: $T_J = 100^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Conditions	Minimum	Typical	Maximum	Units	Notes
Clock conditioning circuitry input frequency f_{IN_CCC}	All CCC	1	–	200	MHz	–
	32 kHz capable CCC	0.032	–	200	MHz	–
Clock conditioning circuitry output frequency f_{OUT_CCC}	–	0.078	–	400	MHz	1
PLL VCO frequency	–	500	–	1000	MHz	2
Delay increments in programmable delay blocks	–	–	75	100	ps	–
Number of programmable values in each programmable delay block	–	–	–	64	–	–
Acquisition time	$f_{IN} \geq 1\text{MHz}$	–	70	100	μs	–
	$f_{IN} = 32\text{kHz}$	–	1	16	ms	–
Input duty cycle (Reference Clock)	Internal Feedback					
	$1\text{ MHz} \leq f_{IN_CCC} \leq 25\text{ MHz}$	10	–	90	%	–
	$25\text{ MHz} \leq f_{IN_CCC} \leq 100\text{ MHz}$	25	–	75	%	–
	$100\text{ MHz} \leq f_{IN_CCC} \leq 150\text{ MHz}$	35	–	65	%	–
	$150\text{ MHz} \leq f_{IN_CCC} \leq 200\text{ MHz}$	45	–	55	%	–
	External Feedback (CCC, FPGA, Off-chip)					
	$1\text{ MHz} \leq f_{IN_CCC} \leq 25\text{ MHz}$	25	–	75	%	–
	$25\text{ MHz} \leq f_{IN_CCC} \leq 35\text{ MHz}$	35	–	65	%	–
	$35\text{ MHz} \leq f_{IN_CCC} \leq 50\text{ MHz}$	45	–	55	%	–

Table 139 • IGLOO2 and SmartFusion2 SoC FPGAs CCC/PLL Specification (continued)

 Worst-Case Industrial Conditions: $T_J = 100^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Conditions	Minimum	Typical	Maximum	Units	Notes
Output duty cycle	050 Devices $F_{out} \leq 400\text{ MHz}$	48	–	52	%	–
	005, 010, and 025 Devices $F_{out} < 350\text{ MHz}$	48	–	52	%	–
	005, 010, and 025 Devices $350\text{ MHz} \leq F_{out} \leq 400\text{ MHz}$	46	–	54	%	–
	090 Devices $F_{out} \leq 100\text{ MHz}$	48	–	52	%	–
	090 Devices $100\text{ MHz} \leq F_{out} \leq 400\text{ MHz}$	44	–	52	%	–
	150 Devices $F_{out} \leq 120\text{ MHz}$	48	–	52	%	–
	150 Devices $120\text{ MHz} \leq F_{out} \leq 400\text{ MHz}$	45	–	52	%	–

Spread Spectrum Characteristics

Modulation frequency range	–	25	35	50	k	–
Modulation depth range	–	0	–	1.5	%	–
Modulation depth control	–	–	0.5	–	%	–

Note:

- The minimum output clock frequency is limited by the PLL. For more information, refer to the [UG0449: SmartFusion2 and IGLOO2 Clocking Resources User Guide](#)
- The PLL is used in conjunction with the Clock Conditioning Circuitry. Performance is limited by the CCC output frequency.

Table 140 • IGLOO2 and SmartFusion2 SoC FPGAs CCC/PLL Jitter Specifications

 Worst-Case Industrial Conditions: $T_J = 100^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

CCC Output Maximum Peak-to-Peak Period Jitter f_{OUT_CCC}							
Parameter	Conditions/Package Combinations					Units	Notes
10 FG484, 050 FG896/FG484/FC S325 Packages	SSO = 0	$0 < \text{SSO} \leq 2$	$\text{SSO} \leq 4$	$\text{SSO} \leq 8$	$\text{SSO} \leq 16$	–	*
20 MHz to 100 MHz	$\text{Max}(110, \pm 1\% \times (1/f_{OUT_CCC}))$	$\text{Max}(150, \pm 1\% \times (1/f_{OUT_CCC}))$				ps	–
100 MHz to 400 MHz	$\text{Max}(120, \pm 1\% \times (1/f_{OUT_CCC}))$	$\text{Max}(150, \pm 1\% \times (1/f_{OUT_CCC}))$		$\text{Max}(170, \pm 1\% \times (1/f_{OUT_CCC}))$		ps	–
025 FG484/FCS325 Package	$0 < \text{SSO} \leq 16$						*
20 MHz to 74 MHz	$\pm 1\% \times (1/f_{OUT_CCC})$					ps	–
74 MHz to 400 MHz	210					ps	–
005 FG484 Package	$0 < \text{SSO} \leq 16$					–	*

Table 140 • IGLOO2 and SmartFusion2 SoC FPGAs CCC/PLL Jitter Specifications (continued)

 Worst-Case Industrial Conditions: $T_J = 100^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

CCC Output Maximum Peak-to-Peak Period Jitter fOUT_CCC			
Parameter	Conditions/Package Combinations	Units	Notes
20 MHz to 53 MHz	$\pm 1\% \times (1/f_{\text{OUT_CCC}})$	ps	–
53 MHz to 400 MHz	270	ps	–
090 FG676 and FC325 Package	$0 < \text{SSO} \leq 16$	–	*
20 MHz to 100 MHz	$\pm 1\% \times (1/f_{\text{OUT_CCC}})$	ps	–
100 MHz to 400 MHz	150	ps	–
060 FG676 Package	$0 < \text{SSO} \leq 16$		*
20 MHz to 100 MHz	$\pm 1\% \times (1/f_{\text{OUT_CCC}})$	ps	–
100 MHz to 400 MHz	150	–	–
150 FC1152 Package	$0 < \text{SSO} \leq 16$	–	*
20 MHz to 100 MHz	$\pm 1\% \times (1/f_{\text{OUT_CCC}})$	ps	–
100 MHz to 400 MHz	120	ps	–
<i>Note: * SSO data is based on LVCMOS 2.5 V MSIO and/or MSIOD bank I/Os</i>			

17. JTAG

Table 141 • JTAG 1532

Parameter	Description	Speed Grade														Units
		-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	-1	Std	
		005		010		025		050		060		090		150		
t _{TCK2Q}	Clock to Q (data out)	7.47	8.79	7.73	9.09	7.75	9.12	7.89	9.28	8.38	9.86	8.96	10.54	8.66	10.19	ns
t _{RSTB2Q}	Reset to Q (data out)	7.65	9	6.43	7.56	6.13	7.21	7.40	8.70	8.54	10.04	7.75	9.12	8.79	10.34	ns
t _{DISU}	Test Data Input Setup Time	-1.05	-0.89	-0.69	-0.59	-0.67	-0.57	-0.30	-0.25	-1.18	-1	-1.31	-1.11	-0.96	-0.82	ns
t _{DIHD}	Test Data Input Hold Time	2.38	2.8	2.38	2.8	2.42	2.85	2.09	2.45	2.52	2.97	2.68	3.15	2.57	3.02	ns
t _{TMSSU}	Test Mode Select Setup Time	-0.73	-0.62	-1.03	-1.21	-1.1	-0.94	0.28	0.33	-0.97	-0.83	-1.02	-0.87	-0.53	-0.45	ns
t _{TMDHD}	Test Mode Select Hold Time	1.36	1.6	1.43	1.68	1.93	2.27	0.16	0.19	1.7	2	1.67	1.96	1.02	1.2	ns
t _{TRSTREM}	ResetB Removal Time	-0.77	-0.65	-1.08	-0.92	-1.33	-1.13	-0.45	-0.38	-1.21	-1.03	-0.76	-0.65	-1.03	-0.88	ns
t _{TRSTREC}	ResetB Recovery Time	-0.76	-0.65	-1.07	-0.91	-1.34	-1.14	-0.45	-0.38	-1.21	-1.03	-0.77	-0.65	-1.03	-0.88	ns
F _{TCKMAX}	TCK Maximum frequency	25	21.25	25	21.25	25	21.25	25.00	21.25	25	21.25	25	21.25	25	21.25	MHz

18. DEVRST_N Characteristics

Table 142 • DEVRST_N Characteristics

Symbol	Description	All Devices/Speed Grades			Units	Notes
		Min	Typ	Max		
TRAMPDEVRSTN	DEVRST_N ramp rate	—	—	1	us	—
FMAXPDEVRSTN	DEVRST_N cycling rate	—	—	100	kHz	—

19. System Controller SPI Characteristics

Table 143 • System Controller SPI Characteristics

 Worst-Case Industrial Conditions: T_J = 100°C, V_{DD} = 1.14 V

Symbol	Description	Conditions	All Devices/Speed Grades			Units	Notes
			Min	Typ	Max		
sp1	SC_SPI_SCK minimum period	—	20	—	—	ns	—
sp2	SC_SPI_SCK minimum pulse width high	—	10	—	—	ns	—
sp3	SC_SPI_SCK minimum pulse width low	—	10	—	—	ns	—
sp4	SC_SPI_SCK, SC_SPI_SDO, SC_SPI_SS rise time (10%–90%) 1	IO Configuration: LVTTTL 3.3 V-20mA AC Loading: 35pF Test Conditions: Typical Voltage, 25C	—	1.239	—	ns	*
sp5	SC_SPI_SCK, SC_SPI_SDO, SC_SPI_SS fall time (10%–90%) 1	IO Configuration: LVTTTL 3.3 V-20mA AC Loading: 35pF Test Conditions: Typical Voltage, 25C	—	1.245	—	ns	*
sp6	Data from master (SC_SPI_SDO) setup time	—	160	—	—	ns	—
sp7	Data from master (SC_SPI_SDO) hold time	—	160	—	—	ns	—
sp8	SC_SPI_SDI setup time	—	20	—	—	ns	—
sp9	SC_SPI_SDI hold time	—	20	—	—	ns	—

Note: *For specific Rise/Fall Times, board design considerations and detailed output buffer resistances, use the corresponding IBIS models located on the Microsemi SoC Products Group website: <http://www.microsemi.com/soc/download/ibis/default.aspx>. Use the supported I/O Configurations for the System Controller SPI in Table 144.

Table 144 • Supported I/O Configurations for System Controller SPI (for MSIO Bank Only)

Voltage Supply	I/O Drive Configuration	Units
3.3 V	20	mA
2.5 V	16	mA
1.8 V	12	mA
1.5 V	8	mA
1.2 V	4	mA

20. Mathblock Timing Characteristics

The fundamental building block in any digital signal processing algorithm is the multiply-accumulate function. Each IGLOO2 and SmartFusion2 SoC mathblock supports 18x18 signed multiplication, dot product, and built-in addition, subtraction, and accumulation units to combine multiplication results efficiently.

Table 145 • Mathblocks with all Registers Used
 Worst Commercial-Case Conditions: T_J = 85°C, VDD = 1.14 V

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t _{MISU}	Input, control register setup time	0.149	–	0.176	–	ns
t _{MIHD}	Input, control register hold time	1.68	–	1.976	–	ns
t _{MOCDINSU}	CDIN input setup time	0.185	–	0.218	–	ns
t _{MOCDINH}	CDIN input hold time	0.08	–	0.094	–	ns
t _{MSRSTENSU}	Synchronous reset/enable setup time	–0.419	–	–0.493	–	ns
t _{MSRSTENHD}	Synchronous reset/enable hold time	0.011	–	0.013	–	ns
t _{MARSTREM}	Asynchronous reset removal time	0	–	0	–	ns
t _{MARSTREC}	Asynchronous reset recovery time	0.088	–	0.104	–	ns
t _{MOCQ}	Output register clock to out delay	–	0.232	–	0.273	ns
t _{MCLKMP}	CLK minimum period	2.245	–	2.641	–	ns

Table 146 • Mathblock with Input Bypassed and Output Registers Used
 Worst Commercial-Case Conditions: T_J = 85°C, VDD = 1.14 V

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t _{MOSU}	Output register setup time	2.294	–	2.699	–	ns
t _{MOHD}	Output register hold time	1.68	–	1.976	–	ns
t _{MOCDINSU}	CDIN input setup time	0.115	–	0.136	–	ns
t _{MOCDINH}	CDIN input hold time	–0.444	–	–0.522	–	ns
t _{MSRSTENSU}	Synchronous reset/enable setup time	–0.419	–	–0.493	–	ns
t _{MSRSTENHD}	Synchronous reset/enable hold time	0.011	–	0.013	–	ns
t _{MARSTREM}	Asynchronous reset removal time	0	–	0	–	ns

Table 146 • Mathblock with Input Bypassed and Output Registers Used
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$ (continued)

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{MARSTREC}	Asynchronous reset recovery time	0.014	–	0.017	–	ns
t_{MOCQ}	Output register clock to out delay	–	0.232	–	0.273	ns
t_{MCLKMP}	CLK minimum period	2.179	–	2.563	–	ns

Table 147 • Mathblock with Input Register Used and Output in Bypass Mode
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{MISU}	Input register setup time	0.149	–	0.176	–	ns
t_{MIHD}	Input register hold time	0.185	–	0.218	–	ns
$t_{\text{MSRSTENSU}}$	Synchronous reset/enable setup time	0.08	–	0.094	–	ns
$t_{\text{MSRSTENHD}}$	Synchronous reset/enable hold time	–0.012	–	–0.014	–	ns
t_{MARSTREM}	Asynchronous reset removal time	–0.005	–	–0.005	–	ns
t_{MARSTREC}	Asynchronous reset recovery time	0.088	–	0.104	–	ns
t_{MICQ}	Input register clock to output delay	–	2.52	–	2.964	ns
t_{MCDIN2Q}	CDIN to output delay	–	1.951	–	2.295	ns

Table 148 • Mathblock with Input and Output in Bypass Mode
 Worst Commercial-Case Conditions: $T_J = 85^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade				Units
		-1		Std		
		Min	Max	Min	Max	
t_{MIQ}	Input to output delay	–	2.568	–	3.022	ns
t_{MCDIN2Q}	CDIN to output delay	–	1.951	–	2.295	ns

21. Flash*Freeze Timing Characteristics

Table 149 • Flash*Freeze Entry and Exit Times
 Worst-Case Industrial Conditions: T_J = 100°C, VDD = 1.14 V

Symbols	Parameters	Conditions	Entry/Exit Timing FCLK = 100MHz		Entry/Exit Timing FCLK = 3 MHz	Units	Notes
			005, 010, 025,060, 090, and 150	050	All Devices		
TFF_ENTRY	Entry time	eNVM and MSS/HPMS PLL = ON	160	150	320	µs	
		eNVM and MSS/HPMS PLL = OFF	215	200	430	µs	
TFF_EXIT	Exit time with respect to the MSS PLL Lock	eNVM and MSS/HPMS PLL = ON during F*F	100	100	140	µs	
		eNVM = ON and MSS/HPMS PLL = OFF during F*F and MSS/HPMS PLL turned back on at exit	136	120	190	µs	
		eNVM and MSS/HPMS PLL = OFF during F*F and both are turned back on at exit	200	200	285	µs	
		eNVM = OFF and MSS/HPMS PLL = ON during F*F and eNVM turned back on at exit	200	200	285	µs	
	Exit time with respect to the Fabric PLL Lock	eNVM and MSS/HPMS PLL = ON during F*F	1.5	1.5	1.5	ms	1
		eNVM and MSS/HPMS PLL = OFF during F*F and both are turned back on at exit	1.5	1.5	1.5	ms	1
	Exit time with respect to the Fabric buffer output	eNVM and MSS/HPMS PLL = ON during F*F	21	15	21	µs	
		eNVM and MSS/HPMS PLL = OFF during F*F and both are turned back on at exit	65	55	65	µs	

Notes:
 1. PLL Lock Delay set to 1024 cycles (default)

22. DDR Memory Interface Characteristics

Table 150 • DDR Memory Interface Characteristics

 Worst-Case Industrial Conditions: $T_J = 100^{\circ}\text{C}$, $V_{DD} = 1.14\text{ V}$

Standard	Supported Data Rate			Unit
	Min	Typ	Max	
DDR3	667			Mbps
DDR2	667			Mbps
LPDDR	50	–	400	Mbps

23. SFP Transceiver Characteristics

IGLOO2 and SmartFusion2 SERDES complies with small form-factor pluggable (SFP) requirements as specified in SFP INF-80741. Table 151 provides the electrical characteristics.

Table 151 • SFP Transceiver Electrical Characteristics

 Worst-Case Industrial Conditions: $T_J = 100^{\circ}\text{C}$, $V_{DD} = 1.14\text{ V}$

Pin	Direction	Differential Peak-Peak Voltage			Unit	Note
		Min	Typ	Max		
RD+/-	Output	1600	–	2400	mV	1
TD+/-	Input	350	–	2400	mV	2

Notes:

1. Based on default SERDES transmitter settings for PCIe Gen1. Lower amplitudes are available through programming changes to TX_AMP setting.
2. Based on Input Voltage Common-Mode (VICM) = 0 V. Requires AC Coupling.

24. SERDES Electrical and Timing AC and DC Characteristics

PCIe® is a high speed, packet-based, point-to-point, low pin count, serial interconnect bus. The IGLOO2 and SmartFusion2 SoC FPGAs has up to four hard high-speed serial interface blocks. Each SERDES block contains a PCIe system block. The PCIe system is connected to the SERDES block.

Table 152 • Transmitter Parameters

Worst-Case Industrial Conditions: T_J = 100°C, VDD = 1.14 V

Parameter	Description	Min	Typ	Max	Units
VTX-DIFF-PP	Differential swing (2.5 Gbps, 5.0 Gbps)	0.8	–	1.2	V
VTX-CM-AC-P	Output common mode voltage (2.5 Gbps)	–	–	20	mV
VTX-CM-AC-PP	Output common mode voltage (5.0 Gbps)	–	–	100	mV
VTX-RISE-FALL	Rise and fall time (20% to 80%, 2.5 Gbps)	0.125	–	–	UI
	Rise and fall time (20% to 80%, 5.0 Gbps)	0.15	–	–	UI
ZTX-DIFF-DC	Output impedance – differential	80	–	120	Ω
LTX-SKEW	Lane-to-lane TX skew within a SERDES block (2.5 Gbps)	–	–	500 ps+ 2 UI	ps
	Lane-to-lane TX skew within a SERDES block (5.0 Gbps)	–	–	500 ps+4 UI	ps
RLTX-DIFF	Return loss differential mode (2.5 Gbps)	–10	–	–	dB
	Return loss differential mode (5.0 Gbps) 0.05 GHz to 1.25 GHz	–10	–	–	dB
	1.25 GHz to 2.5 GHz	–8	–	–	dB
RLTX-CM	Return loss common mode (2.5 Gbps, 5.0 Gbps)	–6	–	–	dB
TX-LOCK-RST	Transmit PLL lock time from reset	–	–	10	μs

Table 153 • Receiver Parameters

Worst-Case Industrial Conditions: T_J = 100°C, VDD = 1.14 V

Parameter	Description	Min	Typ	Max	Units	Notes
VRX-IN-PP-CC	Differential input peak-to-peak sensitivity (2.5 Gbps)	0.238	–	1.2	V	–
	Differential input peak-to-peak sensitivity (2.5 Gbps, de-emphasized)	0.219	–	1.2	V	–
	Differential input peak-to-peak sensitivity (5.0 Gbps)	0.300	–	1.2	V	–
	Differential input peak-to-peak sensitivity (5.0 Gbps, de-emphasized)	0.300	–	1.2	V	–
VRX-CM-AC-P	Input common mode range (AC coupled)	–	–	150	mV	–
ZRX-DIFF-DC	Differential input termination	80	100	120	Ω	–
REXT	External calibration resistor	1,188	1,200	1,212	Ω	–
CDR-LOCK-RST	CDR relock time from reset	–	–	15	μs	–

Table 153 • Receiver Parameters (continued)

 Worst-Case Industrial Conditions: $T_J = 100^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Min	Typ	Max	Units	Notes
RLRX-DIFF	Return loss differential mode (2.5 Gbps)	-10	-	-	dB	-
	Return loss differential mode (5.0 Gbps) 0.05GHz to 1.25GHz	-10	-	-	dB	-
		1.25GHz to 2.5GHz	-8	-	-	dB
RLRX-CM	Return loss common mode (2.5 Gbps, 5.0 Gbps)	-6	-	-	dB	-
RX-CID	CID limit PCIe Gen1/2	-	-	200	UI	*
VRX-IDLE-DET-DIFF-PP	Signal detect limit	65	-	175	mV	-

Note: * AC-coupled, $BER = e^{-12}$

Table 154 • SERDES Protocol Compliance

Protocol	Maximum Data Rate (Gbps)	Speed Grade	
		STD	-1
PCIe Gen 1	2.5	Yes	Yes
PCIe Gen 2	5.0	—	Yes
XAUI	3.125	—	Yes

Table 155 • SERDES Reference Clock AC Specifications

 Worst-Case Industrial Conditions: $T_J = 100^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Symbols	Description	Min	Typ	Max	Units
FREFCLK	Reference Clock Frequency	100	-	160	MHz
TRISE	Reference Clock Rise Time	0.6	-	4	V/ns
TFALL	Reference Clock Fall Time	0.6	-	4	V/ns
TCYC	Reference Clock Duty Cycle	40	-	60	%
Mmrefclk	Reference Clock Mismatch	-300	-	300	ppm
SSCref	Reference Spread Spectrum Clock	0	-	5000	ppm

Table 156 • HCSL Minimum and Maximum DC Input Levels (Applicable to SERDES REFCLK Only)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
Recommended DC Operating Conditions						
VDDI	Supply Voltage	-	2.375	2.5	2.625	V
HCSL DC Input Voltage Specification						
VI	DC Input voltage	-	0	-	2.625	V
HCSL Differential Voltage Specification						
VICM	Input common mode voltage	-	0.05	-	2.4	V
VIDIFF	Input differential voltage	-	100	-	1100	mV

Table 157 • HCSL Minimum and Maximum AC Switching Speeds (Applicable to SERDES REFCLK Only)

Symbols	Parameters	Conditions	Min	Typ	Max	Units
HCSL AC Specifications						
Fmax	Maximum Data Rate (for MSIO I/O Bank)	–	–	–	350	Mbps
HCSL Impedance Specifications						
Rt	Termination Resistance	–	–	100	–	Ω

25. SmartFusion2 Specifications

25.1 MSS Clock Frequency

Table 158 • Maximum Frequency for MSS Main Clock

Worst-Case Industrial Conditions: T_J = 100°C, VDD = 1.14 V

Symbol	Description	Speed Grade		Units
		–1	Std	
M3_CLK	Maximum frequency for the MSS Main Clock	166	142	MHz

25.2 SmartFusion2 Inter-Integrated Circuit (I²C) Characteristics

This section describes the DC and switching of the I²C interface. Unless otherwise noted, all output characteristics given are for a 100 pF load on the pins. For timing parameter definitions, refer to [Figure 17 on page 123](#).

Table 159 • I²C Characteristics

Worst-Case Industrial Conditions: T_J = 100°C, VDD = 1.14 V

Parameter	Definition	Conditions	Min	Typ	Max	Units	Notes
VIL	Input low voltage	Refer to the "Single-Ended I/O Standards" section on page 30 for more information. I/O standard used for illustration: MSIO bank – LVTTTL 8 mA low drive.	–0.3	–	0.8	V	–
VIH	Input high voltage	Refer to the "Single-Ended I/O Standards" section on page 30 for more information. I/O standard used for illustration: MSIO bank – LVTTTL 8 mA low drive.	2	–	3.45	V	–
VHYS	Hysteresis of Schmitt triggered inputs for VDDI > 2 V	Refer to Table 23 on page 30 for more information.	0.05 × VDDI	–	–	V	–
IIL	Input current high	Refer to the "Single-Ended I/O Standards" section on page 30 for more information.	–	–	10	μA	–
IIH	Input current low	Refer to the "Single-Ended I/O Standards" section on page 30 for more information.	–	–	10	μA	–
Tir	Input rise time	Standard Mode	–	–	1000	ns	–
		Fast Mode	–	–	300	ns	–
Tif	Input fall time	Standard Mode	–	–	300	ns	–
		Fast Mode	–	–	300	ns	–

Table 159 • I2C Characteristics (continued)

 Worst-Case Industrial Conditions: $T_J = 100^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Definition	Conditions	Min	Typ	Max	Units	Notes
VOL	Maximum output voltage low (open drain) at 3 mA sink current for $V_{DDI} > 2\text{ V}$	Refer to the "Single-Ended I/O Standards" section on page 30 for more information. I/O standard used for illustration: MSIO bank – LVTTTL 8 mA low drive.	–	–	0.4	V	–
Cin	Pin capacitance	$V_{IN} = 0$, $f = 1.0\text{ MHz}$	–	–	10	pF	–
t _{OF}	Output fall time from V_{IHMin} to V_{ILMax}	V_{IHmin} to V_{ILMax} , $C_{load} = 400\text{ pF}$	–	21.04	–	ns	1
		V_{IHmin} to V_{ILMax} , $C_{load} = 100\text{ pF}$	–	5.556	–	ns	–
t _{OR}	Output rise time from V_{ILMax} to V_{IHMin}	V_{ILMax} to V_{IHmin} , $C_{load} = 400\text{ pF}$	–	19.887	–	ns	1
		V_{ILMax} to V_{IHmin} , $C_{load} = 100\text{ pF}$	–	5.218	–	ns	–
R _{pull-up}	Output buffer maximum pull-down resistance	–	–	–	50	Ω	2, 3
R _{pull-down}	Output buffer maximum pull-up resistance	–	–	–	131.25	Ω	2, 4
D _{max}	Maximum data rate	Fast mode	–	–	400	Kbps	–
		Standard mode	–	–	100	Kbps	–
t _{FILT}	Pulse width of spikes which must be suppressed by the input filter	Fast mode	–	50	–	ns	–

Notes:

1. These values are provided for MSIO Bank – LVTTTL 8 mA Low Drive at 25°C , typical conditions. For Board Design considerations and detailed output buffer resistances, use the corresponding IBIS models located on the SoC Products Group website: <http://www.microsemi.com/soc/download/ibis/default.aspx>.
2. These maximum values are provided for information only. Minimum output buffer resistance values depend on V_{DDIx} , drive strength selection, temperature, and process. For board design considerations and detailed output buffer resistances, use the corresponding IBIS models located on the SoC Products Group website: <http://www.microsemi.com/soc/download/ibis/default.aspx>.
3. $R(\text{PULL-DOWN-MAX}) = (V_{OLspec}) / I_{OLspec}$
4. $R(\text{PULL-UP-MAX}) = (V_{DDImax} - V_{OHspec}) / I_{OHspec}$

Table 160 • I2C Switching Characteristics

 Worst-Case Industrial Conditions: $T_J = 100^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Definition	Conditions	Speed Grade				Units
			–1		Std		
			Min	Max	Min	Max	
t _{LOW}	Low period of I2C_x_SCL	–	1	–	1	–	clk cycles
t _{HIGH}	High period of I2C_x_SCL	–	1	–	1	–	clk cycles
t _{HD;STA}	START hold time	–	1	–	1	–	clk cycles
t _{SU;STA}	START setup time	–	1	–	1	–	clk cycles
t _{HD;DAT}	DATA hold time	–	1	–	1	–	clk cycles
t _{SU;DAT}	DATA setup time	–	1	–	1	–	clk cycles
t _{SU;STO}	STOP setup time	–	1	–	1	–	clk cycles

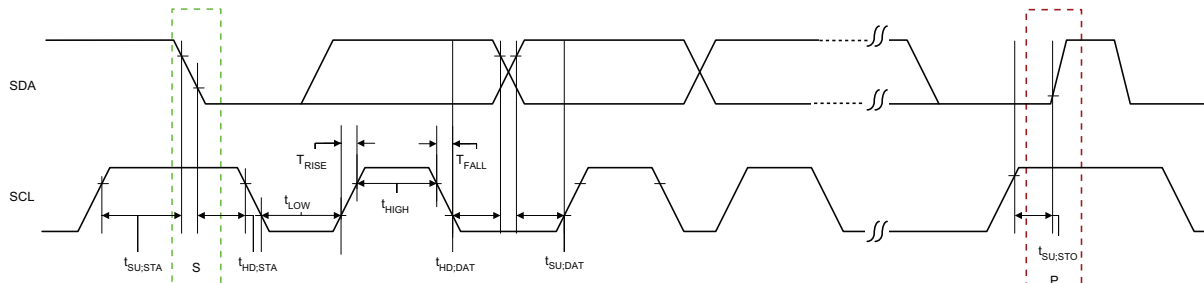


Figure 17 • I²C Timing Parameter Definition

25.3 Serial Peripheral Interface (SPI) Characteristics

This section describes the DC and switching of the SPI interface. Unless otherwise noted, all output characteristics given are for a 35 pF load on the pins and all sequential timing characteristics are related to SPI_x_CLK. For timing parameter definitions, refer to Figure 18 on page 126.

Table 161 • SPI Characteristics
Worst-Case Industrial Conditions: T_J = 100°C, VDD = 1.14 V

Symbol	Description	Conditions	All Devices/Speed Grades			Unit	Notes
			Min	Typ	Max		
SPIFMA X	Maximum operating frequency of SPI interface	–	–	–	20	MHz	–
sp1	SPI_[0]1_CLK minimum period						
	SPI_[0]1_CLK = PCLK/2	–	12	–	–	ns	–
	SPI_[0]1_CLK = PCLK/4	–	24.1	–	–	ns	–
	SPI_[0]1_CLK = PCLK/8	–	48.2	–	–	ns	–
	SPI_[0]1_CLK = PCLK/16	–	0.1	–	–	µs	–
	SPI_[0]1_CLK = PCLK/32	–	0.19	–	–	µs	–
	SPI_[0]1_CLK = PCLK/64	–	0.39	–	–	µs	–
	SPI_[0]1_CLK = PCLK/128	–	0.77	–	–	µs	–
sp2	SPI_[0]1_CLK minimum pulse width high						
	SPI_[0]1_CLK = PCLK/2	–	6	–	–	ns	–
	SPI_[0]1_CLK = PCLK/4	–	12.05	–	–	ns	–
	SPI_[0]1_CLK = PCLK/8	–	24.1	–	–	ns	–
	SPI_[0]1_CLK = PCLK/16	–	0.05	–	–	µs	–
	SPI_[0]1_CLK = PCLK/32	–	0.095	–	–	µs	–
	SPI_[0]1_CLK = PCLK/64	–	0.195	–	–	µs	–
	SPI_[0]1_CLK = PCLK/128	–	0.385	–	–	µs	–

Table 161 • SPI Characteristics (continued)

 Worst-Case Industrial Conditions: $T_J = 100^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Symbol	Description	Conditions	All Devices/Speed Grades			Unit	Notes
			Min	Typ	Max		
sp3	SPI_[0 1]_CLK minimum pulse width low						
	SPI_[0 1]_CLK = PCLK/2	–	6	–	–	ns	–
	SPI_[0 1]_CLK = PCLK/4	–	12.05	–	–	ns	–
	SPI_[0 1]_CLK = PCLK/8	–	24.1	–	–	ns	–
	SPI_[0 1]_CLK = PCLK/16	–	0.05	–	–	μs	–
	SPI_[0 1]_CLK = PCLK/32	–	0.095	–	–	μs	–
	SPI_[0 1]_CLK = PCLK/64	–	0.195	–	–	μs	–
	SPI_[0 1]_CLK = PCLK/128	–	0.385	–	–	μs	–
sp4	SPI_[0 1]_CLK, SPI_[0 1]_DO, SPI_[0 1]_SS rise time (10%–90%)	IO Configuration: LVCMOS 2.5 V-8mA AC Loading: 35pF Test Conditions: Typical Voltage, 25°C	–	2.77	–	ns	1
sp5	SPI_[0 1]_CLK, SPI_[0 1]_DO, SPI_[0 1]_SS fall time (10%–90%)	IO Configuration: LVCMOS 2.5 V-8mA AC Loading: 35pF Test Conditions: Typical Voltage, 25°C	–	2.906	–	ns	1
SPI Master Configuration (applicable for 005, 010, 025, and 050 devices)							
sp6m	SPI_[0 1]_DO setup time	–	(SPI_x_CLK_pe riod/2) – 8.0	–	–	ns	2
sp7m	SPI_[0 1]_DO hold time	–	(SPI_x_CLK_pe riod/2) – 2.5	–	–	ns	2
sp8m	SPI_[0 1]_DI setup time	–	12	–	–	ns	2
sp9m	SPI_[0 1]_DI hold time	–	2.5	–	–	ns	2
SPI Slave Configuration (applicable for 005, 010, 025, and 050 devices)							
sp6s	SPI_[0 1]_DO setup time	–	(SPI_x_CLK_pe riod/2) – 17.0	–	–	ns	2
sp7s	SPI_[0 1]_DO hold time	–	(SPI_x_CLK_pe riod/2) + 3.0	–	–	ns	2
sp8s	SPI_[0 1]_DI setup time	–	2	–	–	ns	2
sp9s	SPI_[0 1]_DI hold time	–	7	–	–	ns	2

Table 161 • SPI Characteristics (continued)
Worst-Case Industrial Conditions: T_J = 100°C, VDD = 1.14 V

Symbol	Description	Conditions	All Devices/Speed Grades			Unit	Notes
			Min	Typ	Max		
SPI Master Configuration (applicable for 060, 090, and 150 devices)							
sp6m	SPI_[0 1]_DO setup time	–	(SPI_x_CLK_period/2) – 7.0	–	–	ns	2
sp7m	SPI_[0 1]_DO hold time	–	(SPI_x_CLK_period/2) – 9.5	–	–	ns	2
sp8m	SPI_[0 1]_DI setup time	–	15	–	–	ns	2
sp9m	SPI_[0 1]_DI hold time	–	-2.5	–	–	ns	2
SPI Slave Configuration (applicable for 060, 090, and 150 devices)							
sp6s	SPI_[0 1]_DO setup time	–	(SPI_x_CLK_period/2) – 16.0	–	–	ns	2
sp7s	SPI_[0 1]_DO hold time	–	(SPI_x_CLK_period/2) – 3.5	–	–	ns	2
sp8s	SPI_[0 1]_DI setup time	–	3	–	–	ns	2
sp9s	SPI_[0 1]_DI hold time	–	2.5	–	–	ns	2
<p>Notes:</p> <ol style="list-style-type: none"> For specific Rise/Fall Times board design considerations and detailed output buffer resistances, use the corresponding IBIS models located on the Microsemi SoC Products Group website: http://www.microsemi.com/soc/download/ibis/default.aspx. For allowable pclk configurations, refer to the Serial Peripheral Interface Controller section in the <i>UG0331: SmartFusion2 Microcontroller Subsystem User Guide</i>. 							

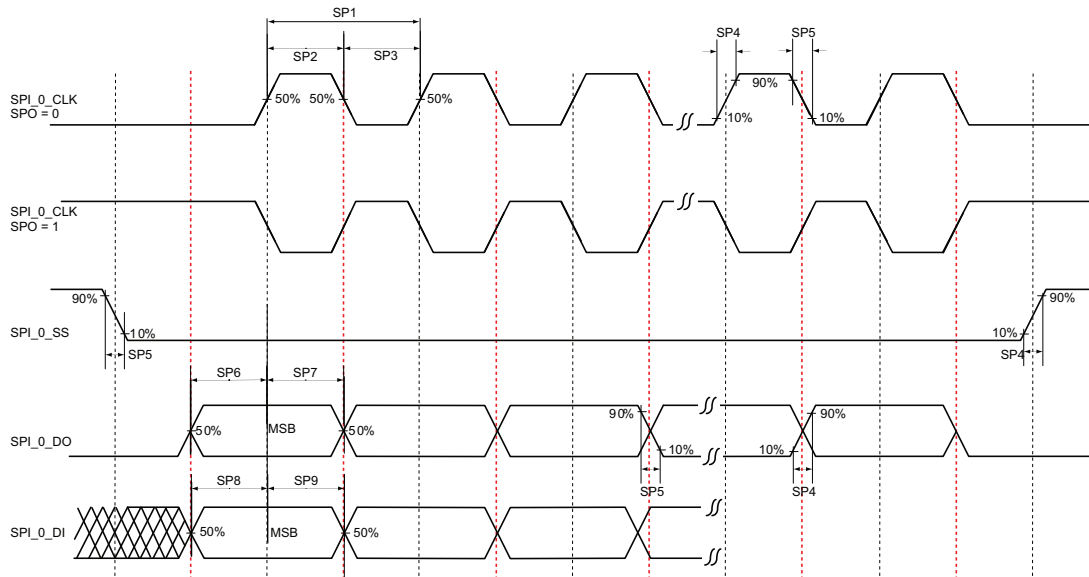


Figure 18 • SPI Timing for a Single Frame Transfer in Motorola Mode (SPH = 1)

26. CAN Controller Characteristics

Table 162 • CAN Controller Characteristics

Worst-Case Industrial Conditions: $T_J = 100^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade		Units	Notes
		-1	Std		
FCANREFCLK	Internally Sourced CAN Reference Clock Frequency	160	136	MHz	*
BAUDCANMAX	Maximum CAN Performance Baud Rate	1	1	Mbps	-
BAUDCANMIN	Minimum CAN Performance Baud Rate	0.05	0.05	Mbps	-

Note: PCLK to CAN controller must be a multiple of 8 MHz.

27. USB Characteristics

Table 163 • USB Characteristics

Worst-Case Industrial Conditions: $T_J = 100^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Parameter	Description	Speed Grade		Units
		-1	Std	
FUSBREFCLK	Internally Sourced USB Reference Clock Frequency	166	142	MHz
TUSBCLK	USB Clock Period	16.66	16.66	ns
TUSBPD	Clock to USB Data Propagation Delay	9.0	9.0	ns
TUSBSU	Setup Time for USB Data	6.0	6.0	ns
TUSBHD	Hold Time for USB Data	0	0	ns

28. IGLOO2 Specifications

28.1 HPMS Clock Frequency

Table 164 • Maximum Frequency for HPMS Main Clock
 Worst-Case Industrial Conditions: $T_J = 100^{\circ}\text{C}$, $V_{DD} = 1.14\text{ V}$

Symbol	Description	Speed Grade		Units
		-1	Std	
HPMS_CLK	Maximum Frequency for the HPMS Main Clock	166	142	MHz

28.2 IGLOO2 Serial Peripheral Interface (SPI) Characteristics

This section describes the DC and switching of the SPI interface. Unless otherwise noted, all output characteristics given are for a 35 pF load on the pins and all sequential timing characteristics are related to SPI_0_CLK. For timing parameter definitions, refer to Figure 19 on page 129.

Table 165 • SPI Characteristics
 Worst-Case Industrial Conditions: $T_J = 100^{\circ}\text{C}$, $V_{DD} = 1.14\text{ V}$

Symbol	Description	Conditions	All Devices/Speed Grades			Unit	Notes
			Min	Typ	Max		
SPIFMAX	Maximum operating frequency of SPI interface	–	–	–	20	MHz	
sp1	SPI_[0 1]_CLK minimum period						
	SPI_[0 1]_CLK = PCLK/2	–	12	–	–	ns	–
	SPI_[0 1]_CLK = PCLK/4	–	24.1	–	–	ns	–
	SPI_[0 1]_CLK = PCLK/8	–	48.2	–	–	ns	–
	SPI_[0 1]_CLK = PCLK/16	–	0.1	–	–	μs	–
	SPI_[0 1]_CLK = PCLK/32	–	0.19	–	–	μs	–
	SPI_[0 1]_CLK = PCLK/64	–	0.39	–	–	μs	–
	SPI_[0 1]_CLK = PCLK/128	–	0.77	–	–	μs	–
sp2	SPI_[0 1]_CLK minimum pulse width high						
	SPI_[0 1]_CLK = PCLK/2	–	6	–	–	ns	–
	SPI_[0 1]_CLK = PCLK/4	–	12.05	–	–	ns	–
	SPI_[0 1]_CLK = PCLK/8	–	24.1	–	–	ns	–
	SPI_[0 1]_CLK = PCLK/16	–	0.05	–	–	μs	–
	SPI_[0 1]_CLK = PCLK/32	–	0.095	–	–	μs	–
	SPI_[0 1]_CLK = PCLK/64	–	0.195	–	–	μs	–
	SPI_[0 1]_CLK = PCLK/128	–	0.385	–	–	μs	–

Notes:

- For specific Rise/Fall Times board design considerations and detailed output buffer resistances, use the corresponding IBIS models located on the Microsemi SoC Products Group website: <http://www.microsemi.com/soc/download/ibis/default.aspx>.
- For allowable pclk configurations, refer to the Serial Peripheral Interface Controller section in the UG0331: SmartFusion2 Microcontroller Subsystem User Guide.

Table 165 • SPI Characteristics (continued)

 Worst-Case Industrial Conditions: $T_J = 100^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

Symbol	Description	Conditions	All Devices/Speed Grades			Unit	Notes
			Min	Typ	Max		
sp3	SPI_[0 1]_CLK minimum pulse width low						
	SPI_[0 1]_CLK = PCLK/2	–	6	–	–	ns	–
	SPI_[0 1]_CLK = PCLK/4	–	12.05	–	–	ns	–
	SPI_[0 1]_CLK = PCLK/8	–	24.1	–	–	ns	–
	SPI_[0 1]_CLK = PCLK/16	–	0.05	–	–	μs	–
	SPI_[0 1]_CLK = PCLK/32	–	0.095	–	–	μs	–
	SPI_[0 1]_CLK = PCLK/64	–	0.195	–	–	μs	–
	SPI_[0 1]_CLK = PCLK/128	–	0.385	–	–	μs	–
sp4	SPI_[0 1]_CLK, SPI_[0 1]_DO, SPI_[0 1]_SS rise time (10%–90%)	IO Configuration: LVCMOS 2.5 V-8mA AC Loading: 35pF Test Conditions: Typical Voltage, 25°C	–	2.77	–	ns	1
sp5	SPI_[0 1]_CLK, SPI_[0 1]_DO, SPI_[0 1]_SS fall time (10%–90%)	IO Configuration: LVCMOS 2.5 V-8mA AC Loading: 35pF Test Conditions: Typical Voltage, 25°C	–	2.906	–	ns	1
SPI Master Configuration (applicable for 005, 010, 025, and 050 devices)							
sp6m	SPI_[0 1]_DO setup time	–	$(\text{SPI_x_CLK_period}/2) - 8.0$	–	–	ns	2
sp7m	SPI_[0 1]_DO hold time	–	$(\text{SPI_x_CLK_period}/2) - 2.5$	–	–	ns	2
sp8m	SPI_[0 1]_DI setup time	–	12	–	–	ns	2
sp9m	SPI_[0 1]_DI hold time	–	2.5	–	–	ns	2
SPI Slave Configuration (applicable for 005, 010, 025, and 050 devices)							
sp6s	SPI_[0 1]_DO setup time	–	$(\text{SPI_x_CLK_period}/2) - 17.0$	–	–	ns	2
sp7s	SPI_[0 1]_DO hold time	–	$(\text{SPI_x_CLK_period}/2) + 3.0$	–	–	ns	2
sp8s	SPI_[0 1]_DI setup time	–	2	–	–	ns	2
sp9s	SPI_[0 1]_DI hold time	–	7	–	–	ns	2

Table 165 • SPI Characteristics (continued)

Worst-Case Industrial Conditions: $T_J = 100^\circ\text{C}$, $V_{DD} = 1.14\text{ V}$

SPI Master Configuration (applicable for 060, 090, and 150 devices)							
sp6m	SPI_[0 1]_DO setup time	–	$(\text{SPI}_x_CLK_period/2) - 7.0$	–	–	ns	2
sp7m	SPI_[0 1]_DO hold time	–	$(\text{SPI}_x_CLK_period/2) - 9.5$	–	–	ns	2
sp8m	SPI_[0 1]_DI setup time	–	15	–	–	ns	2
sp9m	SPI_[0 1]_DI hold time	–	-2.5	–	–	ns	2
SPI Slave Configuration (applicable for 060, 090, and 150 devices)							
sp6s	SPI_[0 1]_DO setup time	–	$(\text{SPI}_x_CLK_period/2) - 16.0$	–	–	ns	2
sp7s	SPI_[0 1]_DO hold time	–	$(\text{SPI}_x_CLK_period/2) - 3.5$	–	–	ns	2
sp8s	SPI_[0 1]_DI setup time	–	3	–	–	ns	2
sp9s	SPI_[0 1]_DI hold time	–	2.5	–	–	ns	2

Notes:

- For specific Rise/Fall Times board design considerations and detailed output buffer resistances, use the corresponding IBIS models located on the Microsemi SoC Products Group website: <http://www.microsemi.com/soc/download/ibis/default.aspx>.
- For allowable pclk configurations, refer to the Serial Peripheral Interface Controller section in the *UG0331: SmartFusion2 Microcontroller Subsystem User Guide*.

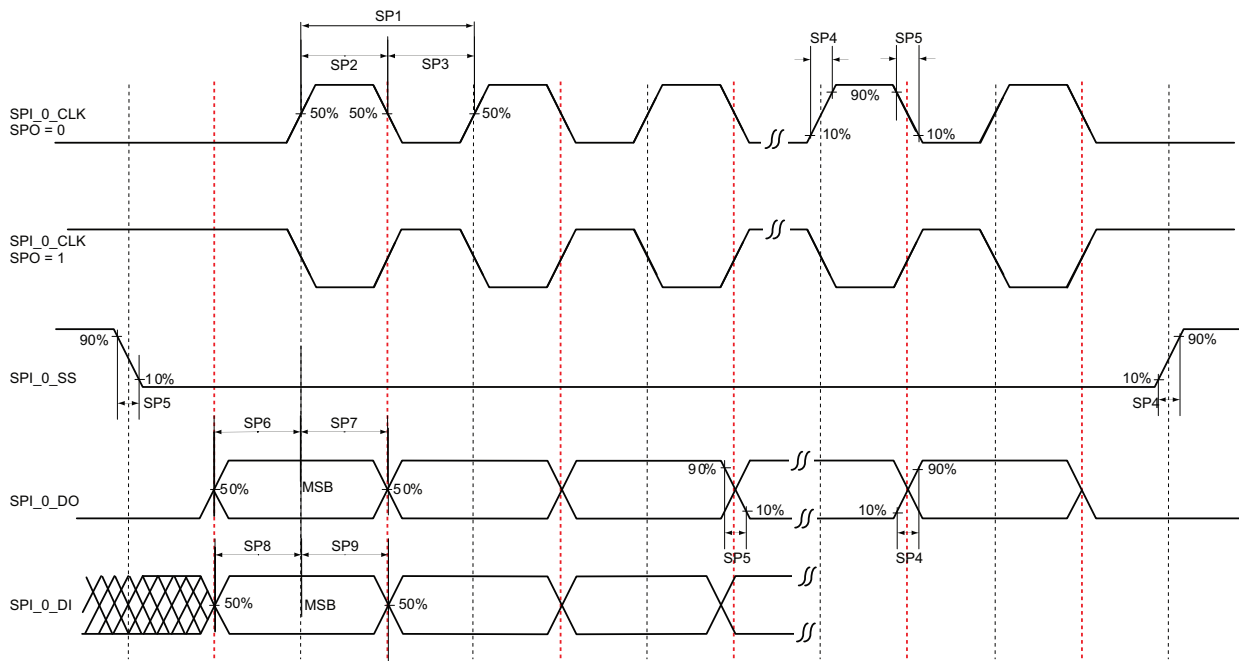


Figure 19 • SPI Timing for a Single Frame Transfer in Motorola Mode (SPH = 1)

Datasheet Information

List of Changes

The following table shows important changes made in this document for each revision.

Revision	Changes	Page
Revision 10 (May 2016)	The Surge Current on VDD during DEVRST_B Assertion and Surge Current on VDD during Digest Check using System Services tables are moved to AC393: Board Design Guidelines for SmartFusion2 SoC and IGLOO2 FPGAs Application Note . (SAR 76865 and 76623).	NA
	Added 060 device in Table 3: "Recommended Operating Conditions" (SAR 76383).	13
	Updated Table 19: "Input Capacitance and Leakage Current" for ramp time input (SAR 72103).	28
	Added 060 device details in Table 141: "JTAG 1532" (SAR 74927).	113
	Updated Table 142: "DEVRST_N Characteristics" for name change (SAR 74925).	114
	Updated Table 140: "IGLOO2 and SmartFusion2 SoC FPGAs CCC/PLL Jitter Specifications" for 060 FG676 Package details (SAR 78849).	111
	Updated Table 161: "SPI Characteristics " for SmartFusion2 and Table 165: "SPI Characteristics " for IGLOO2 for SPI timing and Fmax (SAR 56645, 75331).	123
	Updated Table 149: "Flash*Freeze Entry and Exit Times" for Flash*Freeze entry and exit times (SAR 75329, 75330).	117
	Updated Table 153: "Receiver Parameters" for RX-CID information (SAR 78271).	119
	Added Table 7: "High Temperature Data Retention (HTR) Lifetime" and Figure 1 (SAR 78932).	16 and 16
	Updated Table 108: "Combinatorial Cell Propagation Delays" for timing characteristics and Table 109: "Register Delays" (SAR 75998).	80 and 82
	Added "SRAM PUF" section (SAR 64406).	106
	Added a footnote on digest cycle in Table 4: "FPGA Operating Limits" (SAR 79812).	15
	Revision 9 (December 2015)	Added a note in Table 4: "FPGA Operating Limits" (SAR 71506).
Added a note in Table 5: "Embedded Operating Flash Limits" (SAR 74616).		15
Added a note in Figure 3 (SAR 71506).		24
Updated Quiescent Supply Current for 060 in Table 10: "SmartFusion2 and IGLOO2 Quiescent Supply Current – Typical Process" and Table 11: "SmartFusion2 and IGLOO2 Quiescent Supply Current – Worst-Case Process" (SAR 74483).		20, and 20
Updated programming currents for 060 in Table 12: "Currents During Program Cycle, 0°C <= Tj <= 85°C – Typical Process" , Table 13: "Currents During Verify Cycle, 0°C <= Tj <= 85°C – Typical Process" , and Table 14: "Inrush Currents at Power up, -40°C <= Tj <= 100°C – Typical Process" .		21,21, and 21
Added DEVRST_B assertion tables such as Table 14: Surge Current on VDD during DEVRST_B Assertion and Table 15: Surge Current on VDD during Digest Check using System Services (SAR 74708).		NA
Updated I/O speeds for LVDS 3.3 V in Table 17: "Maximum Data Rate Summary Table for Worst-Case Industrial Conditions" and Table 18: "Maximum Frequency Summary Table for Worst-Case Industrial Conditions" (SAR 69829).		27 and 27

Revision	Changes	Page
	Updated Table 19: "Input Capacitance and Leakage Current" (SAR 69418).	28
	Updated Table 20: "I/O Weak Pull-Up/Pull-Down Resistances for DDRIO I/O Bank", Table 21: "I/O Weak Pull-Up/Pull-Down Resistances for MSIO I/O Bank", Table 22: "I/O Weak Pull-Up/Pull-Down Resistances for MSIOD I/O Bank" (SAR 74570).	29, 29, and 29
	Updated all AC/DC table to link to the "Input Capacitance and Leakage Current" for reference (SAR 69418).	28
	Added Table 129: "Programming Times" and Table 130: "Programming Times" (SAR 73971).	100 and 103
	Updated the "SERDES Electrical and Timing AC and DC Characteristics" section (SAR 71171).	119
	Added the "DEVRST_N Characteristics" section (SAR 64100, 72103).	114
	Added Table 154: "SERDES Protocol Compliance" (SAR 71897).	120
	Updated Table 20: "I/O Weak Pull-Up/Pull-Down Resistances for DDRIO I/O Bank", Table 21: "I/O Weak Pull-Up/Pull-Down Resistances for MSIO I/O Bank", and Table 22: "I/O Weak Pull-Up/Pull-Down Resistances for MSIOD I/O Bank" (SAR 74570).	29, 29, and 29
	Added 060 devices in Table 134: "Electrical Characteristics of the Crystal Oscillator – High Gain Mode (20 MHz)", Table 135: "Electrical Characteristics of the Crystal Oscillator – Medium Gain Mode (2 MHz)", and Table 136: "Electrical Characteristics of the Crystal Oscillator – Low Gain Mode (32 kHz)" (SAR 57898).	107, 107, and 108
	Updated duty cycle parameter of crystal in Table 137: "Electrical Characteristics of the 50 MHz RC Oscillator" and Table 138: "Electrical Characteristics of the 1 MHz RC Oscillator" (SAR 57898).	109 and 109
	Added 32 KHz mode PLL acquisition time in Table 139: "IGLOO2 and SmartFusion2 SoC FPGAs CCC/PLL Specification" (SAR 68281).	110
	Updated Table 149: "Flash*Freeze Entry and Exit Times" for 060 devices (SAR 57828).	117
	Updated Table 153: "Receiver Parameters" for CID value (SAR 70878).	119
Revision 8 (September 2015)	Updated Table 10: "SmartFusion2 and IGLOO2 Quiescent Supply Current – Typical Process" (SAR 69218).	20
	Updated Table 11: "SmartFusion2 and IGLOO2 Quiescent Supply Current – Worst-Case Process" (SAR 69218).	20
	Updated Table 140: "IGLOO2 and SmartFusion2 SoC FPGAs CCC/PLL Jitter Specifications" (SAR 69000).	111
Revision 7 (June 2015)	Updated Table 1: "IGLOO2 FPGA and SmartFusion2 SoC FPGA Device Status" (SAR 68620).	11

Revision	Changes	Page
Revision 6 (May 2015)	Updated Table 4: "FPGA Operating Limits" (SAR 65949).	15
	Updated Table 8: "Package Thermal Resistance" (SAR 62995).	17
	Updated Table 62: "SSTL18 AC Specifications (Applicable to DDRIO Bank Only)" and Table 66: "SSTL15 AC Specifications (for DDRIO I/O Bank Only)" (SAR 67210).	52, 55
	Added "Embedded NVM (eNVM) Characteristics" (SAR 52509).	106
	Updated Table 134: "Electrical Characteristics of the Crystal Oscillator – High Gain Mode (20 MHz)" (SAR 64855).	107
	Updated Table 139: "IGLOO2 and SmartFusion2 SoC FPGAs CCC/PLL Specification" (SAR 65958 and SAR 56666).	110
	Added "DDR Memory Interface Characteristics" (SAR 66223).	118
	Added "SFP Transceiver Characteristics" (SAR 63105).	118
	Updated Table 158: "Maximum Frequency for MSS Main Clock" and Table 164: "Maximum Frequency for HPMS Main Clock" (SAR 66314).	121, 127
Revision 5 (March 2015)	Updated Table 1: "IGLOO2 FPGA and SmartFusion2 SoC FPGA Device Status"	11
	Updated Table 3: "Recommended Operating Conditions" for T _J symbol information.	13
	Updated Table 4: "FPGA Operating Limits" (SAR 63109).	15
	Updated Table 8: "Package Thermal Resistance"	17
	Updated Table 139: "IGLOO2 and SmartFusion2 SoC FPGAs CCC/PLL Specification" (SAR 62012).	110
	Added Table 142: "DEVRST_N Characteristics" (SAR 64100).	114
	Added Table 162: "CAN Controller Characteristics", Table 163: "USB Characteristics" (SAR 50424).	126, 126
Revision 4 (November 2014)	Updated Table 1. Changed the Status of 090 devices to "Production" (SAR 62750).	11
	Updated Figure 10. Removed inverter bubble from DDR_IN latch (SAR 61418).	74
	Updated "SERDES Electrical and Timing AC and DC Characteristics" (SAR 62836).	119
Revision 3 (October 2014)	Updated Theta B/C columns and FCS325 package in Table 8 (SAR 62002).	17

Revision	Changes	Page
Revision 2 (October 2014)	"IGLOO2 FPGA and SmartFusion2 SoC FPGA Device Status" table was updated (SAR 59056).	11
	Table 6 temperature and data retention information was updated SAR (61363).	15
	Storage Operating Table was updated and split into three tables – Table 4-Table 6 (SAR 58725).	15–21
	Updated Theta B/C columns and FCS325 package in Table 8 (SAR 62002).	17
	Added 090-FCS325 thermal resistance to Table 8 (SAR 59384).	17
	TQ144 package was added to Table 8 (SAR 57708).	17
	Added PLL jitter data for the VF400 package (SAR 53162).	17
	Added Additional Worst Case IDD to Table 10 and Table 11 (SAR 59077).	20
	Table 12, Table 13, and Table 14 were added to verify Inrush currents (SAR 56348).	21
	Table 17 and Table 18 – I/O speeds were replaced.	27, 27
	Max speed was changed in Table 30 (SAR 57221) and in Table 35 (SAR 57113).	33, 36
	"Minimum and Maximum DC/AC Input and Output Levels Specification" and Table 34–Table 38 were added.	35–37
	Added Cloud to Table 50 (SAR 56238).	45
	Removed "Rs" information in DDR Timing Measurement Table 62, Table 66, and Table 70.	52, 55, 57
	Updated drive programming for M/B-LVDS outputs (SAR 58154).	64
	Added an inverter bubble to DDR_IN latch in Figure 10 (SAR 61418).	74
	QF waveform in the Input DDR Timing Diagram was updated (SAR 59816).	75
	uSRAM Write Clock minimum values were updated in Table 122–Table 128 (SAR 55236).	91–98
	Fixed typo in the 32 kHz Crystal (XTAL) oscillator accuracy data section (SAR 59669).	108
	The "On-Chip Oscillator" section was split, and the "Embedded NVM (eNVM) Characteristics" section was added. Table 134–Table 138 were revised.(SARs 57898 and 59669).	109
	PLL VCP Frequency and conditions were added to Table 139 (SAR 57416).	110
	Fixed typo for PLL jitter data in the 100-400 MHz range (SAR 60727).	110
	Updated FCCC information in Table 139 and Table 140 (SAR 60799).	110
	Device 025 specifications were added to Table 140 (SAR 51625).	111
	JTAG Table 141 was replaced (SAR 51188).	113
	Flash*Freeze Table 149 was replaced (SAR 57828).	117
Added support for HCSL I/O Standard for SERDES reference clocks in Table 156 and Table 157 (SAR 50748).	120	
Tir and Tif parameters were added to Table 159 (SAR 52203).	121	
Speed grade consistency was fixed in tables throughout the datasheet (SAR 50722).	NA	

Revision	Changes	Page
	Added jitter attenuation information (SAR 59405).	NA
Revision 1 (May 2014)	The IGLOO2 v2 and the SmartFusion2 v5 datasheets are combined into this single product family datasheet.	N/A

Datasheet Categories

Categories

In order to provide the latest information to designers, some datasheet parameters are published before data has been fully characterized from silicon devices. The data provided for a given device, as highlighted in [Table 1 on page 11](#) is designated as either "Product Brief," "Advance," "Preliminary," or "Production." The definitions of these categories are as follows:

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The product brief is a summarized version of a datasheet (advance or production) and contains general product information. This document gives an overview of specific device and family information.

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This version contains initial estimated information based on simulation, other products, devices, or speed grades. This information can be used as estimates, but not for production.

This label only applies to the DC and Switching Characteristics chapter of the datasheet and will only be used when the data has not been fully characterized.

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Production

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